

Wistron Confidential

MV-1

2008/05/23

REV : -1

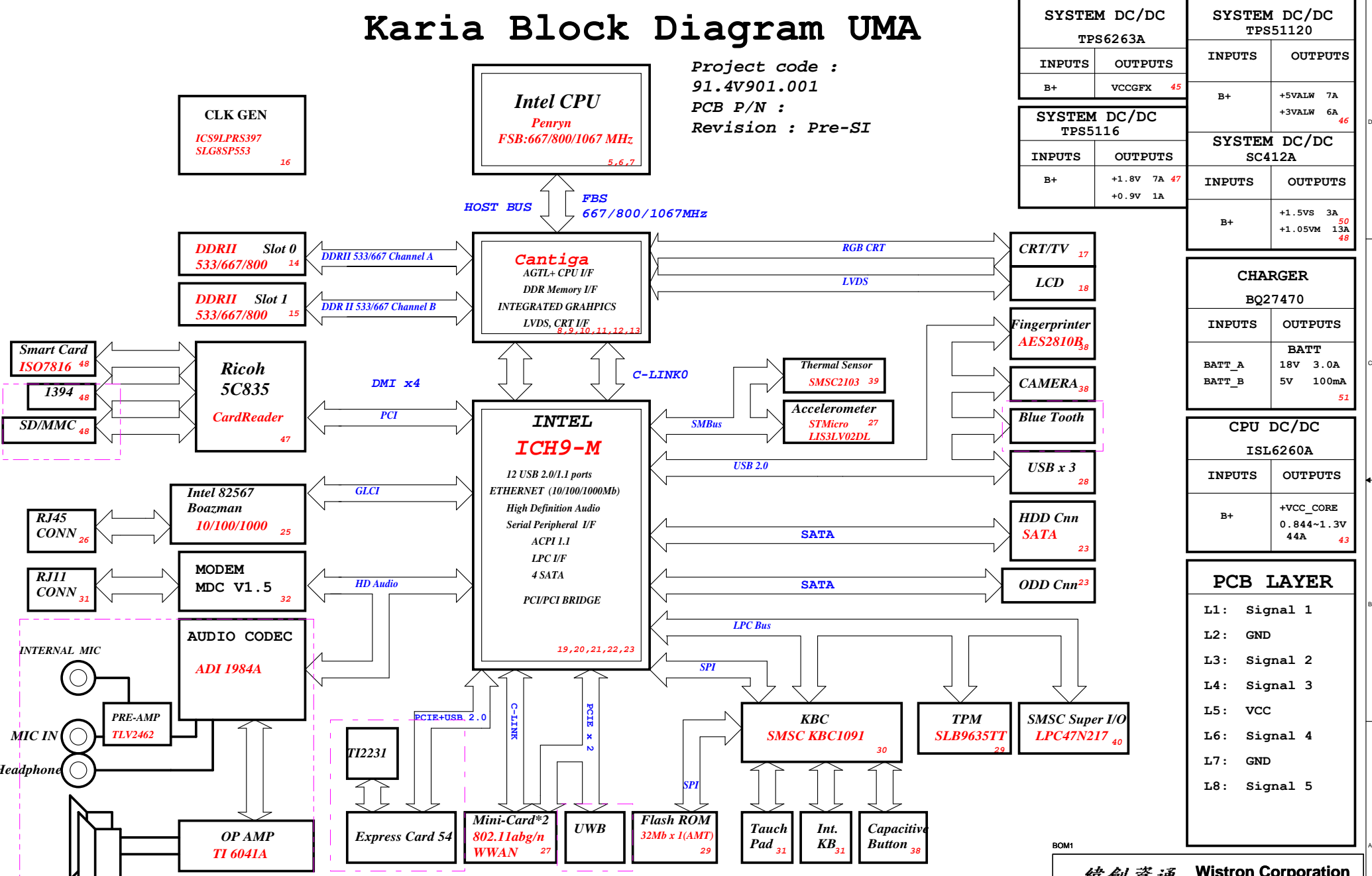
BOM1

緯創資通		Wistron Corporation	
		21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Karia			
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Karia Block Diagram UMA

Project code :
91.4V901.001
PCB P/N :
Revision : Pre-SI



SYSTEM DC/DC TPS6263A		SYSTEM DC/DC TPS51120	
INPUTS	OUTPUTS	INPUTS	OUTPUTS
B+	VCCGFX 45	B+	+5VALW 7A +3VALW 6A 46
SYSTEM DC/DC TPS5116		SYSTEM DC/DC SC412A	
INPUTS	OUTPUTS	INPUTS	OUTPUTS
B+	+1.8V 7A 47 +0.9V 1A	B+	+1.5VS 3A 50 +1.05VM 13A 48

CHARGER BQ27470	
INPUTS	OUTPUTS
BATT_A	BATT 18V 3.0A
BATT_B	5V 100mA 51

CPU DC/DC ISL6260A	
INPUTS	OUTPUTS
B+	+VCC_CORE 0.844~1.3V 44A 43

PCB LAYER	
L1:	Signal 1
L2:	GND
L3:	Signal 2
L4:	Signal 3
L5:	VCC
L6:	Signal 4
L7:	GND
L8:	Signal 5



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1. Page 43 - Change R542.2 to +3VALM from +3VS to power U86.39 (3V3) 0303 OK
2. Page 45 - Change R480 to NO INSTALL 0303 OK
3. Page 30 - Remove D48, connect signal directly to ADP_PRES, and uninstall R506 0303 OK
4. Page 51 - Chage R15 to 22K from 10K NOT DONE ON 0303 0312 OK

3/13

1. Page 27 - Add a 0 ohm series resistor on MC1_DISALBE and MC2_DISALBE RL: Don't need to add; use the 0 ohm at KBC.
2. Page 27 - Reserve a 1u 0603 cap (NO INSTALL) on MC2_DISALBE (same as MC1_DISABLE) 0312 OK
3. Page 19 - Add a 0 ohm series on PLT_RST# at U106.4 RL: Change R185 to 0 ohm; May need to change for damping.
4. Page 33 - Add a 0 ohm series on PM_PWROK_R at R166.2 RL: Pad is ok but needs to be on PM_PWROK_R from U89.40 (It's ok to put it near R541.2 on page43)
7. Page 30 - Change R598 to INSTALL (KBC GPIO08 has no internal PU) 0312 OK
8. Page 39 - Change R78 (SHDN_SEL) to 22K 1% to use External Diode2 for H/W critical shutdown 0312 OK
10. Page 24 - OPEN: May need to change U84 to Paricom level shifter. RL: Investigating
11. Page 25 - May require a discharging FET for +3VM_LAN at Q37.D RL: Change R104 to 470 ohm and change Q55.G to LAN_PY1
12. Page 32 - OPEN: May need to change RGB q-switches power to +5VALW or +5VS (depending on wavy impact) RL: Investigating
13. Page 51 - Change R101 to 33k from 1.27K 0312 OK
14. Page 41 - Change DAUGHT1 pin 52 and pin 54 to +5VS from +5VALW 0312 OK
15. Page 41 - Remove TCH_SMB_CLK/DATA from DAUGHT1 pin 32 and 34 0312 OK

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Change Notes List			
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Voltage Rails o MEANS ON x MEANS OFF

State \ power plane	+BB LDO3 LDO5	+5VALW +5VALW	+1.8V +5V +0.9V	+5VS +3VS +1.8VS +1.5VS +VGA_CORE +CPU_CORE +VCCP	+3VM +1.05VM	CLOCK
S0	O	O	O	O	O	O
S3/M1	O	O	O	X	O	O
S3	O	O	O	X	O	O
S5 S4/AC	O	O	X	X	O	O
S5 S4/Battery only	O	X	X	X	X	X
S5 S4/AC & Battery don't exist	X	X	X	X	X	X

PCI Devices

EXTERNAL	IDSEL#	REQ/GNT#	PIRQ
Cardreader&l394	AD25	2	G, E

PCIE Devices

DEVICE	NUMBER	CHANNEL
WWLAN	1	4
WLAN	1	2
UWB	1	1
Express Card	1	3

USB PORT	Device
0	USB1
1	Free
2	EX-P
3	WLAN
4	USB2
5	USB3
6	BLUETOOTH
7	WWAN
8	FingerPrint
9	Dock1
10	WEBCAM
11	DOCK2

Symbols	Description
DY/DUMMY	No install
1KR2J	Resistor 1K ohm ,Size 0402 ,5%
1KR3F	Resistor 1K ohm ,Size 0603 ,1%
GP	ROHS parts
NC	Pin no connect to anything
1U16V2ZY-2GP	Caps 1U ,Size 0402 Y5V
2D2U6D3V3MX	Caps 2.2U ,Size 0603 X5R

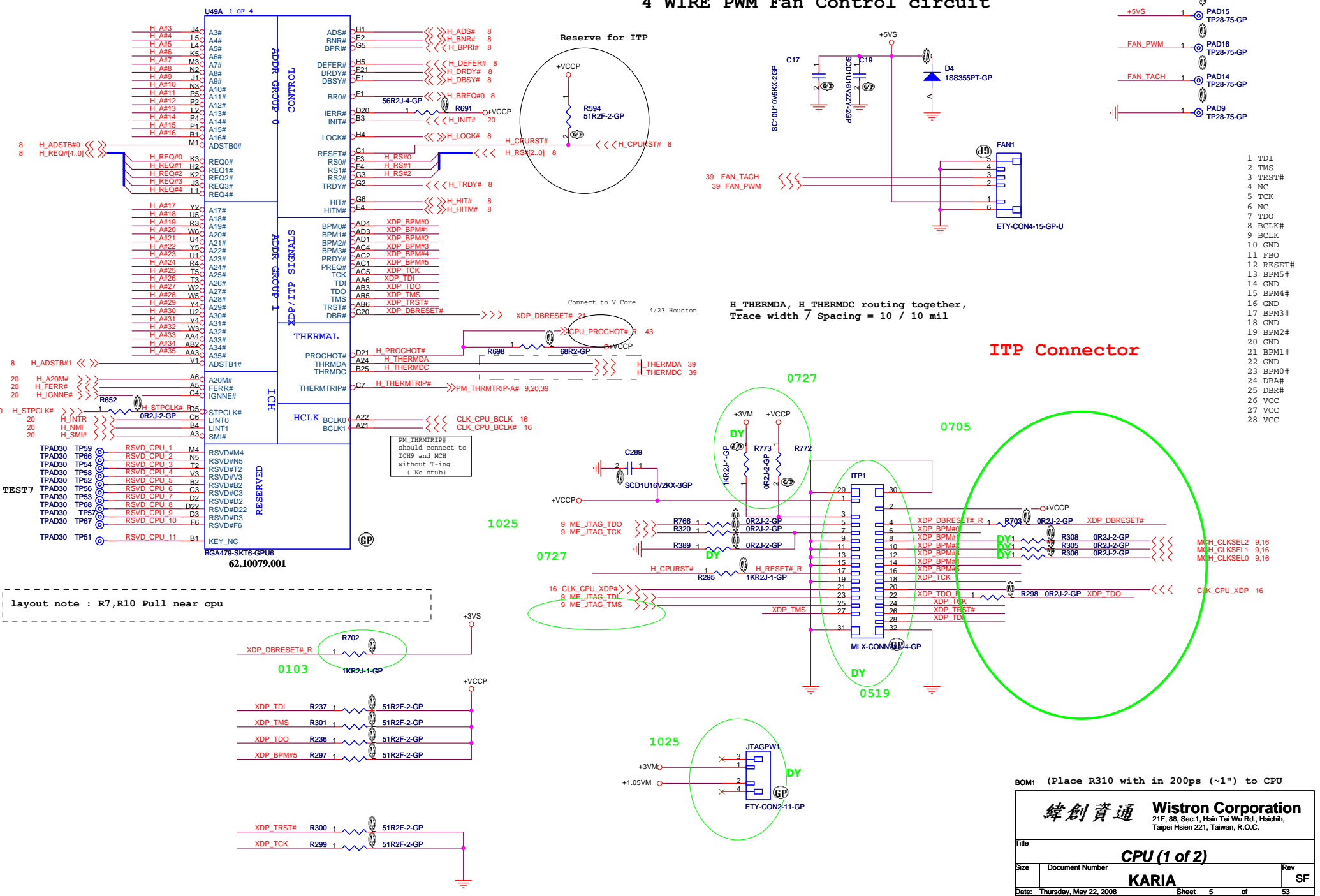
Fingerprint

IRQ	Device
0	System Timer
1	Keyboard
2	N/A
3	Serial port (COM2) ,LAN/Modem
4	Serial port (COM1)
5	Audio/VGA
6	Floppy
7	Parallel port
8	System CMOS/Real-time clock
9	Microsoft ACPI
10	N/A,Modem,LAN
11	Mass storage control/PCI simple communication control
12	synactic PS2 port GlidePAD
13	Numeric Data Process
14	Primary IDE interface ,HDD
15	Secondary IDE interface ,CD-ROM
16	Mobile Intel Crestline Express Chipset Family Microsoft UAA Bus Drive for High Definition Audio Intel 82801H (ICH9 Family) PCI Express Root Port -27D0 Broadcom NetXtreme Gigabit Ethernet
17	Intel 82801H (ICH9 Family) PCI Express Root Port -27D2 Broadcom 802.11b/g WLAN Intel 82801H (ICH9 Family) USB Universal Host Control
18	Intel 82801H (ICH9 Family) USB Universal Host Control Richo R5C835 Integrates FlashMedia Control Richo R5C835 Gemcore based SmartCard Control
19	Intel 82801H (ICH9 Family) PCI Express Root Port -27D6 Intel 82801H (ICH9 Family) USB Universal Host Control
20	Intel 82801H (ICH9 Family) USB Universal Host Control Intel 82801H (ICH9 Family) USB2 Enhanced Host Control
21	Intel 82801H (ICH9 Family) USB Universal Host Control
22	SDA Standard Compliant SD Host Control
23	HP Mobile Data Protection Sensor

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Karia List		
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4 WIRE PWM Fan Control circuit



5 H_A#[35..3] <<< H_A#(35..3)

8 H_ADSTB#0 <<< H_REQ#(4..0)

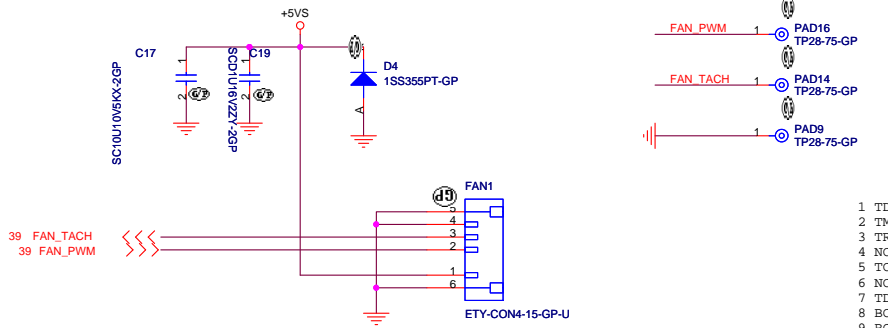
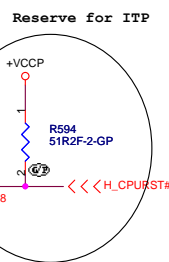
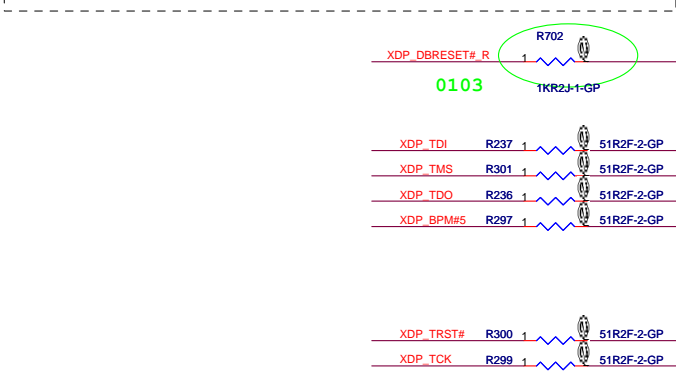
8 H_ADSTB#1 <<<

20 H_A20M# <<< H_INTR# <<< H_NMI# <<< H_SM#

20 H_STPCLK# <<<

TEST7 TPAD30 TP59 <<< RSVD_CPU_1 M4 <<< RSVD_CPU_2 N5 <<< RSVD_CPU_3 T2 <<< RSVD_CPU_4 V3 <<< RSVD_CPU_5 B2 <<< RSVD_CPU_6 C3 <<< RSVD_CPU_7 D2 <<< RSVD_CPU_8 D22 <<< RSVD_CPU_9 D3 <<< RSVD_CPU_10 F6 <<< RSVD_CPU_11 B1 <<< KEY_NC

layout note : R7,R10 Pull near cpu



H_THERMDA, H_THERMDC routing together, Trace width / Spacing = 10 / 10 mil

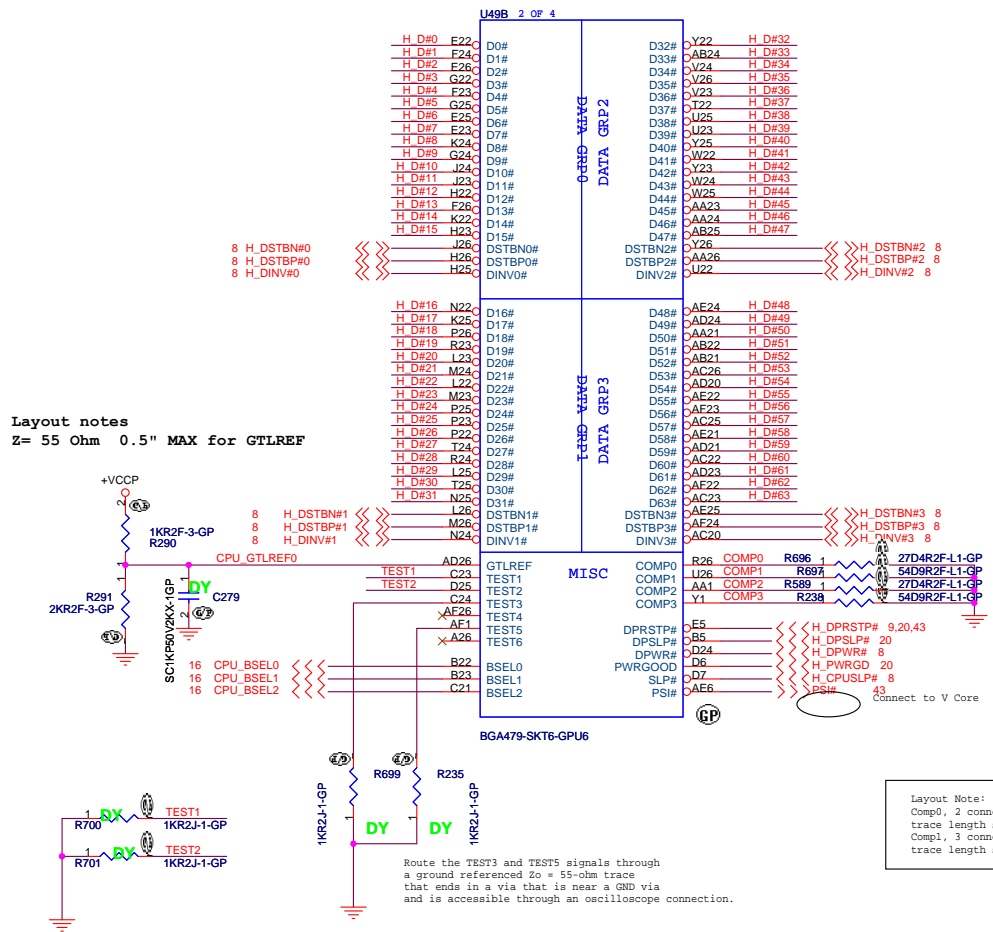
ITP Connector

- 1 TDI
- 2 TMS
- 3 TRST#
- 4 NC
- 5 TCK
- 6 NC
- 7 TDO
- 8 BCLK#
- 9 BCLK
- 10 GND
- 11 FBO
- 12 RESET#
- 13 GND
- 14 GND
- 15 BFM4#
- 16 GND
- 17 BFM3#
- 18 GND
- 19 BFM2#
- 20 GND
- 21 BFM1#
- 22 GND
- 23 BFM0#
- 24 DBA#
- 25 DBR#
- 26 VCC
- 27 VCC
- 28 VCC

BOM1 (Place R310 with in 200ps (~1") to CPU

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H_DINV#[3..0] <<>>H_DINV#[3..0] 8
 H_DSTBN#[3..0] <<>>H_DSTBN#[3..0] 8
 H_DSTBP#[3..0] <<>>H_DSTBP#[3..0] 8
 H_D#[63..0] <<>>H_D#[63..0] 8



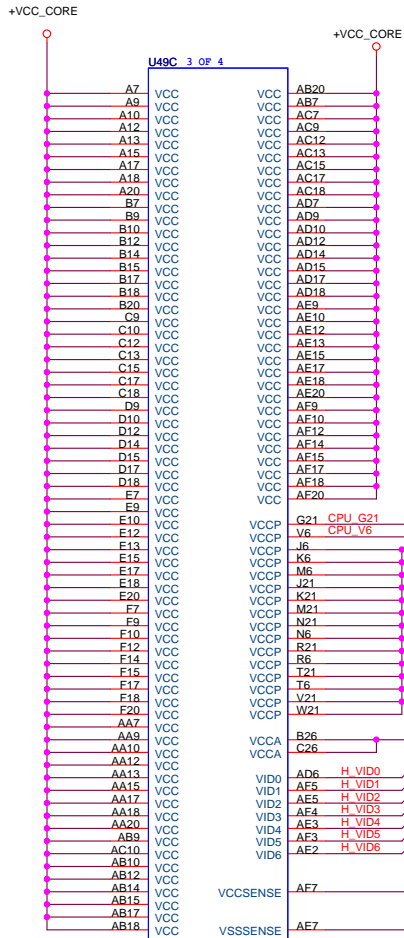
Layout notes
 Z= 55 Ohm 0.5" MAX for GTLREF

Layout Note:
 Comp0, 2 connect with Zo=27.4 ohm, make trace length shorter than 0.5" .
 Comp1, 3 connect with Zo=55 ohm, make trace length shorter than 0.5" .

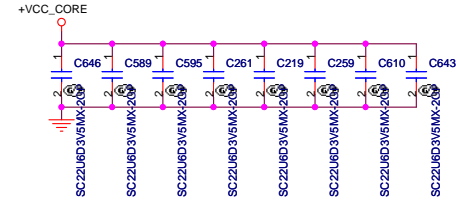
Route the TEST3 and TEST5 signals through a ground referenced Zo = 55-ohm trace that ends in a via that is near a GND via and is accessible through an oscilloscope connection.

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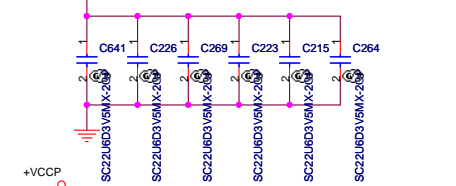
Please these inside socket cavity on L8(North side Secondary)



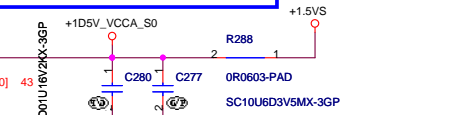
Please these inside socket cavity on L8(South side Secondary)



Please these inside socket cavity on L8(North side Primary)



layout note: "1D5V VCCA_S0" as short as possible

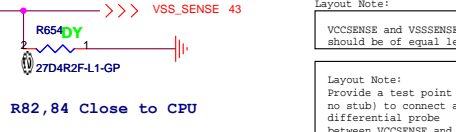


Layout Note: Place as close as possible to the CPU VCCA pin.

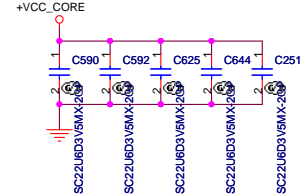
Layout Note: VCCSENSE and VSSSENSE lines should be of equal length.

Layout Note: Provide a test point (with no stub) to connect a differential probe between VCCSENSE and VSSSENSE at the location where the two 54.9ohm resistors terminate the 55 ohm transmission line.

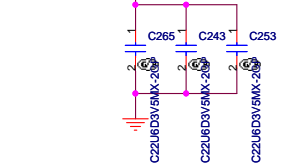
Please these inside socket cavity on L8(North side Secondary)



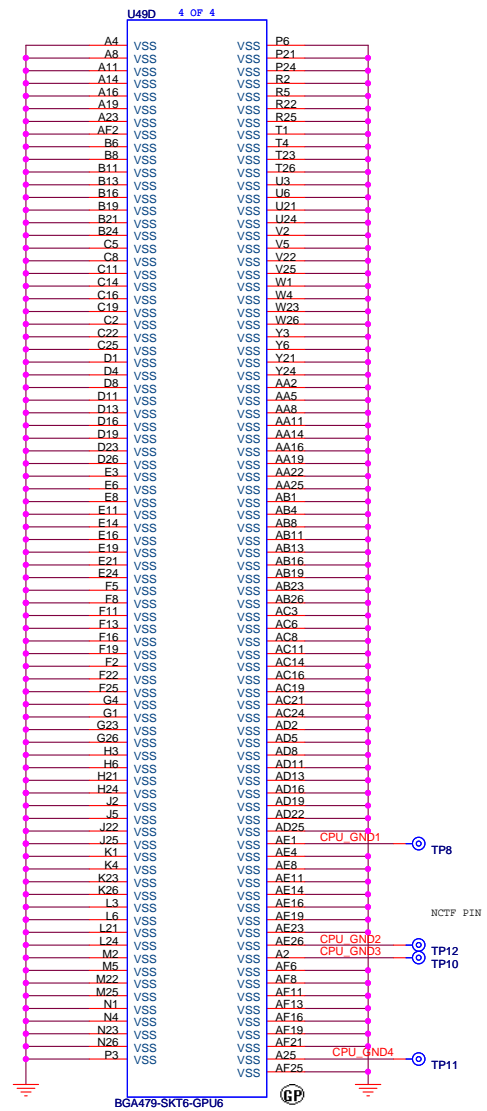
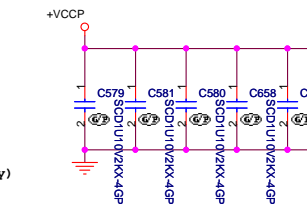
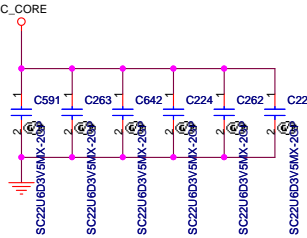
Please these outside socket cavity on L8(North side Secondary)



Please these outside socket cavity on L8(South side Secondary)

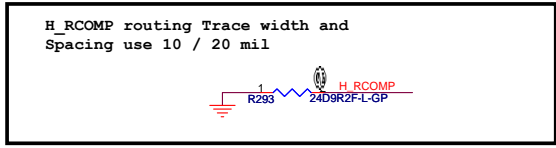
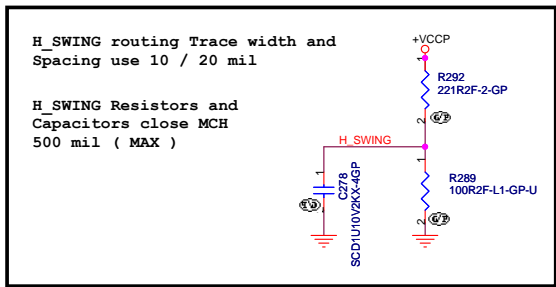


Please these inside socket cavity on L8(South side Primary)

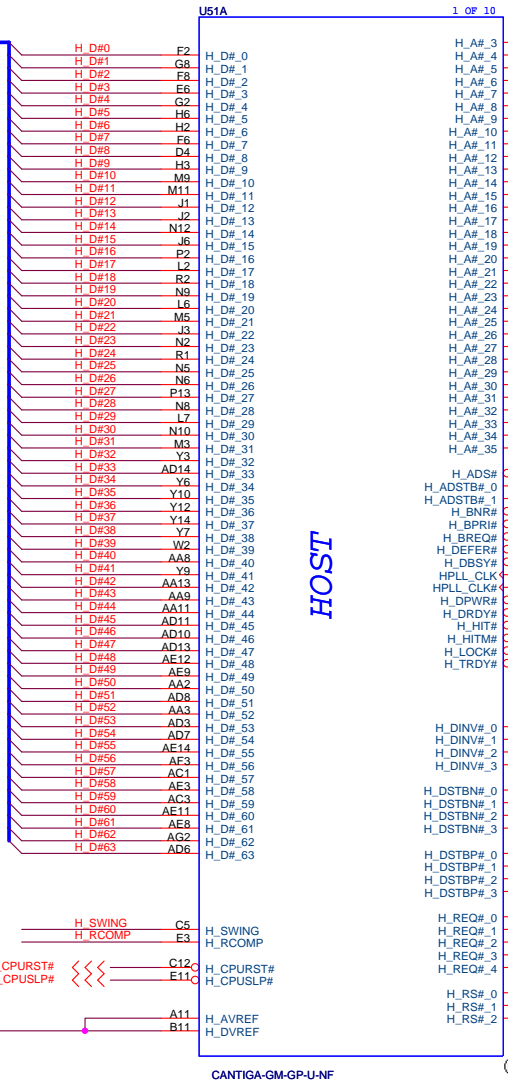
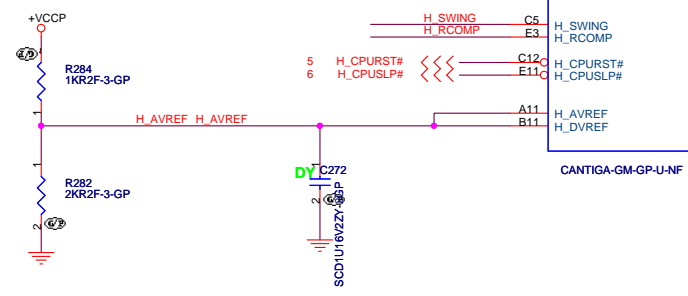


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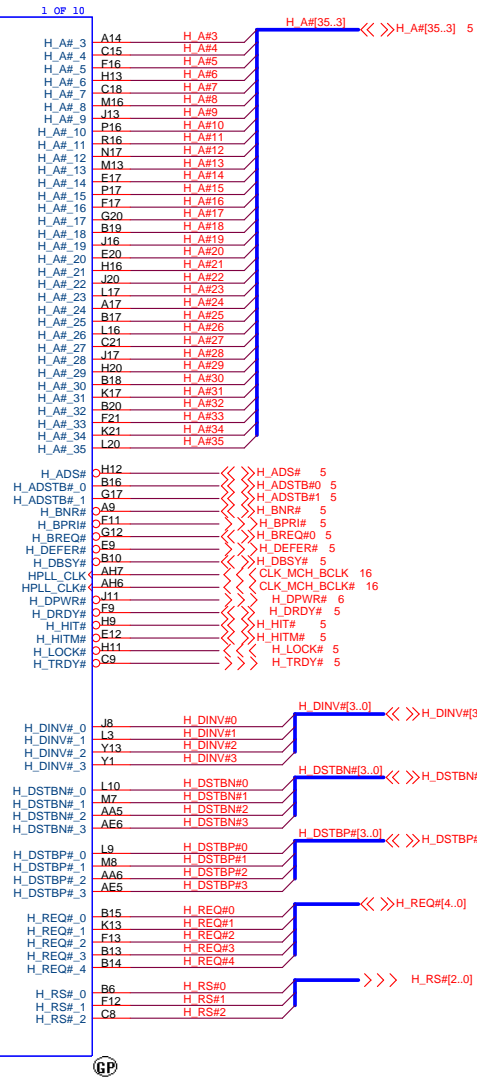
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Place them near to the chip (< 0.5")



HOST



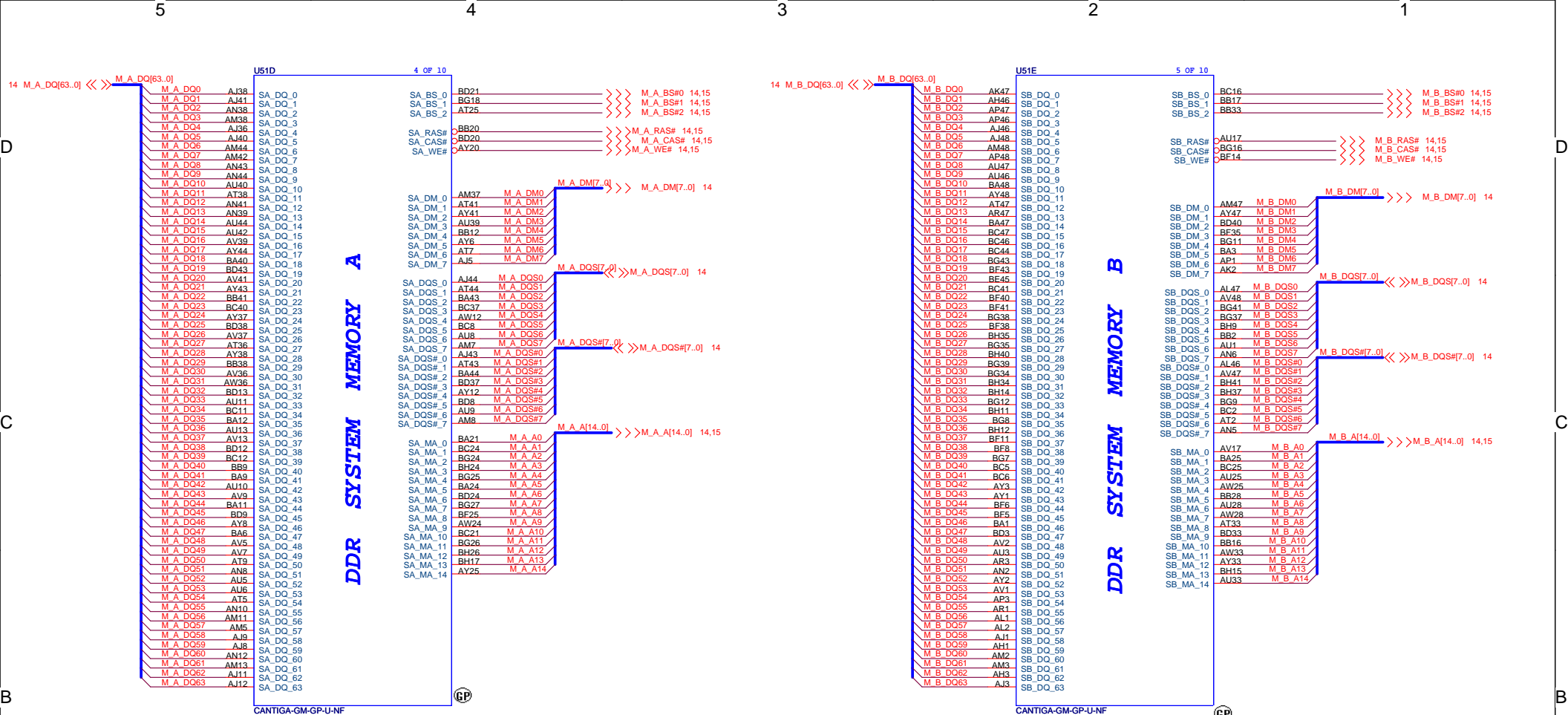
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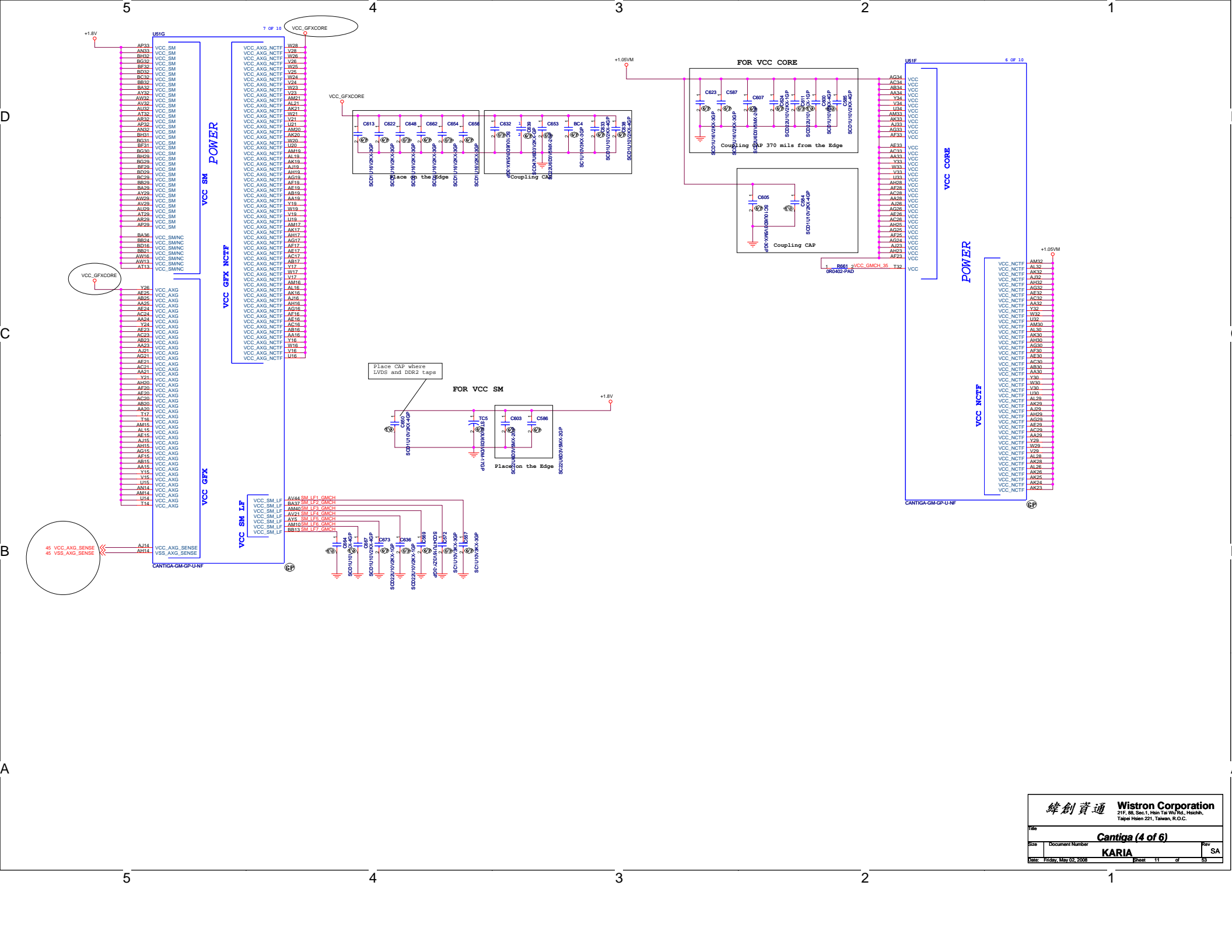
Title: **Cantiga (1 of 6)**

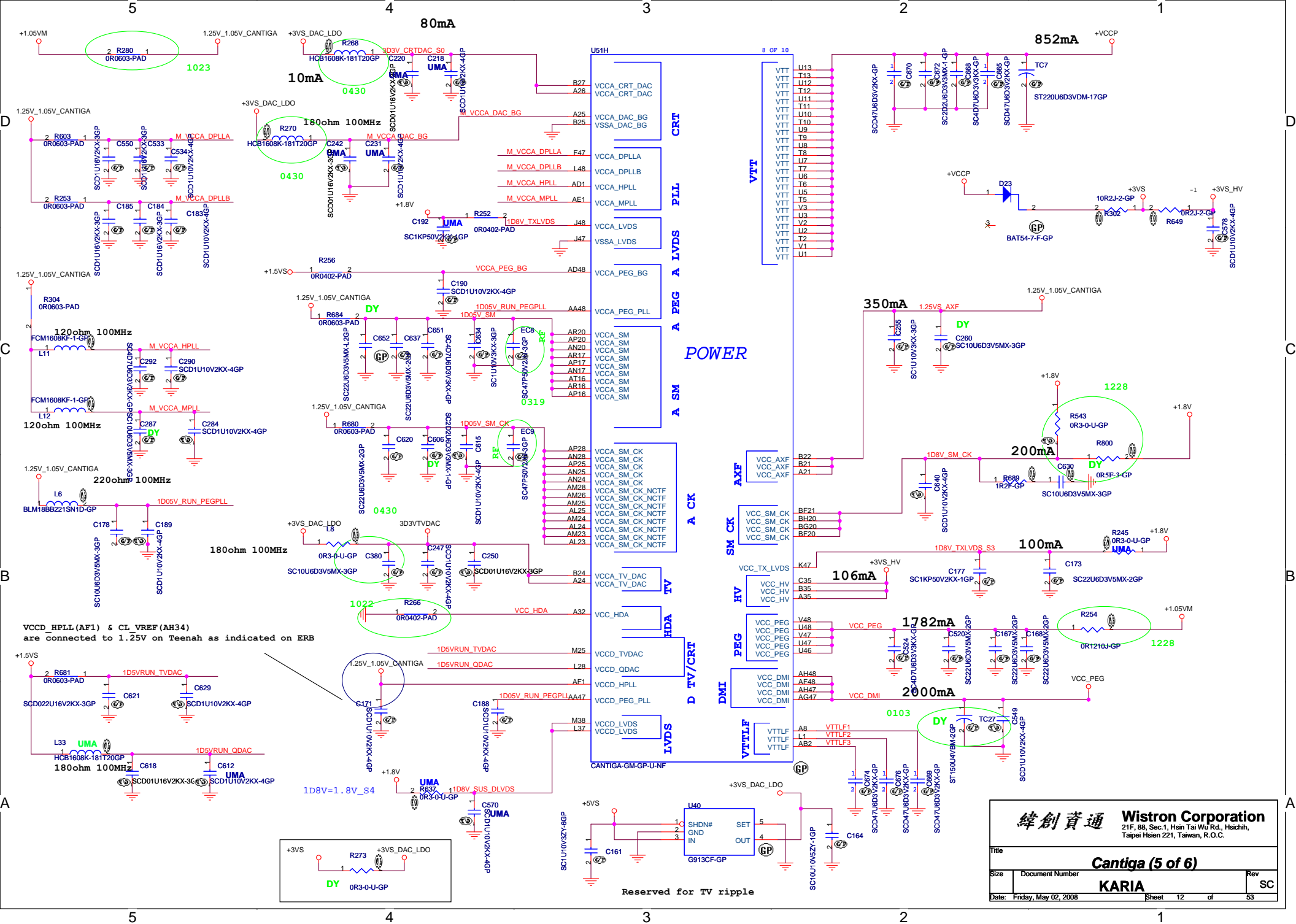
Size: Document Number: **KARIA** Rev: **SC**

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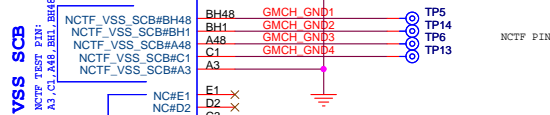
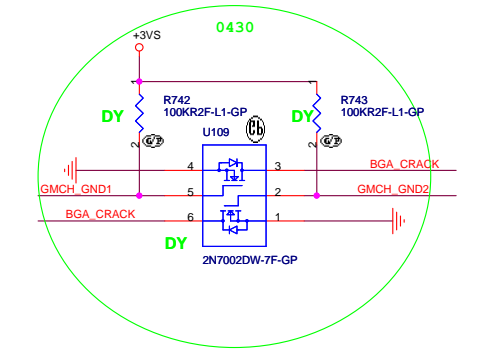
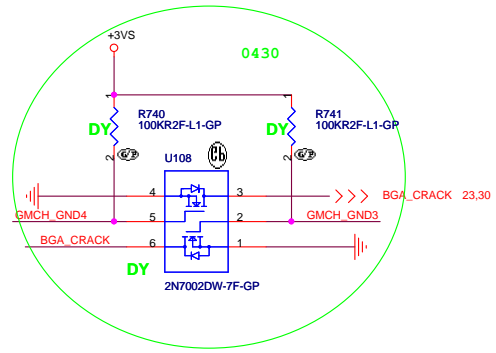
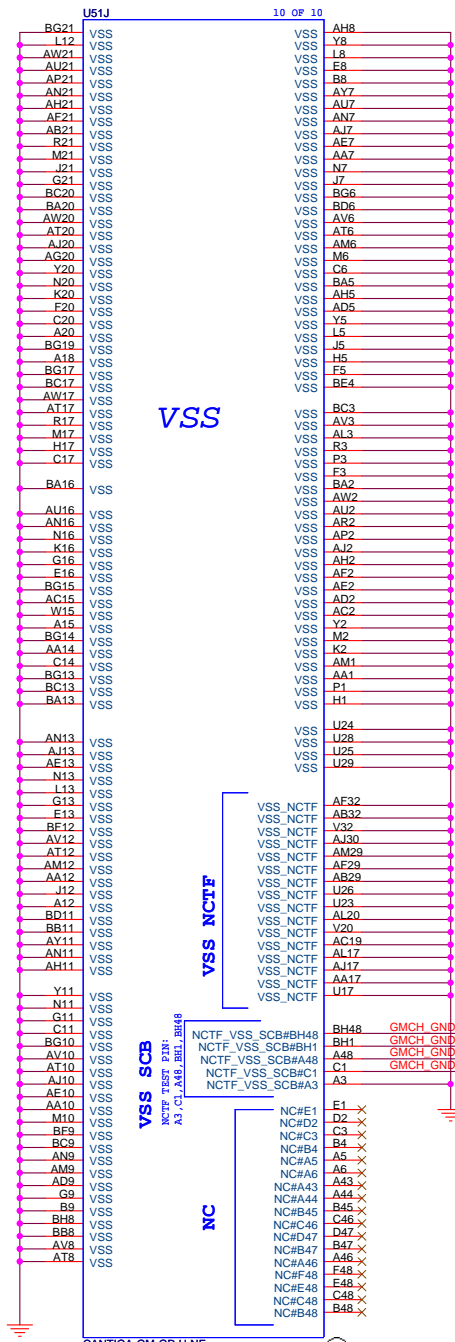
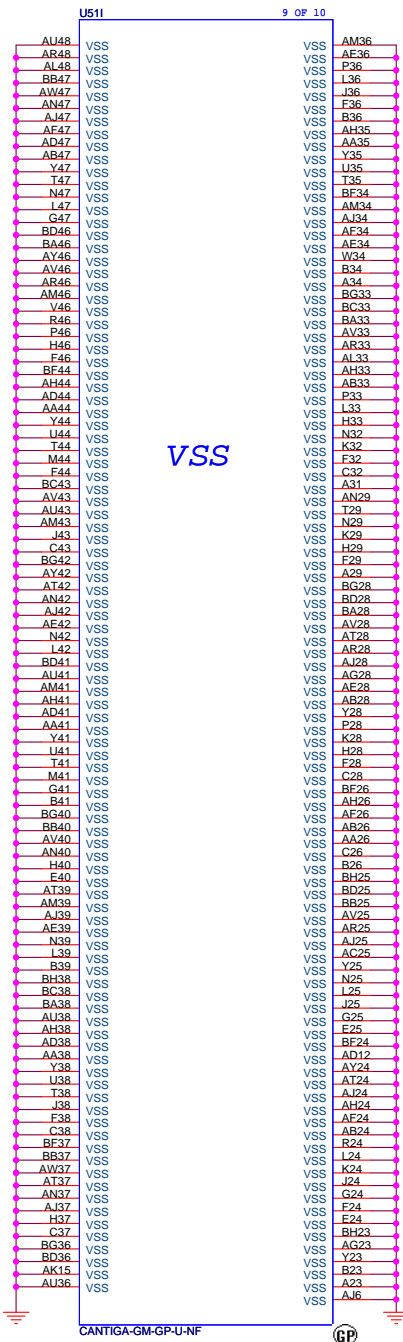


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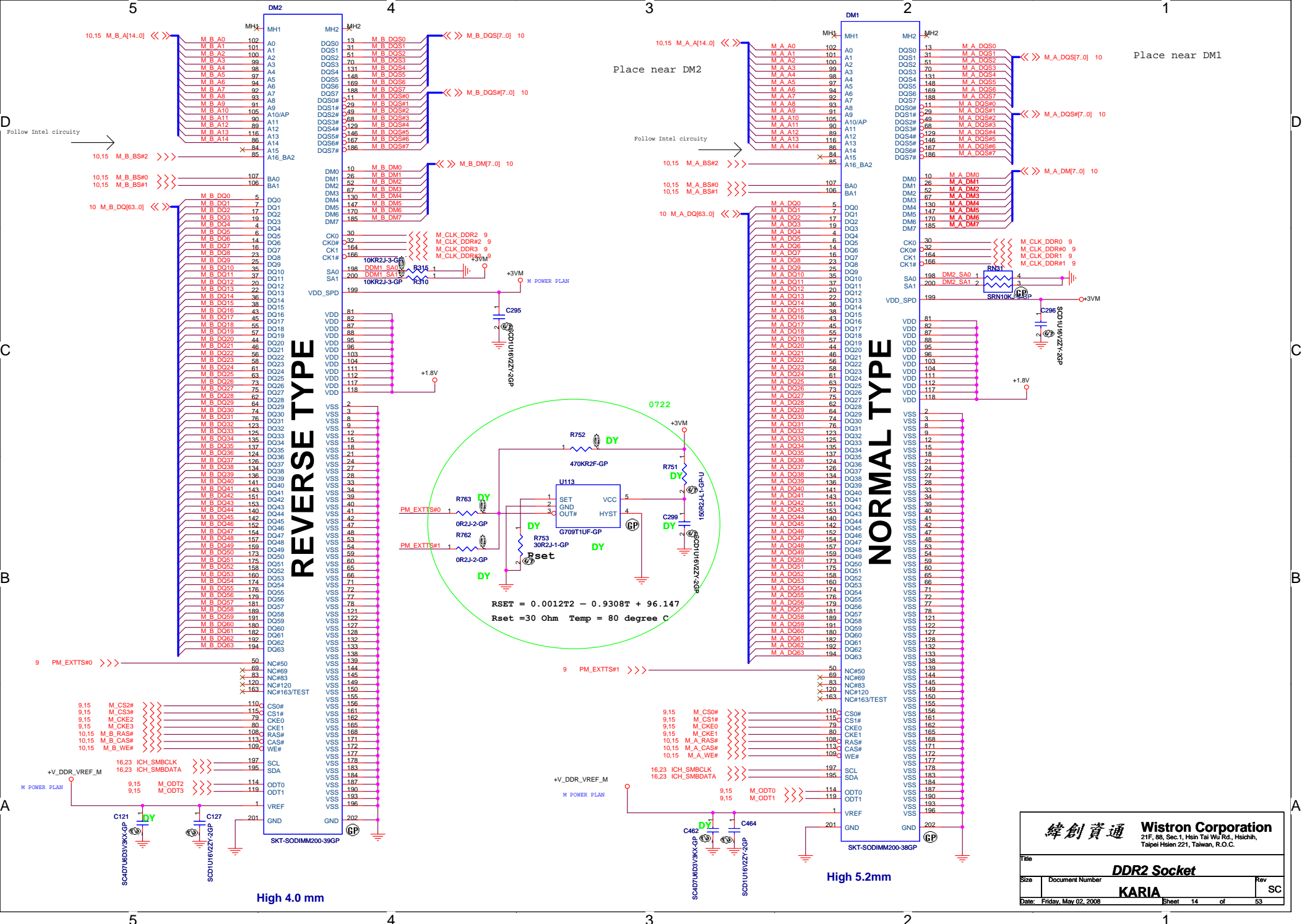


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Place near DM1

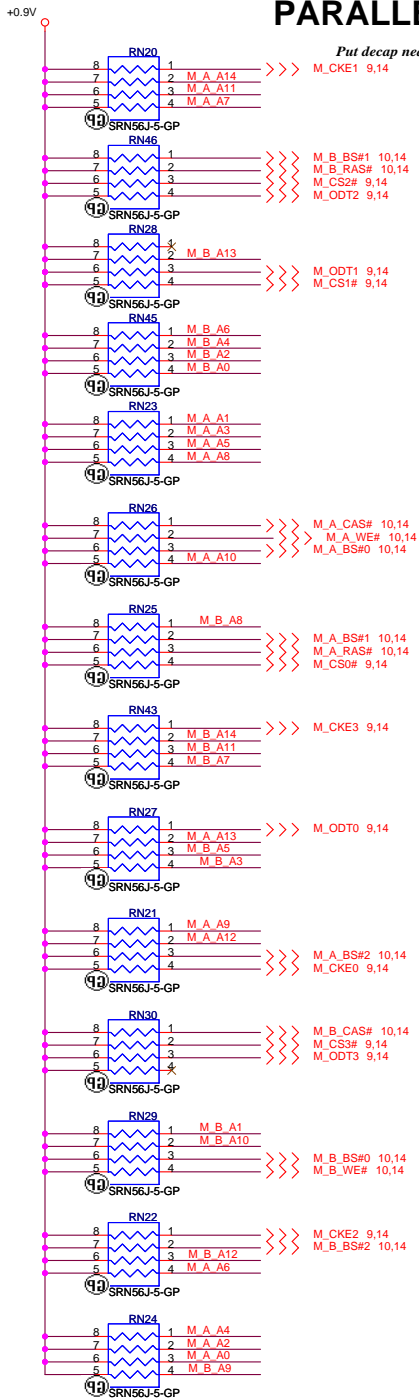
Place near DM2

High 5.2mm

High 4.0 mm

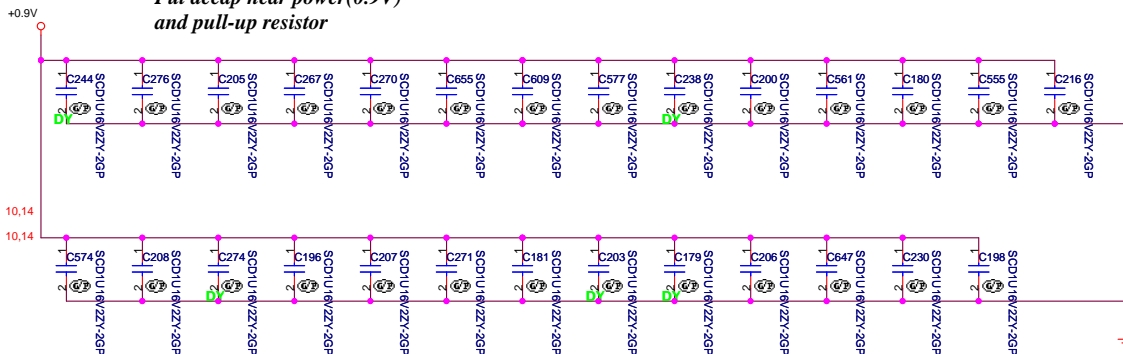
Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title: DDR2 Socket		
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PARALLEL TERMINATION



Put decap near power(0.9V) and pull-up resistor

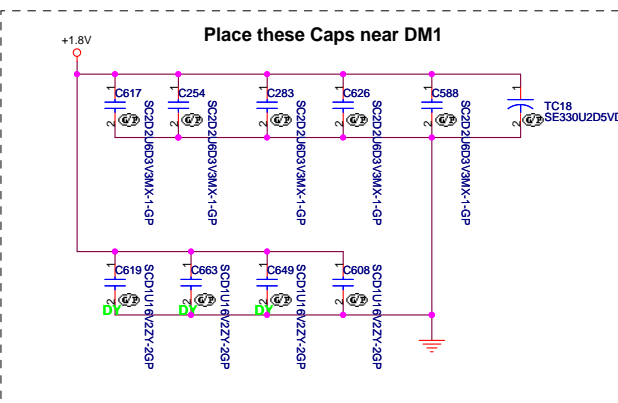
Put decap near power(0.9V) and pull-up resistor



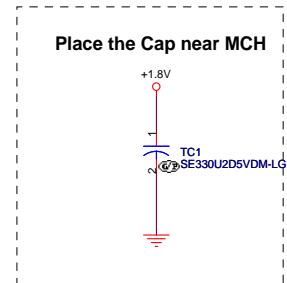
M_A [A14..0] <<< M_A_A[14..0] 10,14
M_B [A14..0] <<< M_B_A[14..0] 10,14

Decoupling Capacitor

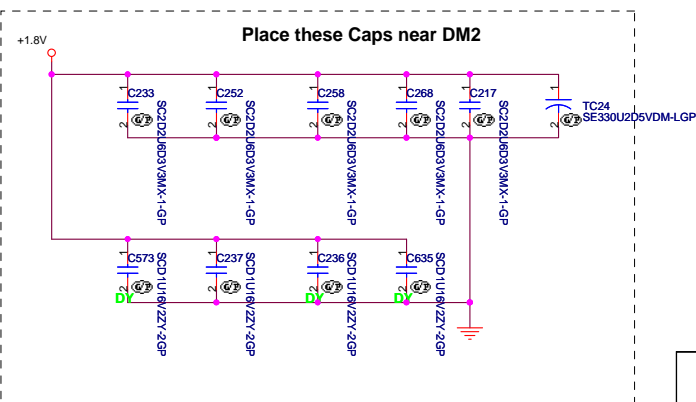
Place these Caps near DM1



Place the Cap near MCH

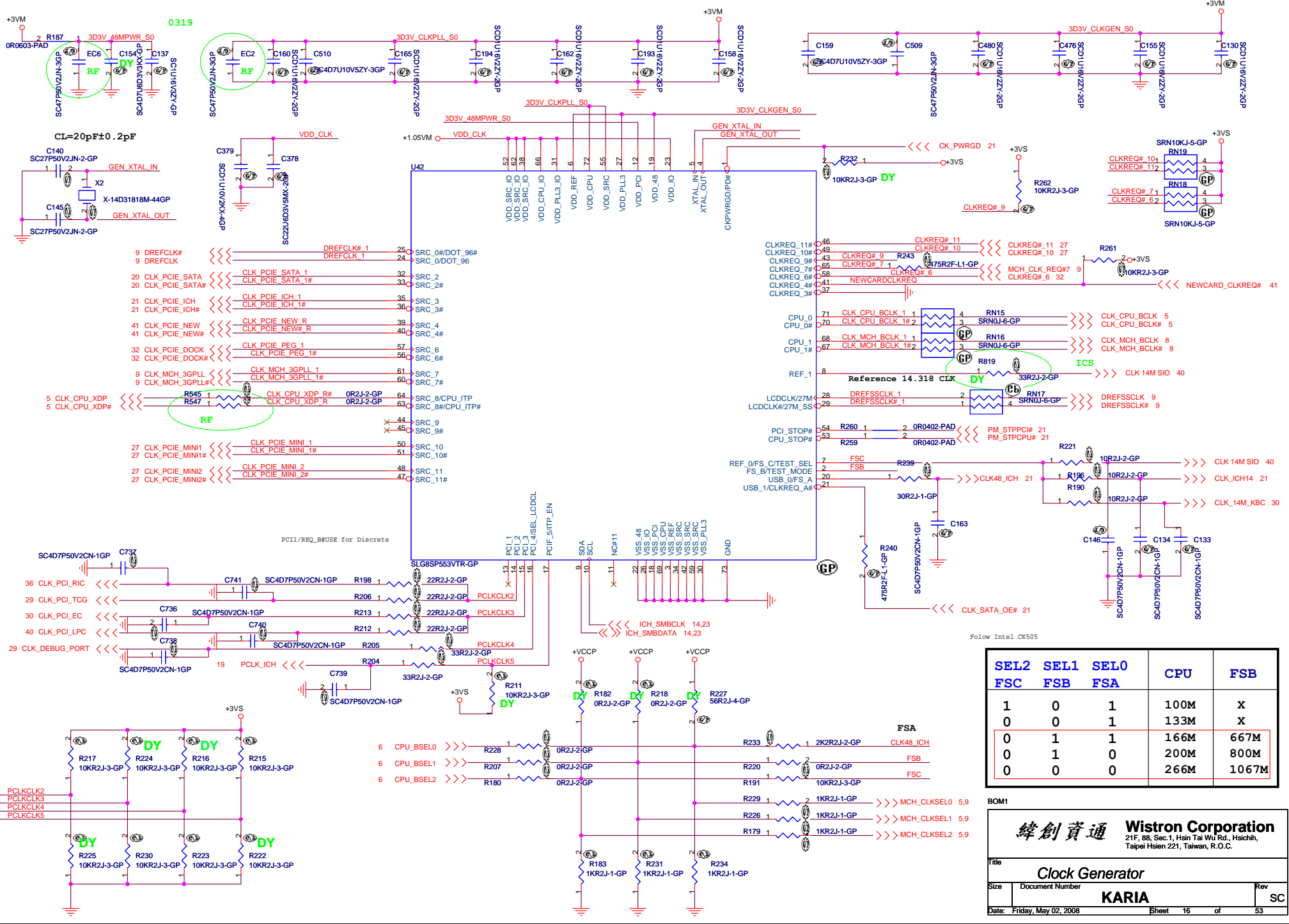


Place these Caps near DM2



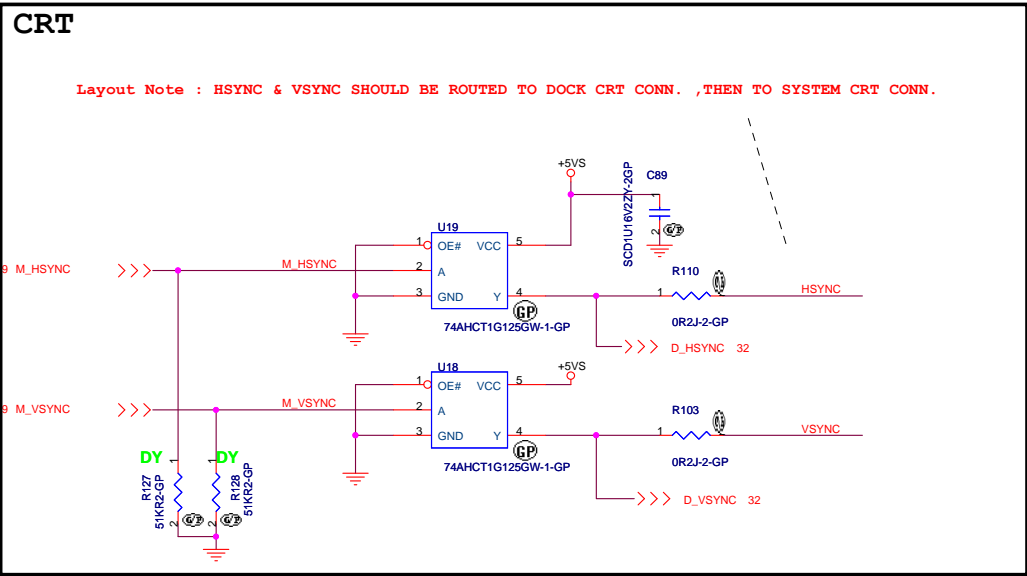
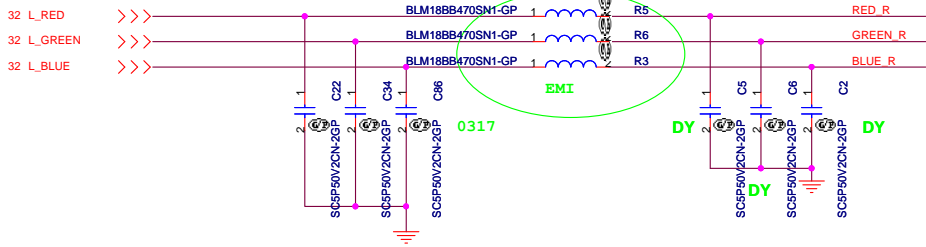
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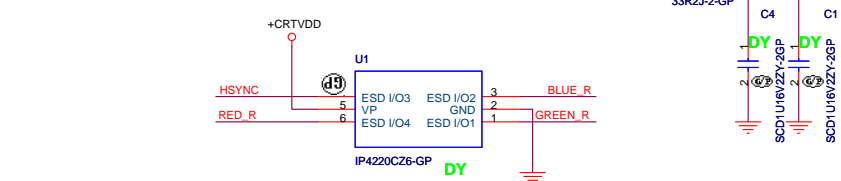
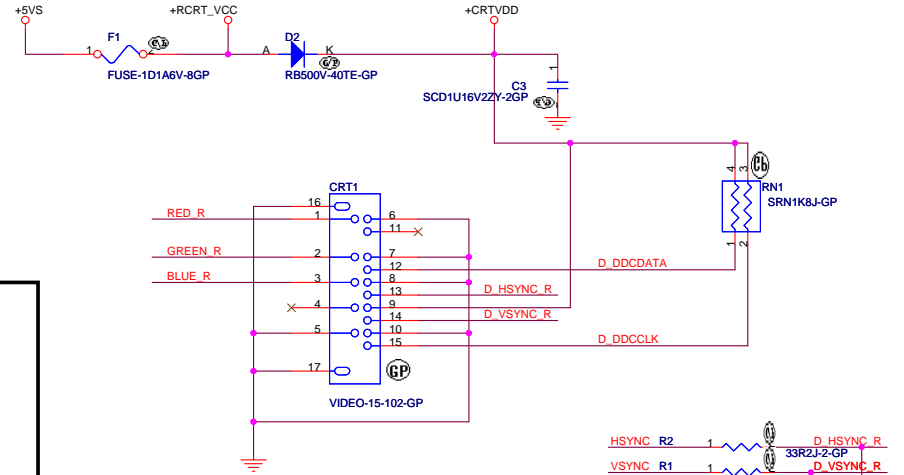


SEL2	SEL1	SEL0	CPU	FSB
FSC	FSB	FSA	100M	X
0	0	1	133M	X
0	1	1	166M	667M
0	1	0	200M	800M
0	0	0	266M	1067M

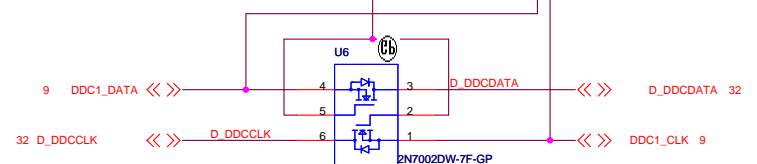
BOM1
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DEL TV connector 1022



PLACE CLOSE TO CRT1
PLACE CLOSE TO DOCKING CONN

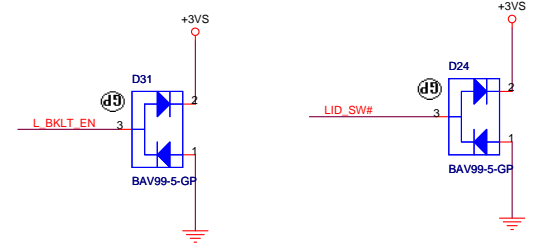
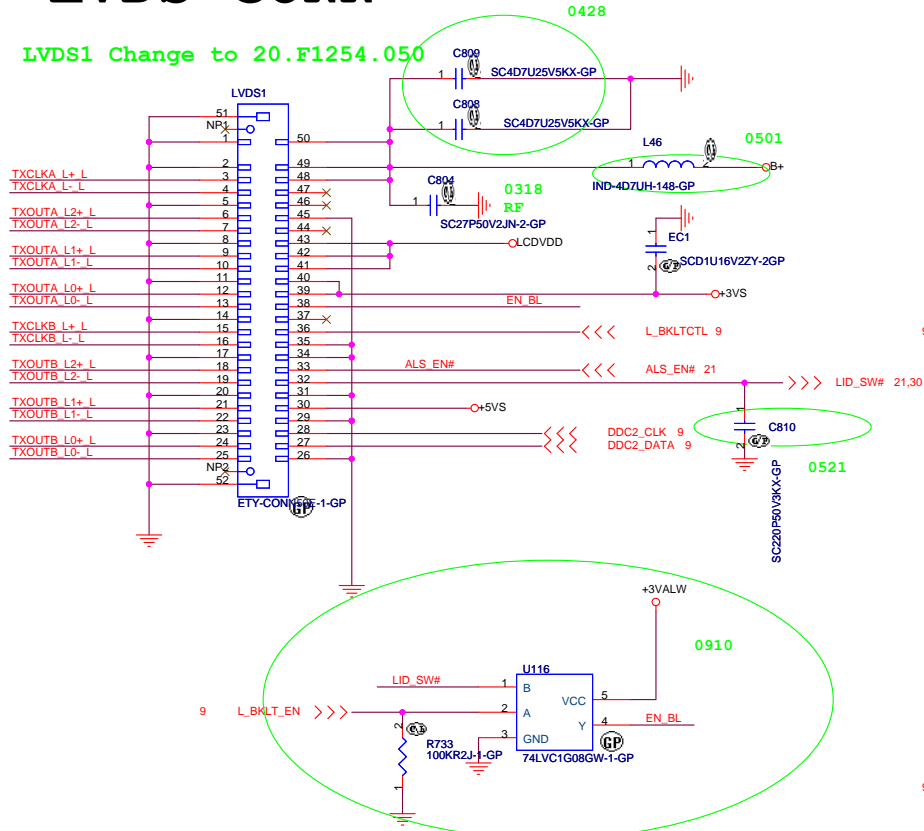


BOM1

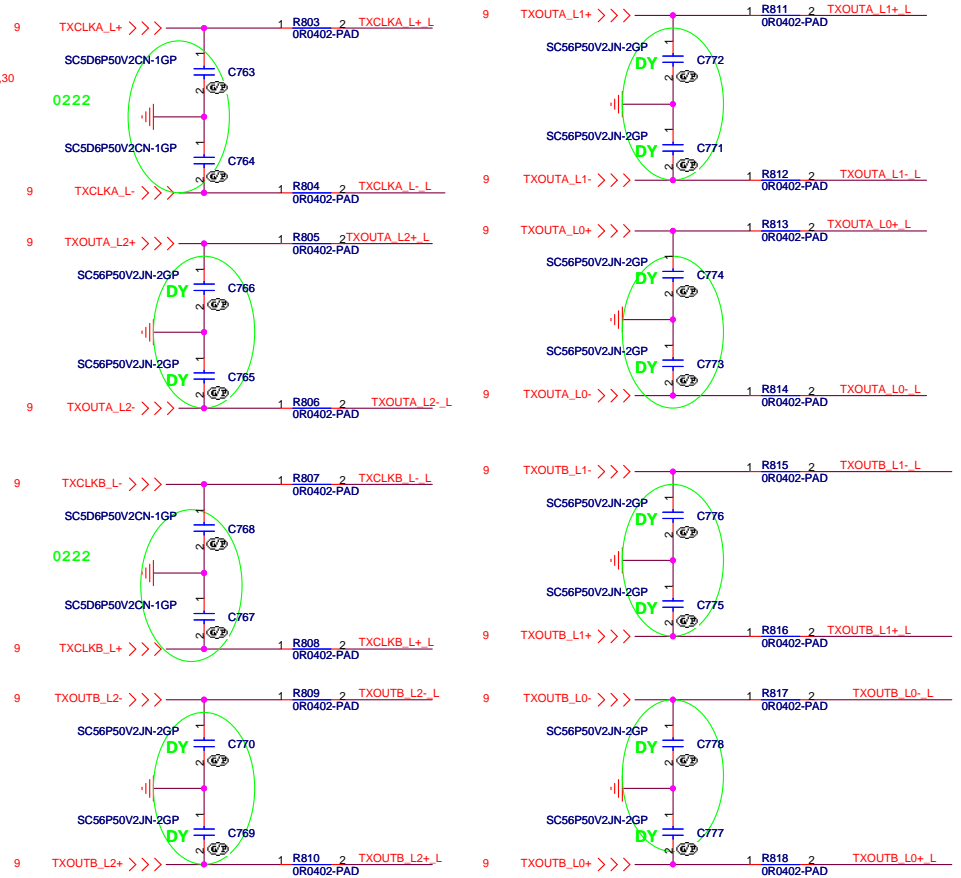
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Title		
CRT CONNECTOR		
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LVDS CONN

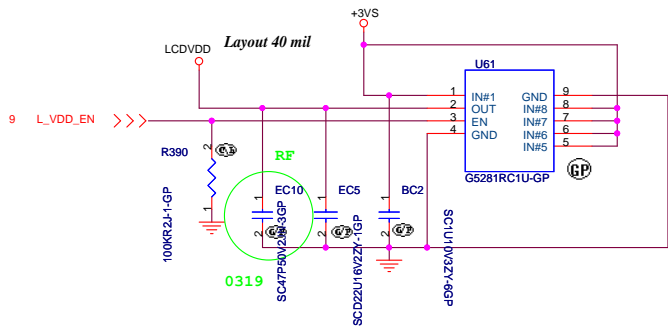
LVDS1 Change to 20.F1254.050



0920 RF request

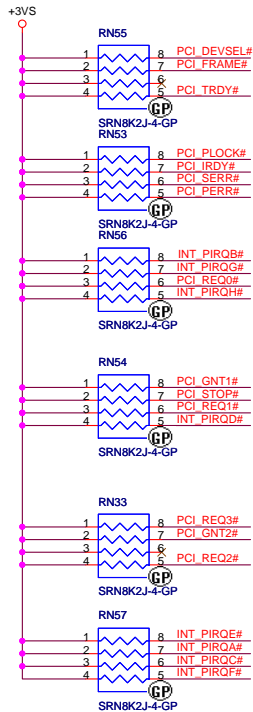


LCD POWER CIRCUIT

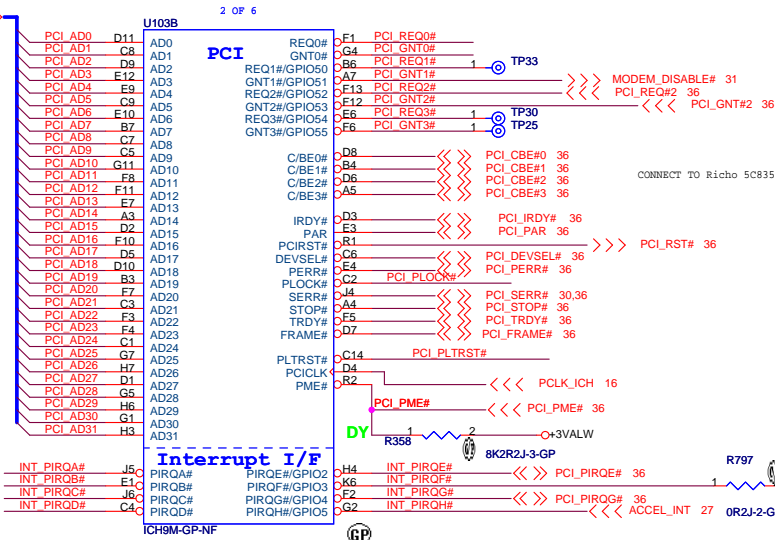


BOM1

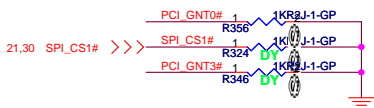
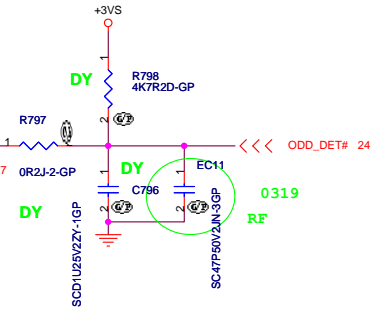
緯創資通 Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
LCD CONN.	
Size A3	Document Number KARIA
Date: Friday, May 23, 2008	Rev SC
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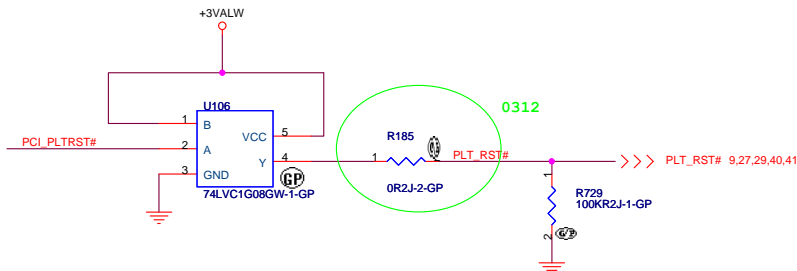
36 PCI_AD[31..0] <<>>



CONNECT TO Richo 5c835

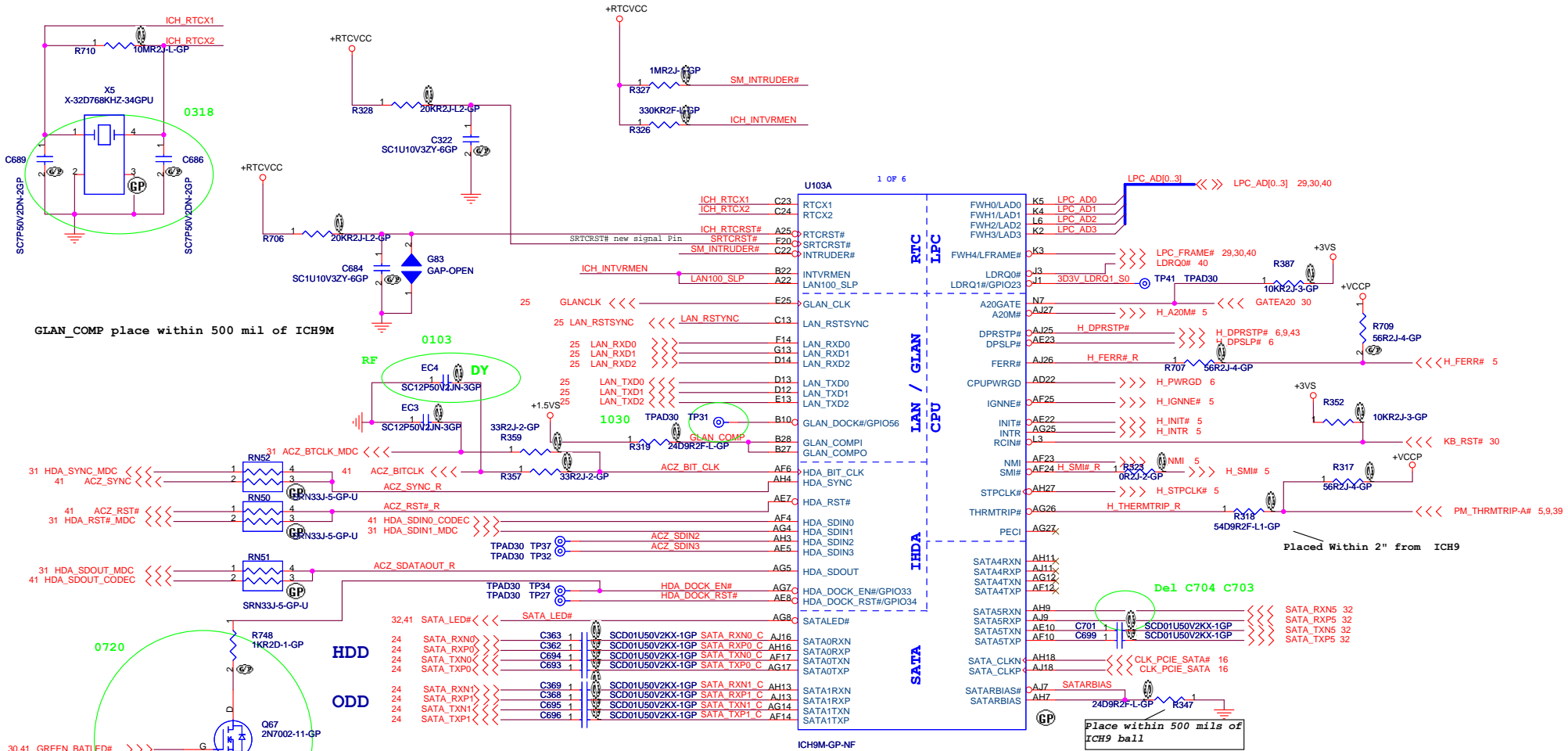


BOOT BIOS Strap		
PCI_GNT#0	SPI_CS#1	BOOT BIOS Location
0	1	SPI
1	0	PCI
1	1	EEP(Defaulst)
A16 swap override strap		
PCI_GNT#3	low = A16 swap override enable	high = default



BOM1

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Title	
ICH9-M (1 of 5)	
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KARIA	
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integrated VccSus1_05,VccSus1_5,VccCl1_5		
INTVRMEN	High=Enable	Low=Disable
integrated VccLan1_05VccCl1_05		
LAN100_SLP	High=Enable	Low=Disable

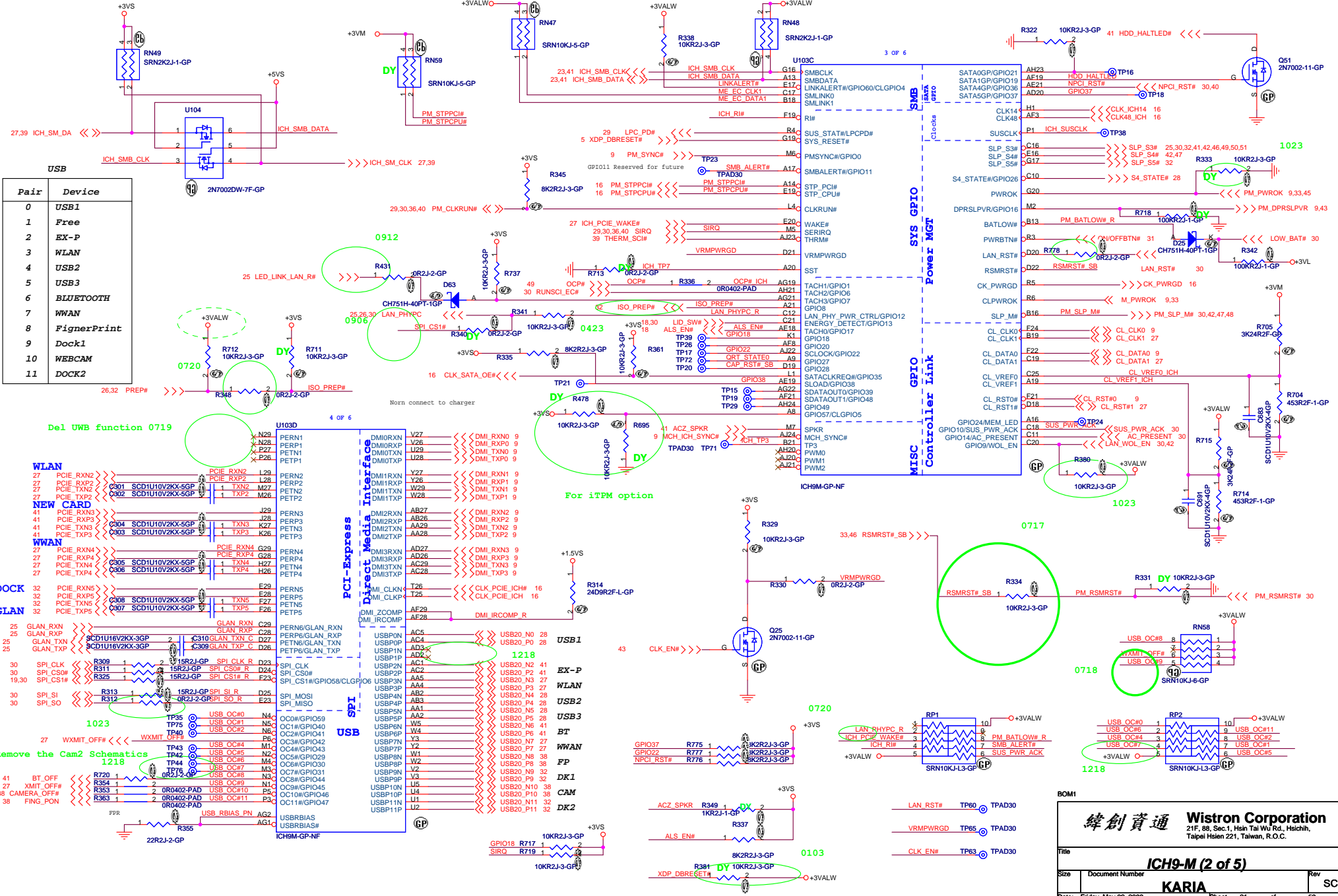
BOM1

緯創資通 Wistron Corporation
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File: **ICH9-M (2 of 5)**

Size: _____ Document Number: **KARIA** Rev: **SC**

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Pair	Device
0	USB1
1	Free
2	EX-P
3	WLAN
4	USB2
5	USB3
6	BLUETOOTH
7	WWAN
8	FingerPrint
9	Dock1
10	WEBCAM
11	DOCK2

- Del UWB function 0719**
- WLAN
 - 27 PCIE_RXN2
 - 27 PCIE_RXP2
 - 27 PCIE_TXN2
 - 27 PCIE_TXP2
 - NEW CARD
 - 41 PCIE_RXN3
 - 41 PCIE_RXP3
 - 41 PCIE_TXN3
 - 41 PCIE_TXP3
 - WWAN
 - 27 PCIE_RXN4
 - 27 PCIE_RXP4
 - 27 PCIE_TXN4
 - 27 PCIE_TXP4
 - DOCK
 - 32 PCIE_RXN5
 - 32 PCIE_RXP5
 - 32 PCIE_TXN5
 - 32 PCIE_TXP5
 - GLAN
 - 25 GLAN_RXN
 - 25 GLAN_RXP
 - 25 GLAN_TXN
 - 25 GLAN_TXP
 - SPI
 - 30 SPI_CLK
 - 30 SPI_CS0#
 - 30 SPI_CS1#
 - 30 SPI_SI
 - 30 SPI_SO

Remove the Cam2 Schematics 1218

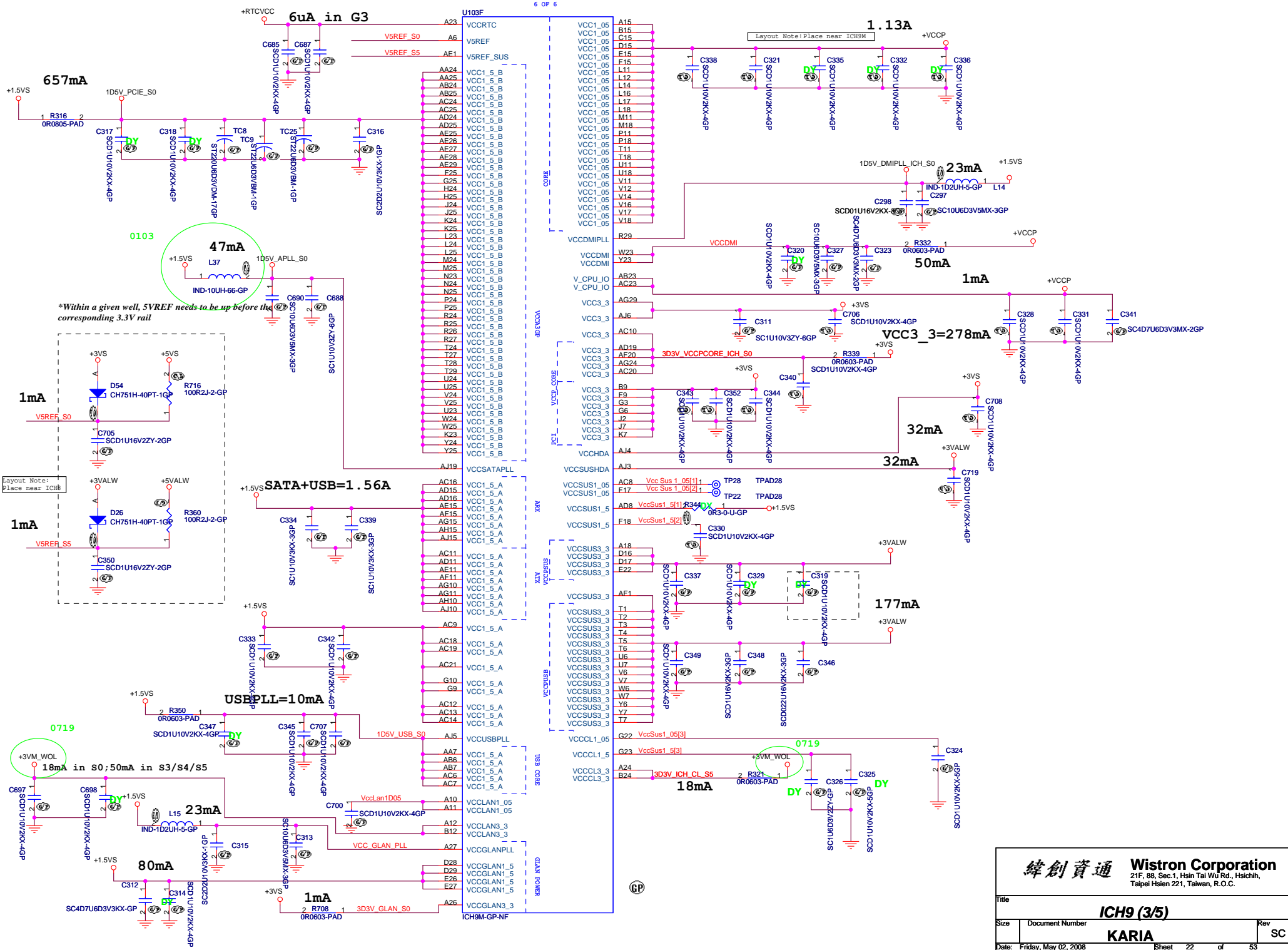
- 41 BT_OFF
- 27 XMIT_OFF#
- 38 CAMERA_OFF#
- 38 FING_PON

緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

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KARIA

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緯創資通 Wistron Corporation
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 Taipei Hsien 221, Taiwan, R.O.C.

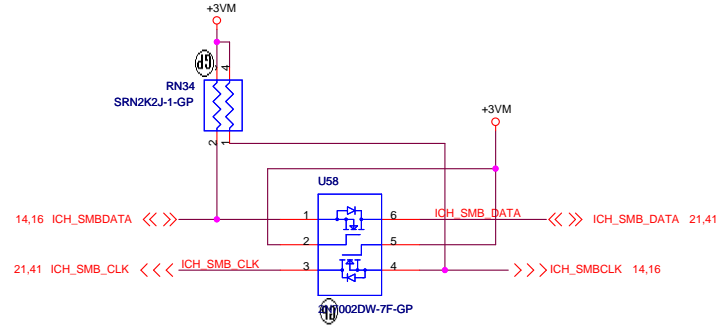
File	ICH9 (3/5)		Rev	SC
Size	Document Number			
KARIA				
Date:	Friday, May 02, 2008	Sheet	22	of 53

5 OF 6

AA26	VSS	H5
AA27	VSS	J23
AA3	VSS	J26
AA6	VSS	J27
AB1	VSS	AC22
AA23	VSS	K28
AB28	VSS	K29
AB29	VSS	L13
AB4	VSS	L15
ABS	VSS	L2
AC17	VSS	L26
AC26	VSS	L27
AC27	VSS	L5
AC3	VSS	L7
AD1	VSS	M12
AD10	VSS	M13
AD12	VSS	M14
AD13	VSS	M15
AD14	VSS	M16
AD17	VSS	M17
AD18	VSS	M23
AD21	VSS	M28
AD28	VSS	M29
AD29	VSS	N11
AD4	VSS	N12
AD5	VSS	N13
AD6	VSS	N14
AD7	VSS	N15
AD9	VSS	N16
AE12	VSS	N17
AE13	VSS	N18
AE14	VSS	N26
AE16	VSS	N27
AE17	VSS	P12
AE2	VSS	P13
AE20	VSS	P14
AE24	VSS	P15
AE3	VSS	P16
AE4	VSS	P17
AE6	VSS	P2
AE9	VSS	P23
AF13	VSS	P28
AF16	VSS	P29
AF18	VSS	P4
AF22	VSS	P7
AH26	VSS	R11
AF28	VSS	R12
AF27	VSS	R13
AF5	VSS	R14
AF7	VSS	R15
AF9	VSS	R16
AG13	VSS	R17
AG16	VSS	R18
AG18	VSS	R28
AG20	VSS	T12
AG23	VSS	T13
AG31	VSS	T14
AG6	VSS	T15
AG9	VSS	T16
AH12	VSS	T17
AH14	VSS	T23
AH17	VSS	B26
AH19	VSS	U12
AH2	VSS	U13
AH22	VSS	U14
AH25	VSS	U15
AH28	VSS	U16
AH5	VSS	U17
AH8	VSS	AD23
AJ12	VSS	U26
AJ14	VSS	U27
AJ17	VSS	U3
AJ8	VSS	V1
B11	VSS	V13
B14	VSS	V15
B17	VSS	V23
B2	VSS	V28
B20	VSS	V29
B23	VSS	V4
B5	VSS	V5
B8	VSS	W26
C26	VSS	W27
C27	VSS	W3
E11	VSS	Y1
E14	VSS	Y28
E18	VSS	Y29
E2	VSS	Y4
E21	VSS	Y5
E24	VSS	AG28
E5	VSS	AH6
E8	VSS	AF2
F16	VSS	B25
F28	VSS	
F29	VSS	A1 ICH_GND1 TP74
G12	VSS	A2
G14	VSS	A28
G18	VSS	A29 ICH_GND2 TP69
G21	VSS	AH1
G24	VSS	AH28
G26	VSS	AJ1 ICH_GND3 TP73
G27	VSS	AJ2
G8	VSS	AJ28
H2	VSS	AJ29 ICH_GND4 TP70
H23	VSS	B1
H28	VSS	B29
H29	VSS	

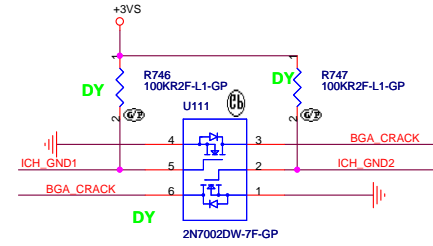
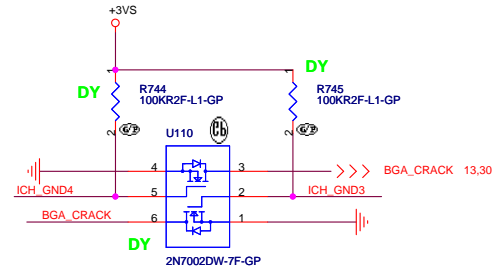
IC98M-GP-NF

NCTF PIN



Q13 & Q14 connect SMLINK and SMBUS in S) for SMBus 2.0 compliance

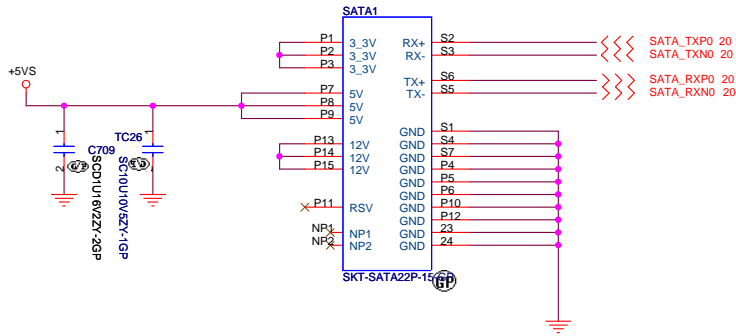
SMBUS



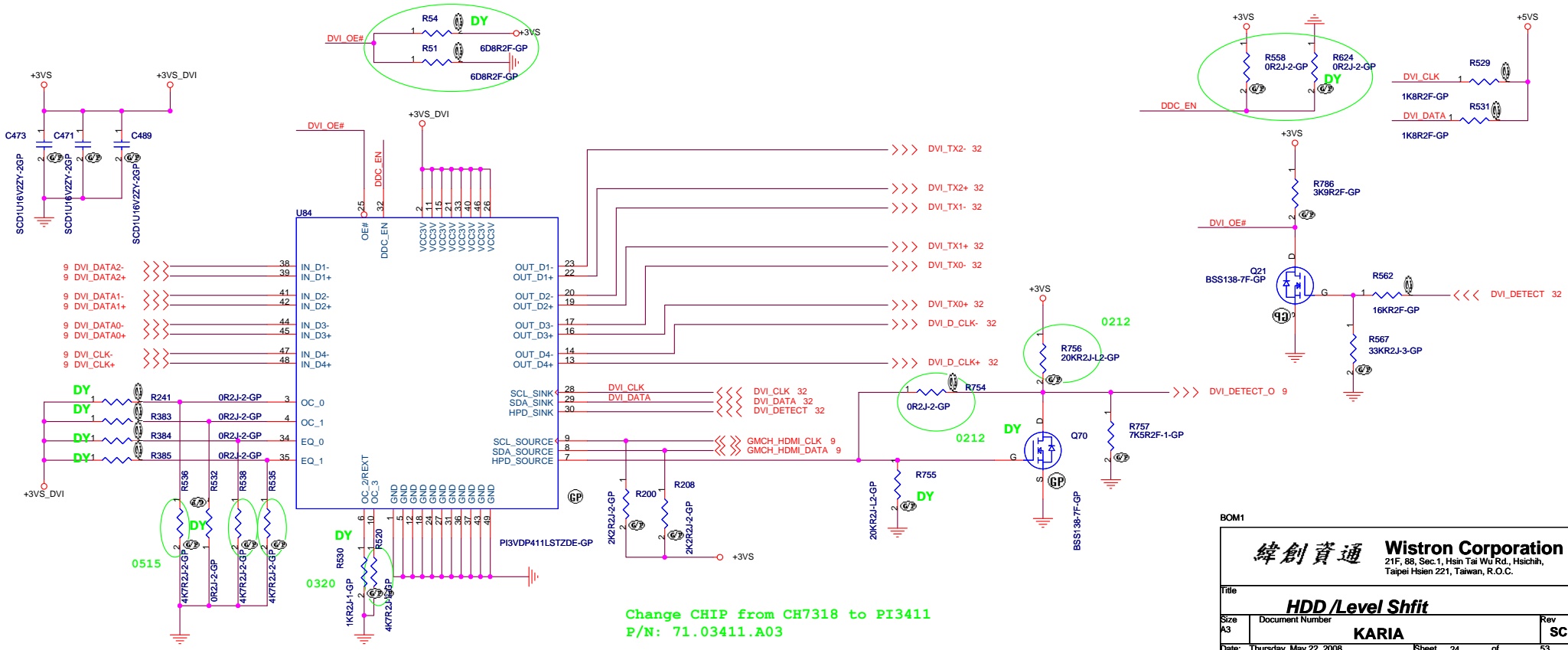
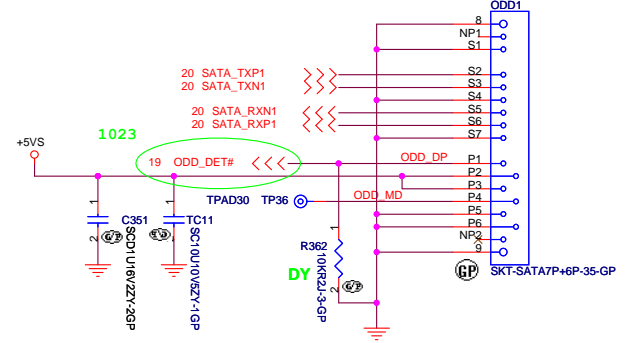
緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title ICH9-M (4 of 4)			
Size	Document Number	Rev	
	KARIA	SC	
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SATA HD Connector

SATA1 Change to 22.10300.251



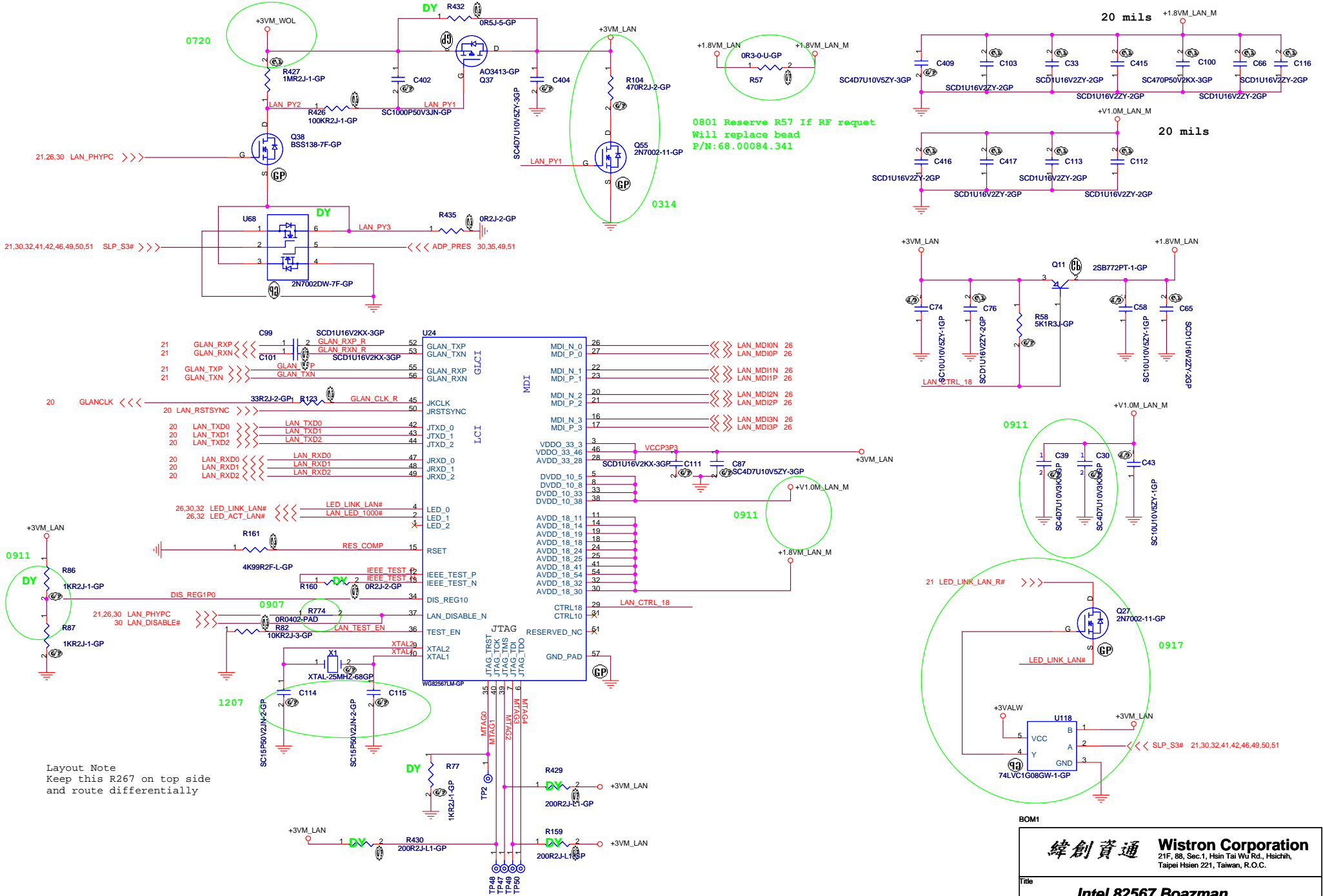
ODD Connector



Change CHIP from CH7318 to PI3411
P/N: 71.03411.A03

BOM1

		Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichin, Taipei Hsin 221, Taiwan, R.O.C.	
Title: HDD /Level Shift			
Size: A3	Document Number:	Rev: SC	
Date: Thursday, May 22, 2008	Sheet: 24	of:	53

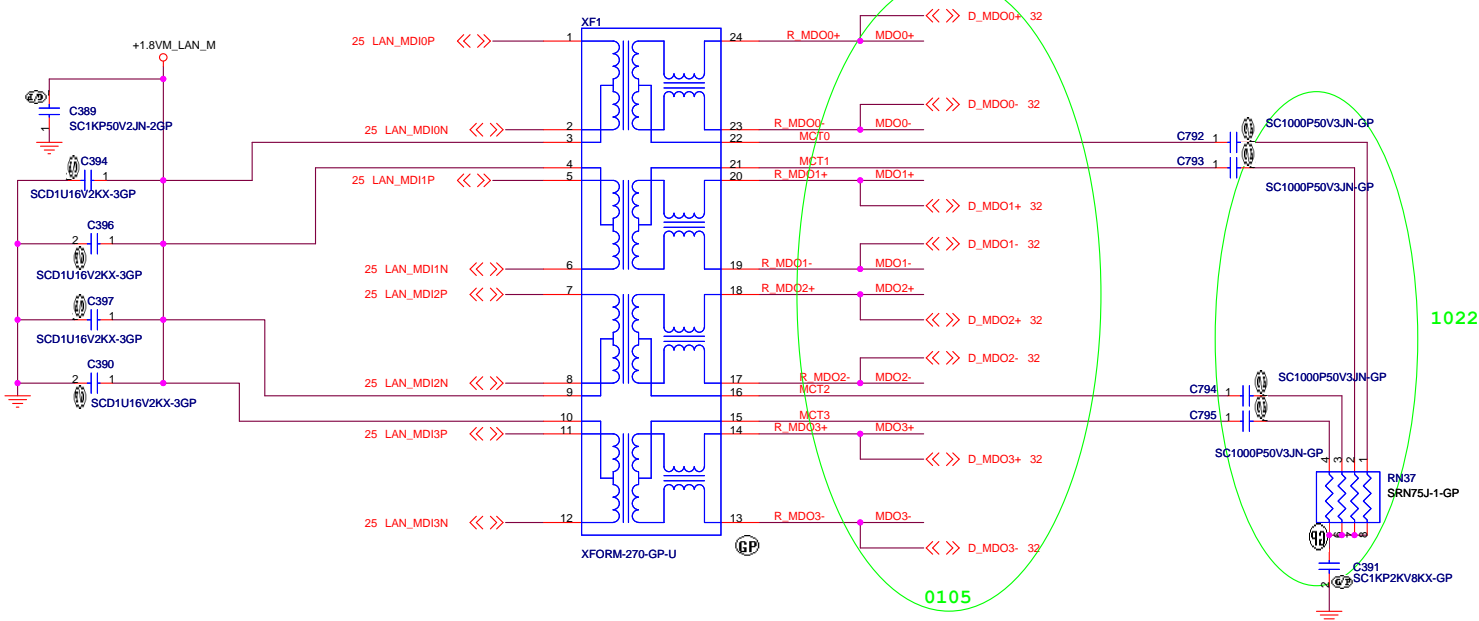


Layout Note
Keep this R267 on top side
and route differentially

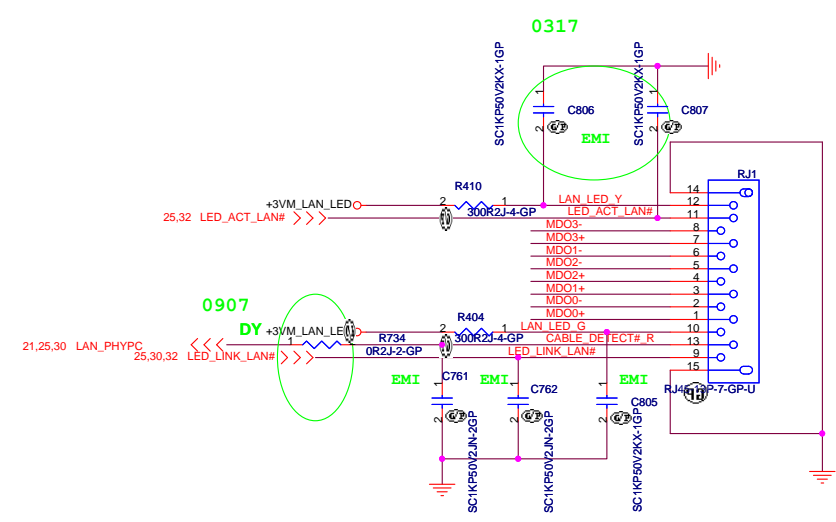
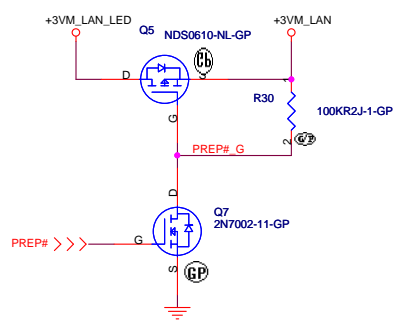
BOM1

緯創資通 Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title: Intel 82567 Boazman		
Size A3	Document Number	Rev PV
KARIA		
Date: Sunday, May 18, 2008	Sheet 25	of 53

Note : MDO[3..0]++ signals should route to RJ45 first then to DOCK CONN .



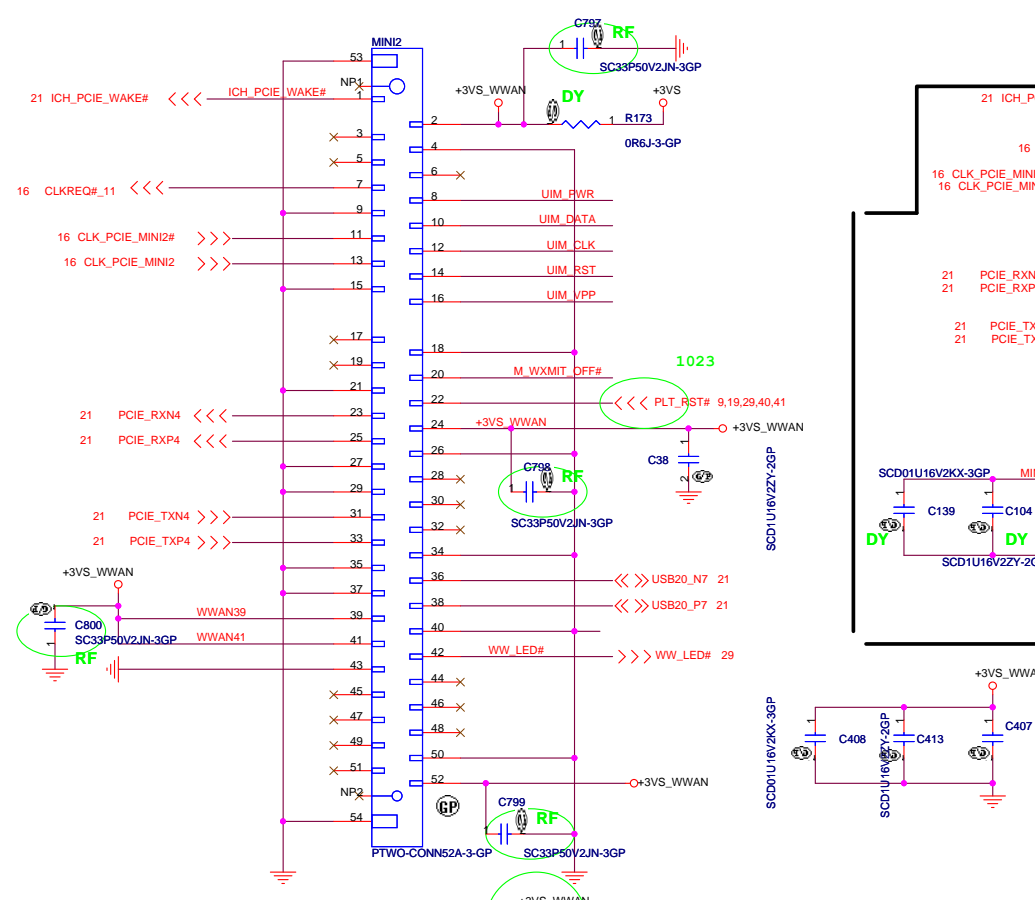
LAN ENERGY DET



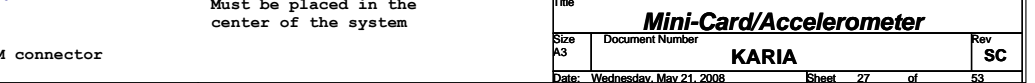
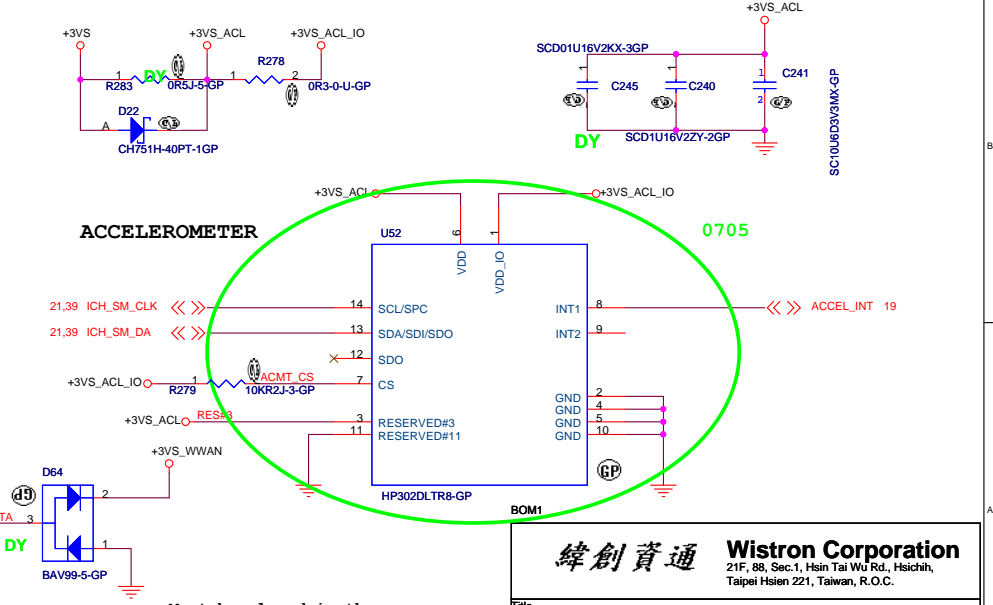
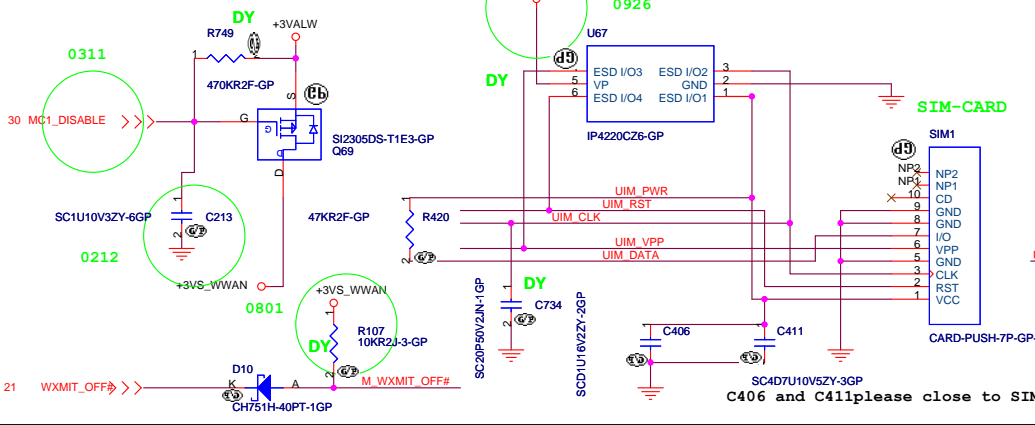
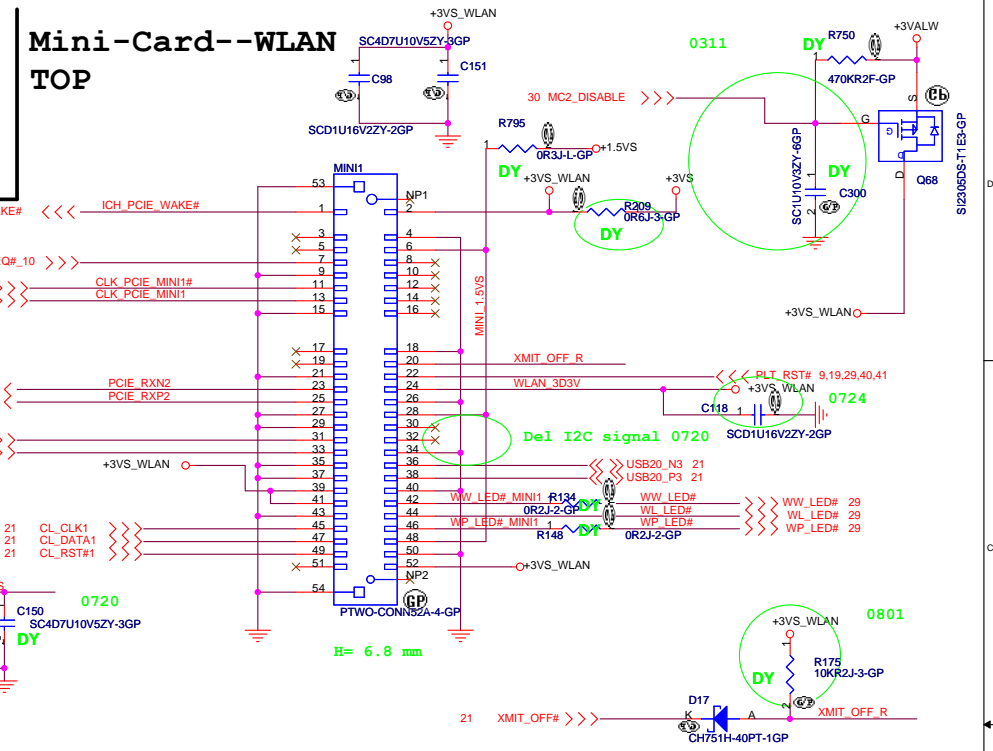
20 mils

BOM1	
緯創資通 Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
Magnetic & RJ45	
Size	Document Number
A3	KARIA
Date: Friday, May 02, 2008	Rev SC
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Mini-Card--WWAN Bottom



Mini-Card--WLAN TOP

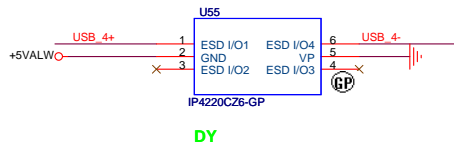
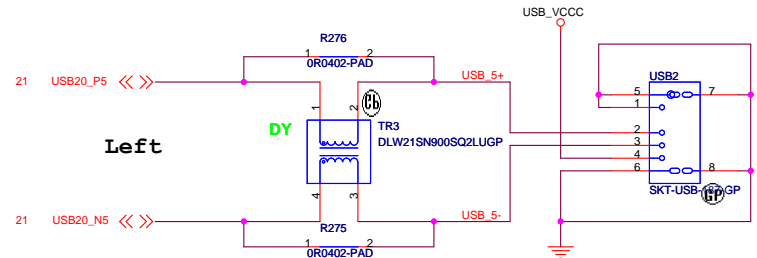
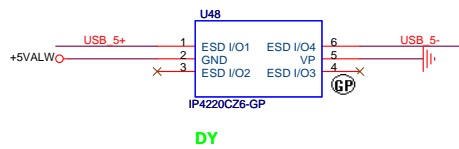
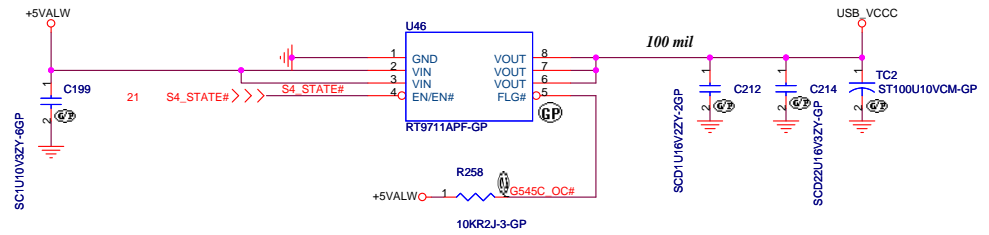
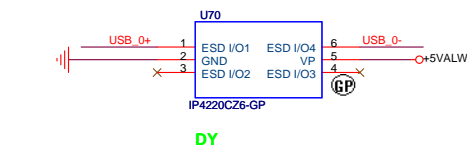
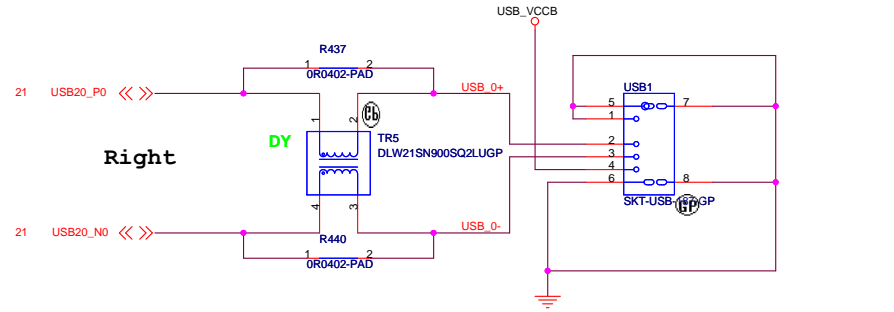
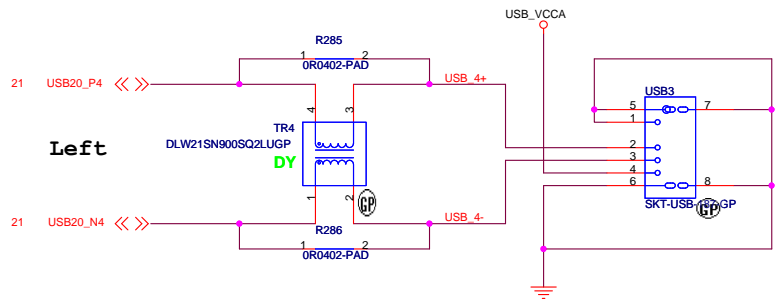
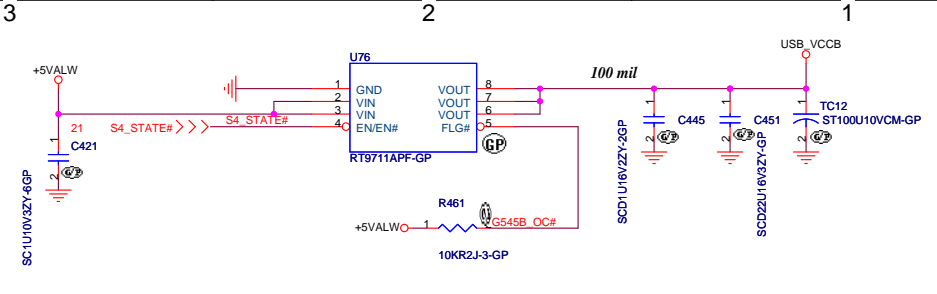
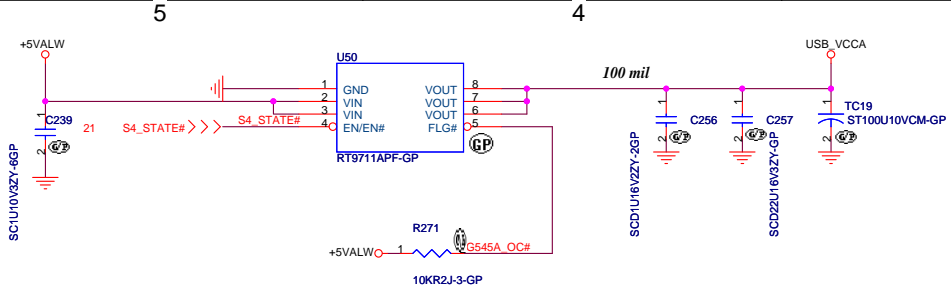


C406 and C411 please close to SIM connector

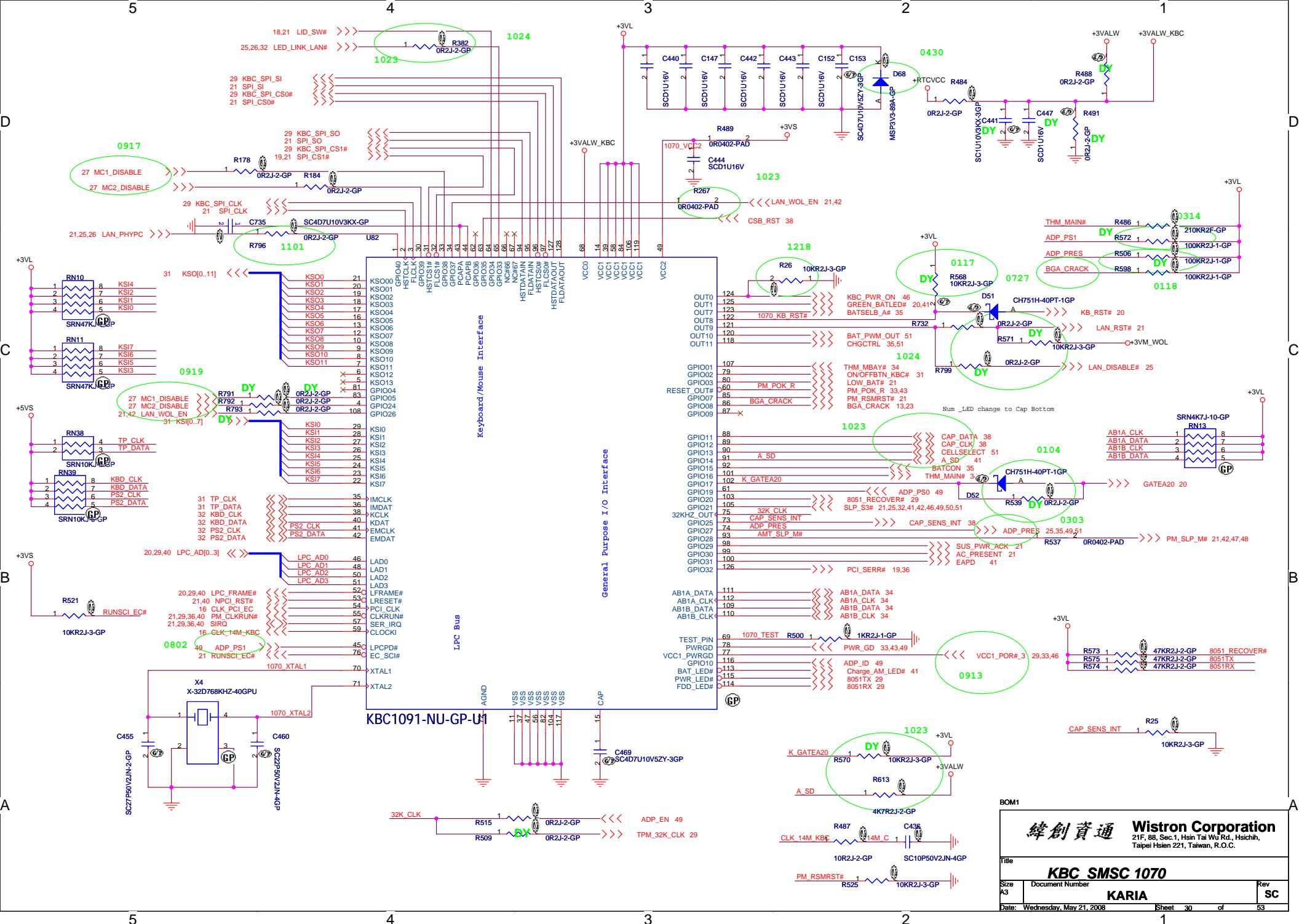
Must be placed in the center of the system

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Title Mini-Card/Accelerometer			
Size A3		Document Number KARIA	
Date: Wednesday, May 21, 2008		Rev SC	
Sheet 27		of 53	



緯創資通 Wistron Corporation	
21F, 8B, Sec. 1, Hsin Tai Wu Rd., Hsichin, Taipei Hsein 221, Taiwan, R.O.C.	
Title: USB Connector	
Size: A3	Document Number: KARIA
Date: Friday, May 02, 2008	Sheet 28 of 53
Rev: SC	



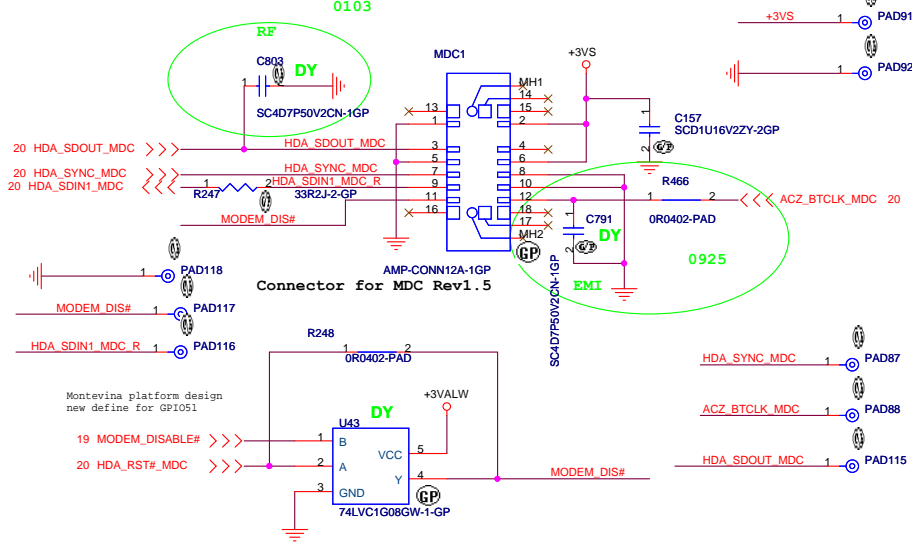
BOM1

緯創資通 Wistron Corporation
 21F, 88, Sec 1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.

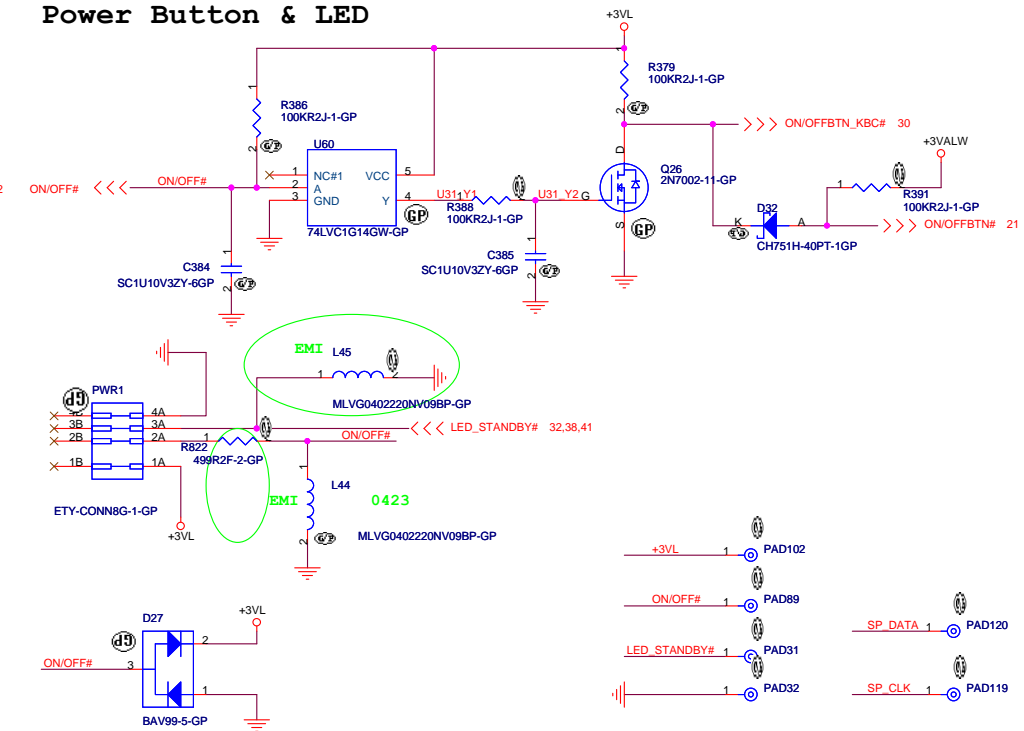
Title			
KBC SMSC 1070			
Size	Document Number	Rev	
A3	KARIA	SC	
Date:	Wednesday, May 21, 2008	Sheet	30 of 53

MDC 1.5 Conn.

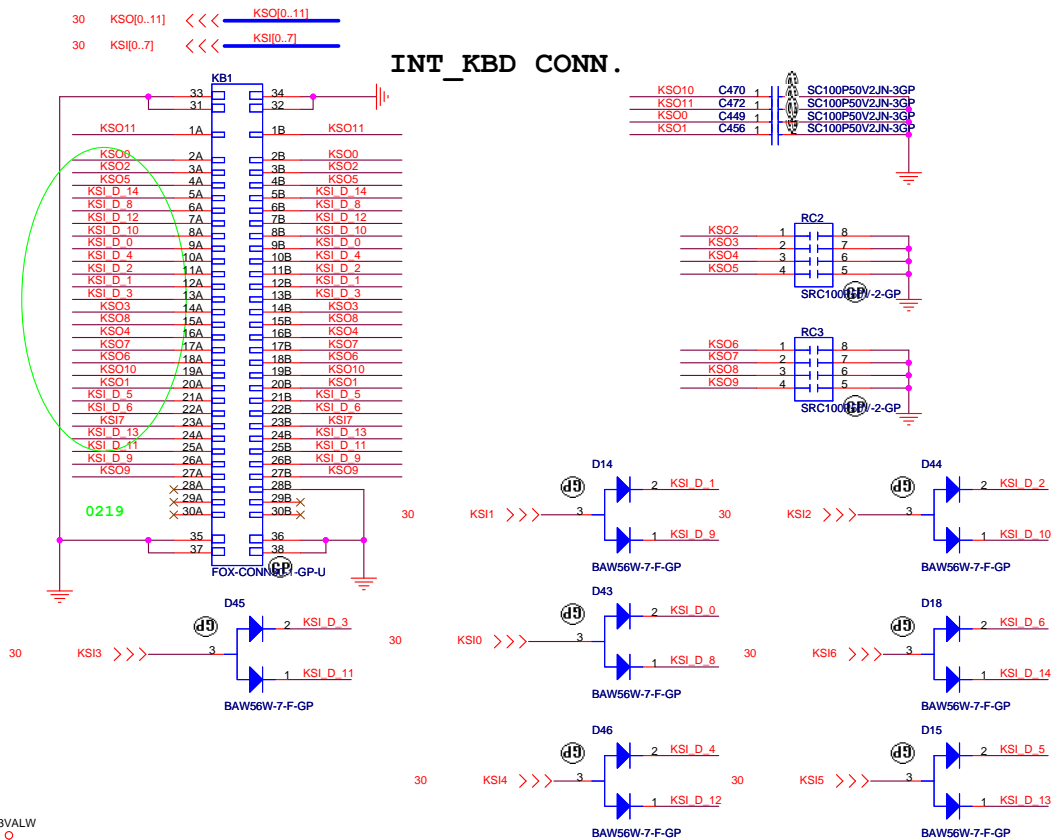
0103



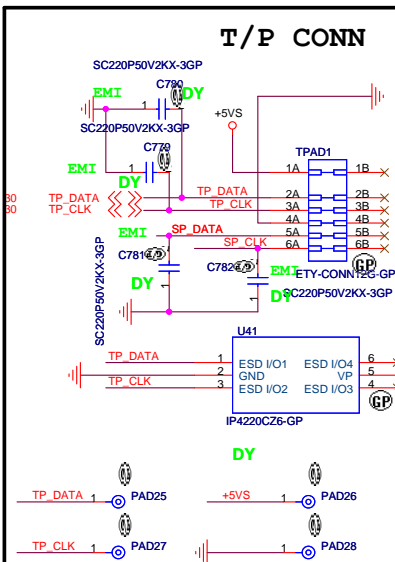
Power Button & LED



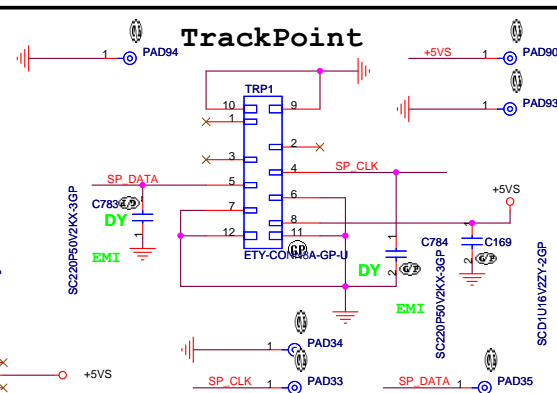
INT_KBD CONN.



T/P CONN



TrackPoint



緯創資通 Wistron Corporation
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 Taipei Hsien 221, Taiwan, R.O.C.

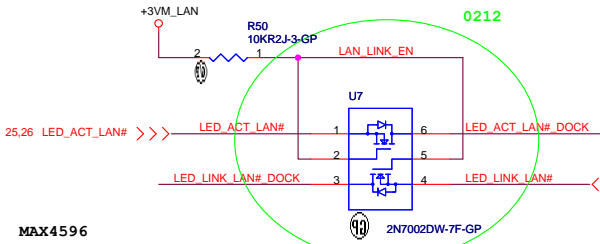
Title: **MDC/KBD/ON OFF/T.P.**

Size A3 Document Number: **KARIA** Rev: **SC**

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Docking CONN. 164 PIN

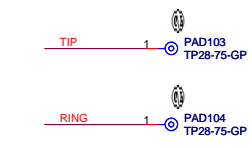
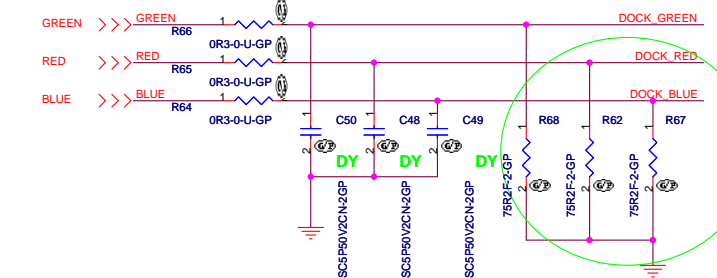
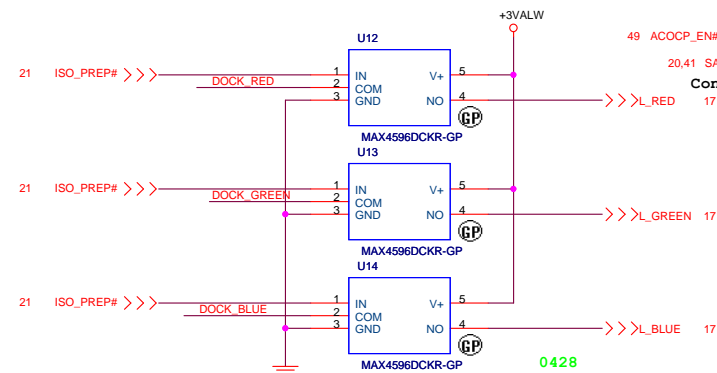
current rating 6A



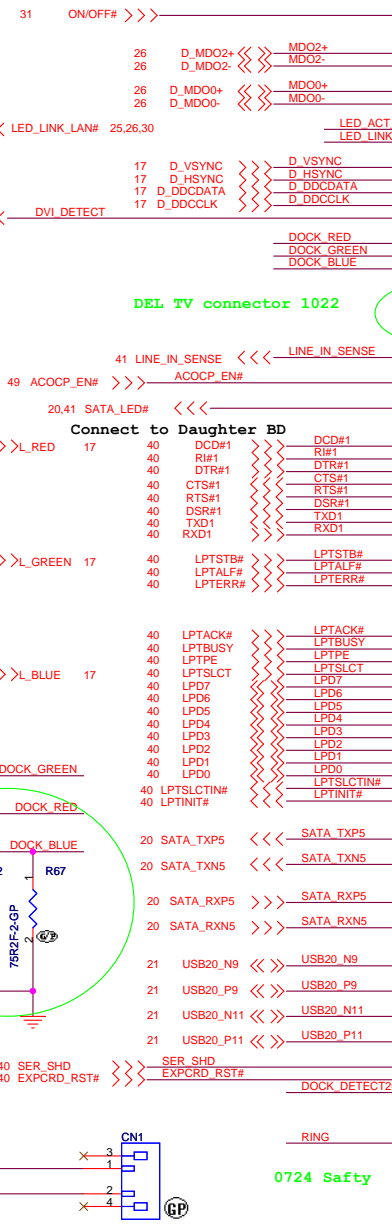
MAX4596

IN	NO TO COM	COM TO NO
L	OFF	
H	ON	

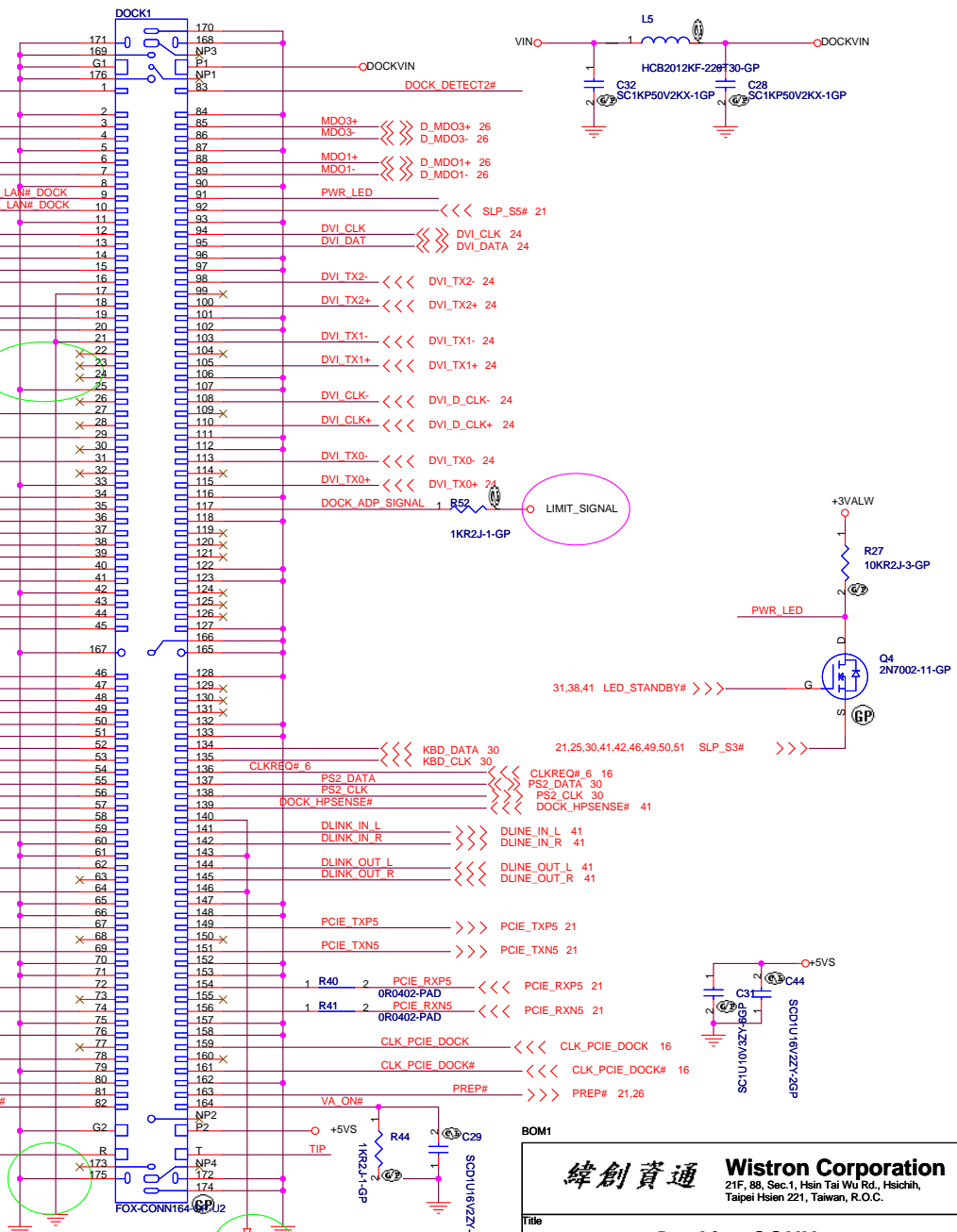
Close to DOCKING CONN.



Layout Notes :
Place MODEM1 & BEAD near Docking connector



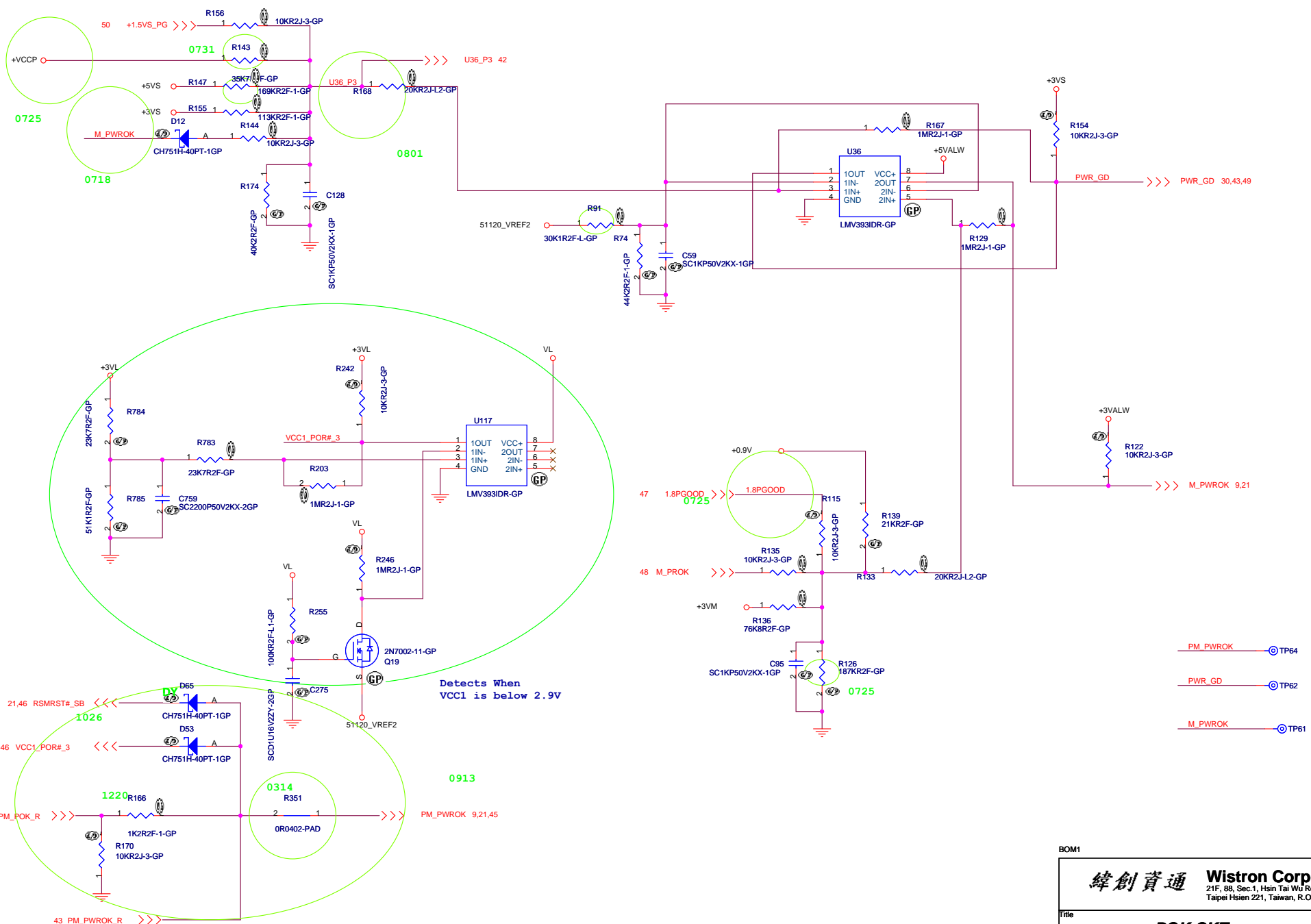
0724 Safty
For TIP and Ring cut all layers



BOM1

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

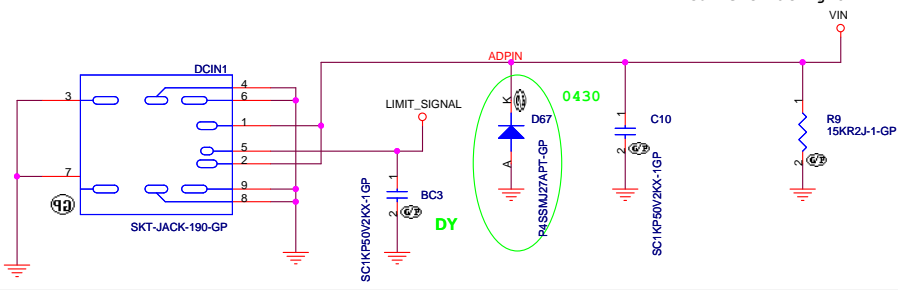
Title		Docking CONN	
Size A3	Document Number	Karia	Rev SC
Date: Thursday, May 15, 2008	Sheet 32	of 53	



BOM1		
緯創資通 Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
POK CKT		
Size	Document Number	Rev
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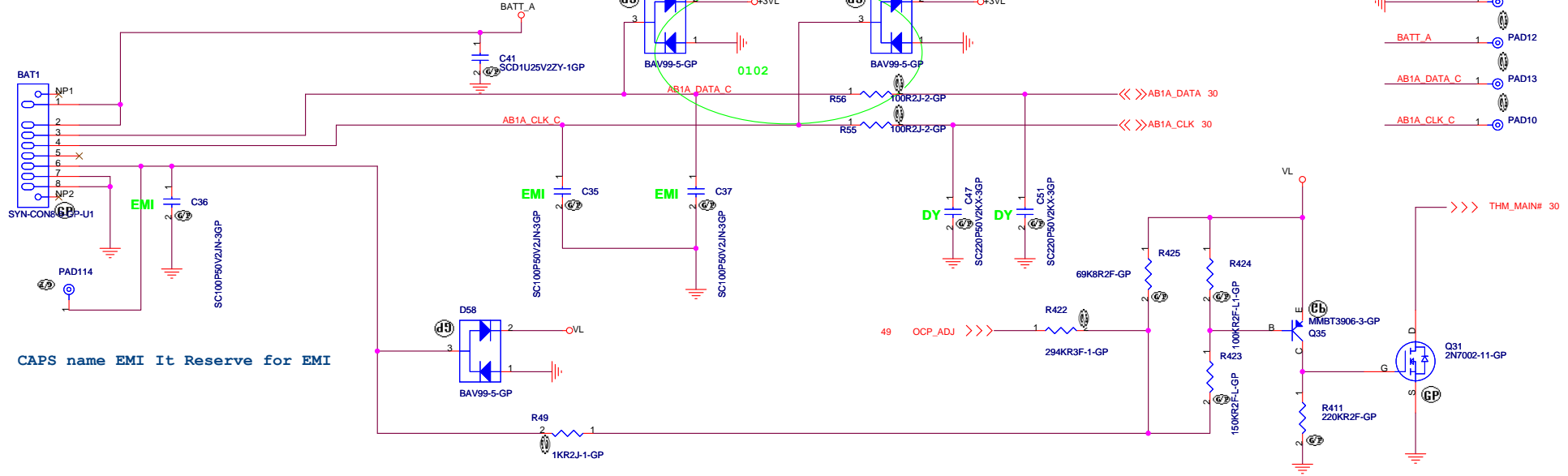
Adaptor in to generate DCBATOUT

Current Rating 6 A



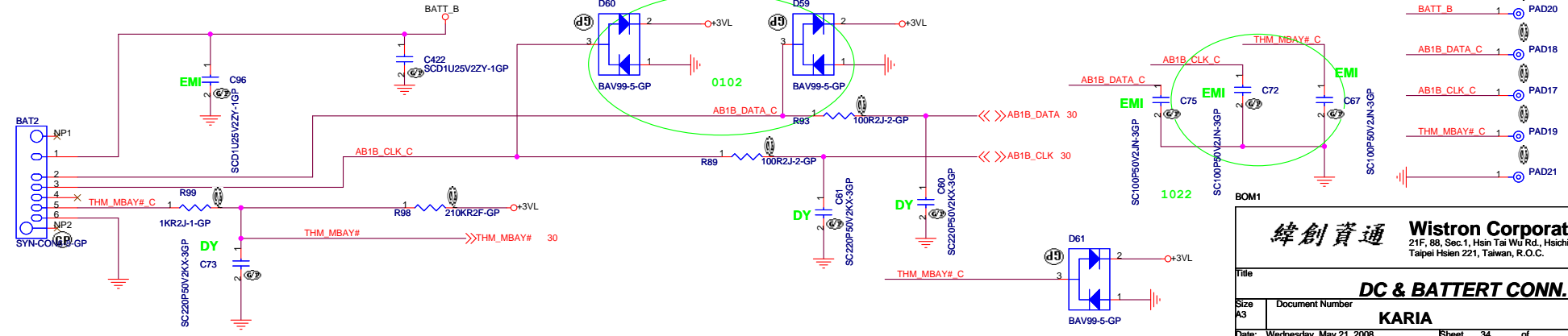
MAIN BATTERY CONNECTOR

Current Rating 6 A



BAY BATTERY CONNECTOR

Current Rating 6 A



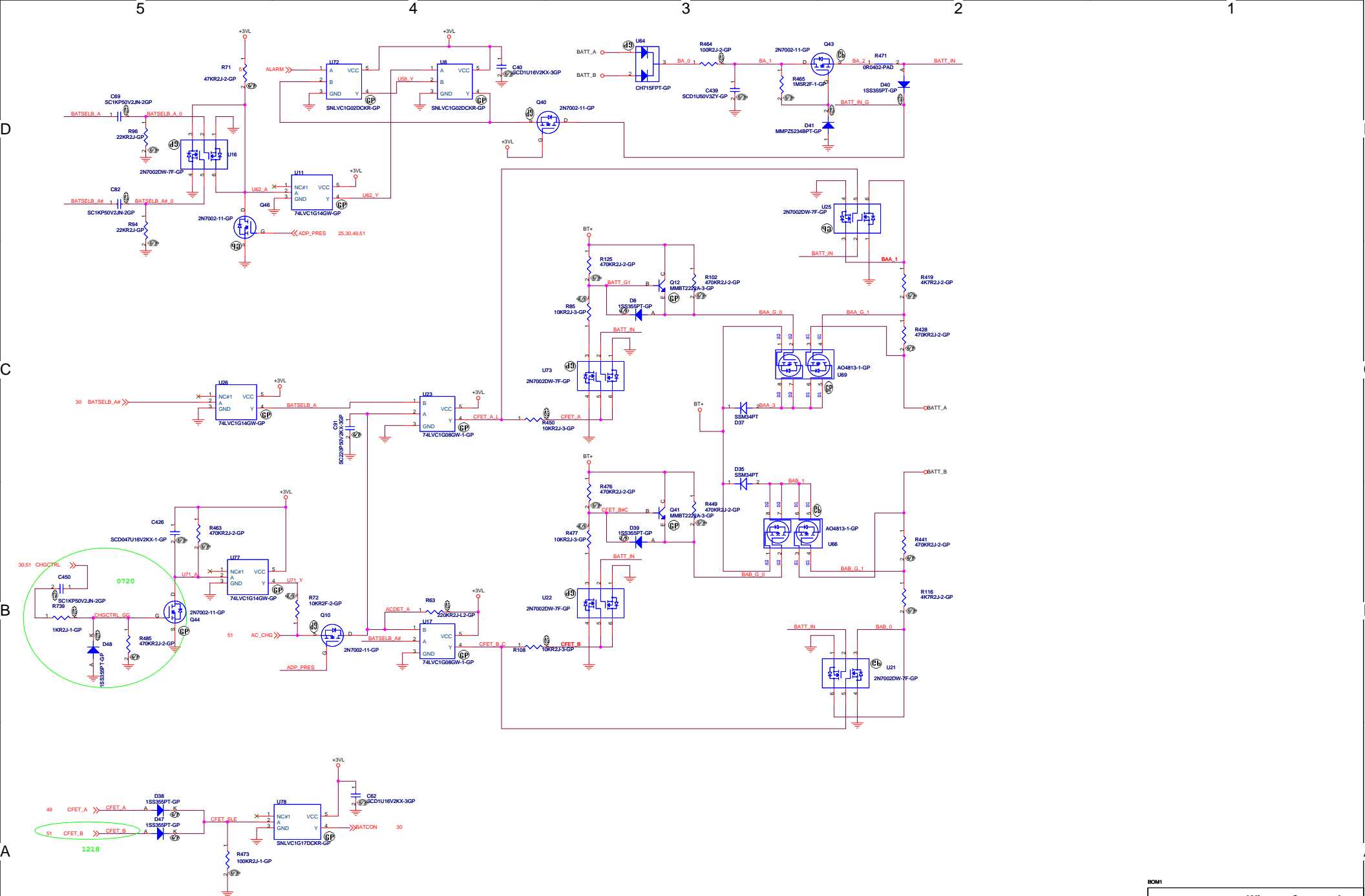
緯創資通 Wistron Corporation
 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.

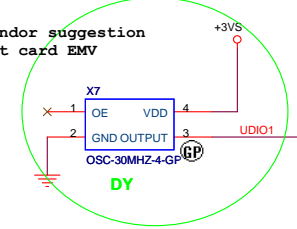
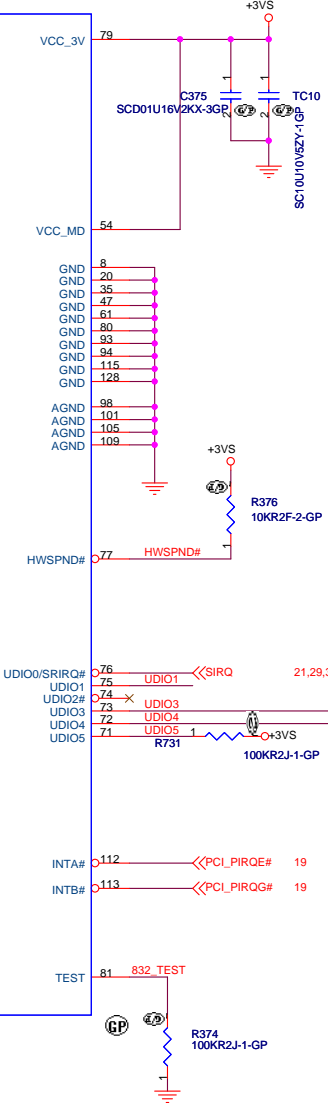
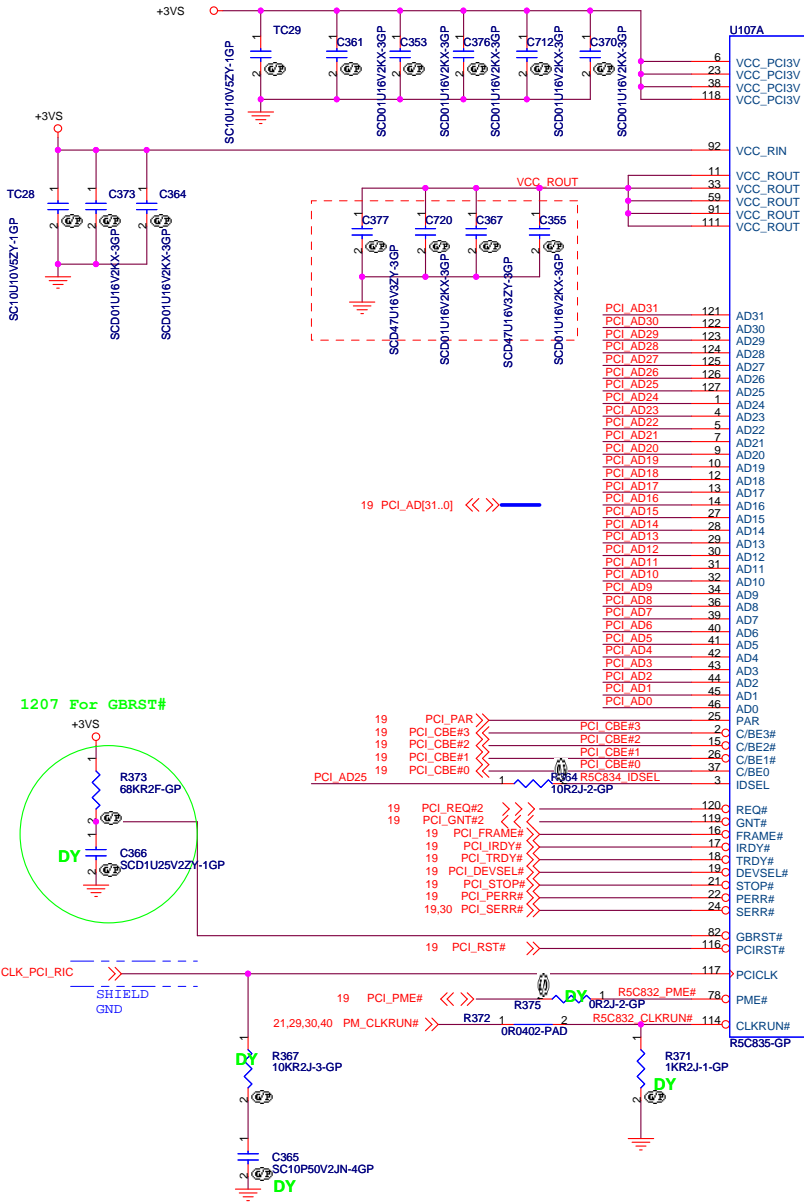
DC & BATTERY CONN.

KARIA

Rev SC

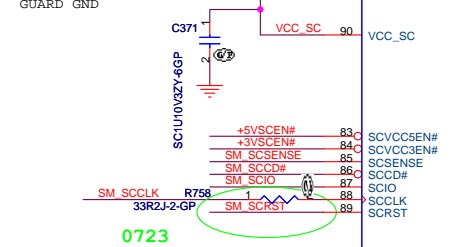
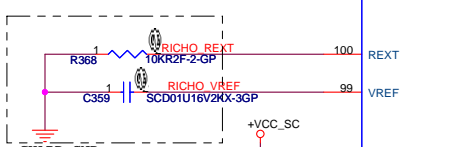
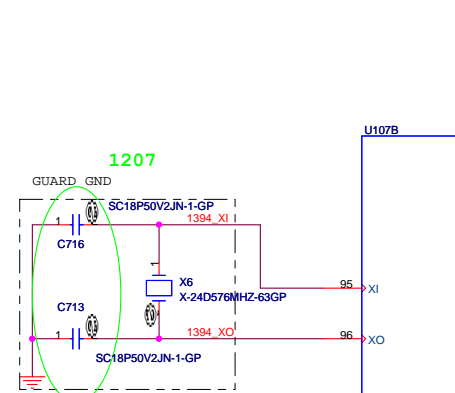
Date: Wednesday, May 21, 2008 Sheet 34 of 53



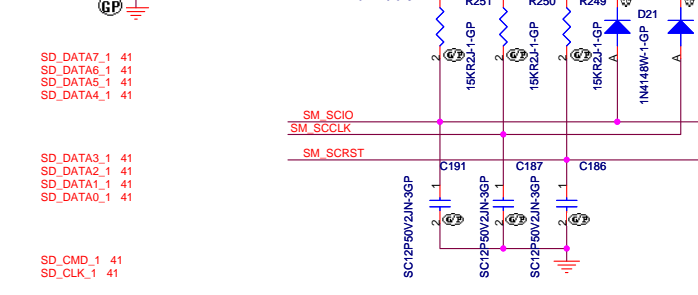
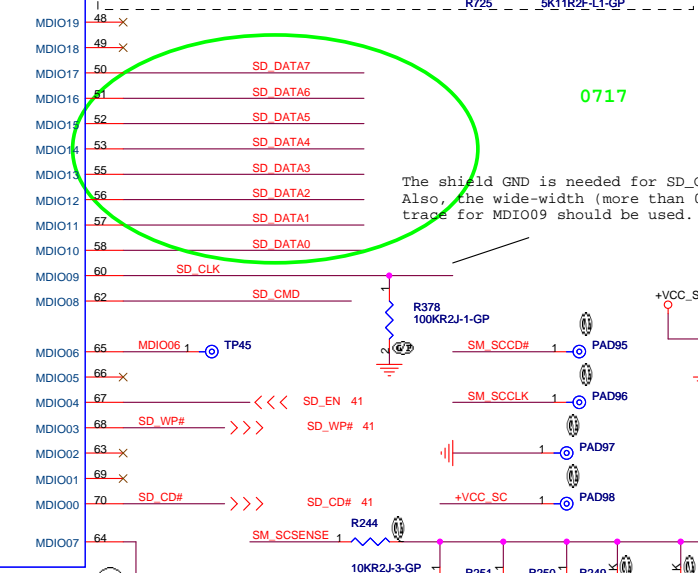
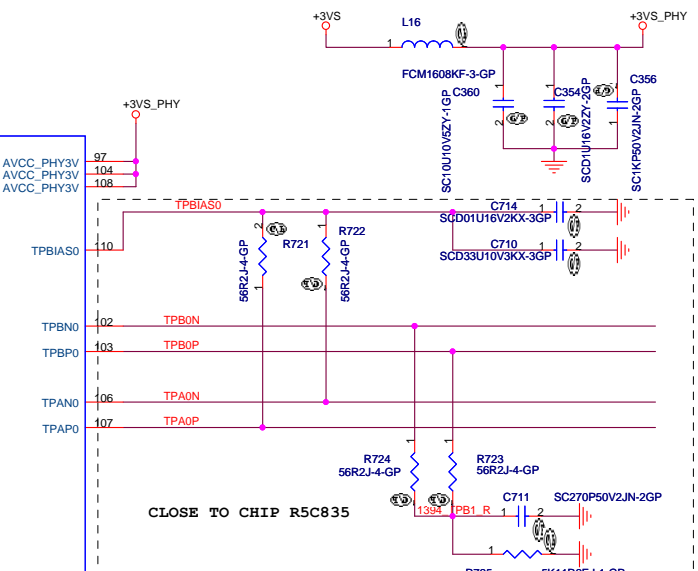
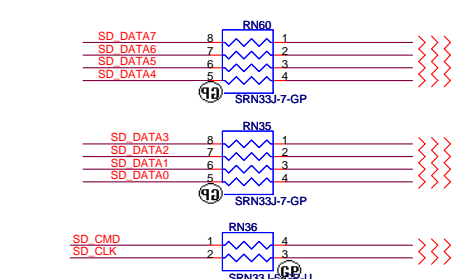


BOM1

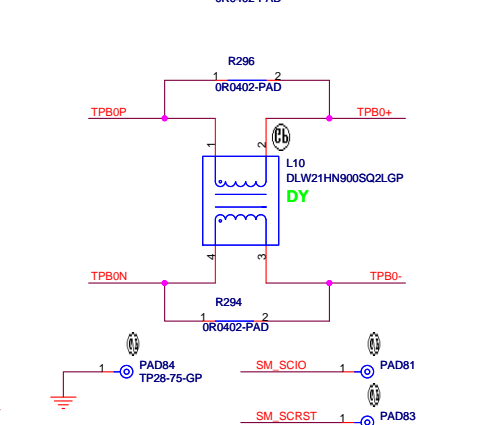
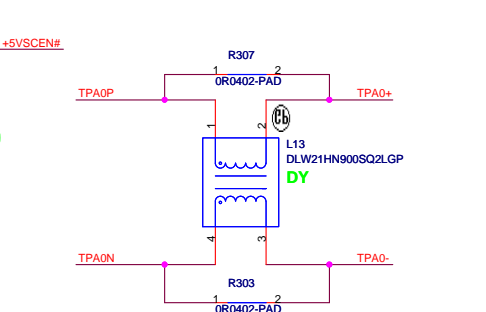
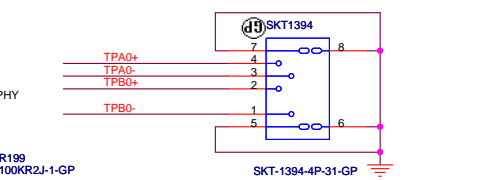
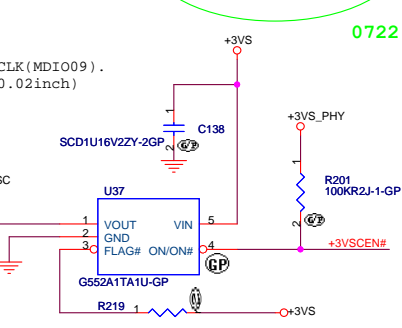
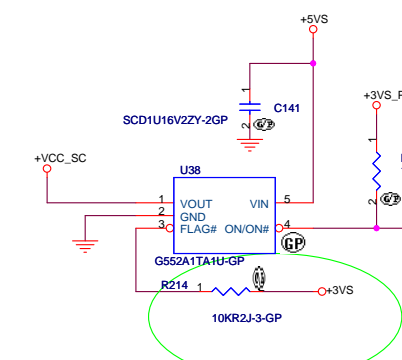
緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
R5C835/PCI			
Size	Document Number	Rev	
A3		SC	
Date:	Friday, May 02, 2008	Sheet	36 of 53



Layout notes :
external parts for
VREF, REXT and FIL0 as
close as possible to R5C833.



Layout notes :
1394
=====GND
-----TPB0-
-----TPB0+
=====GND
-----TPA0-
-----TPA0+
=====GND



BOM1

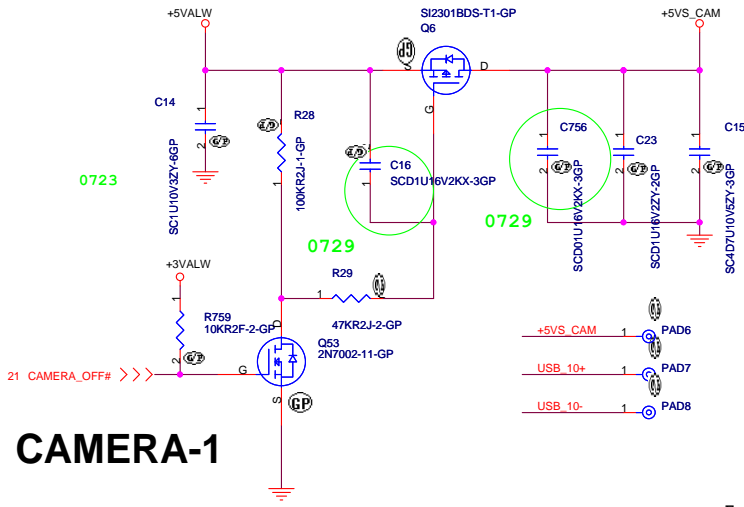
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **R5C835/1394/SD/Smart**

Size A3 Document Number **KARIA** Rev **SA**

Date: Friday, May 02, 2008 Sheet 37 of 53

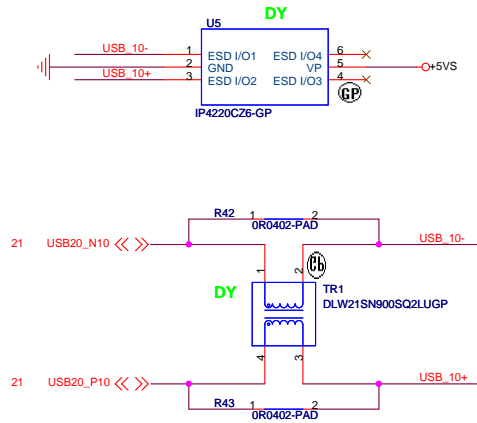
CAMERA-1



0723

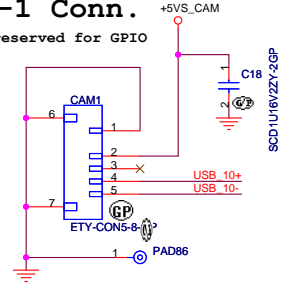
0729

0729

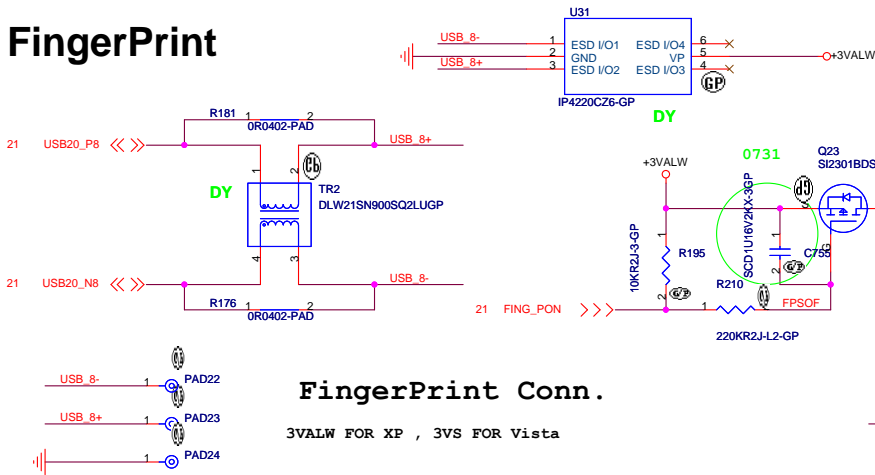


CAMERA-1 Conn.

PIN 3 reserved for GPIO



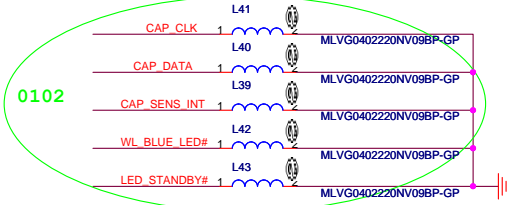
FingerPrint



FingerPrint Conn.

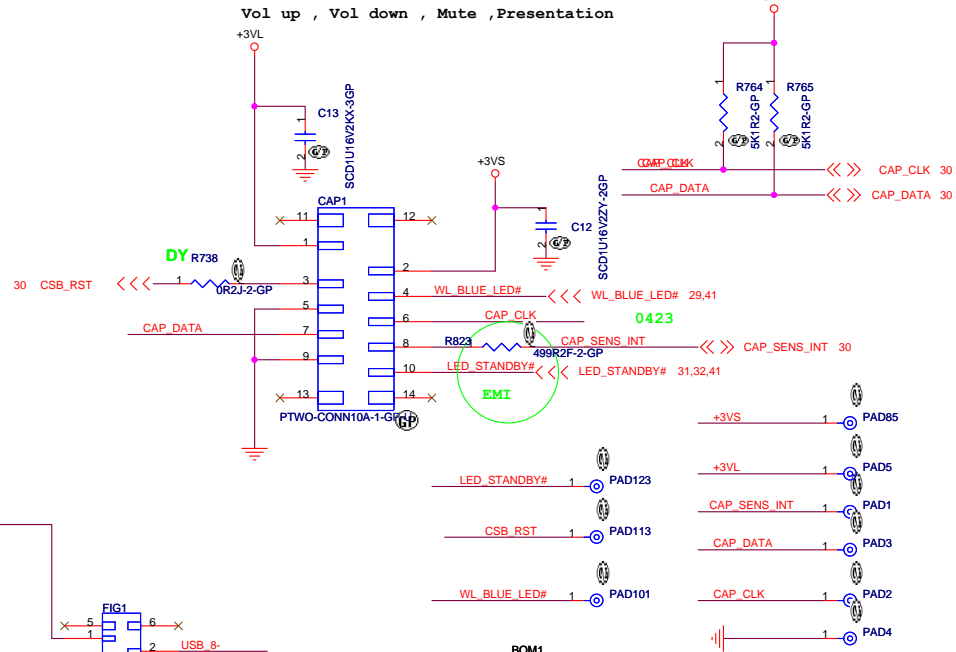
3VALW FOR XP , 3VS FOR Vista

For EMI



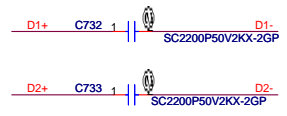
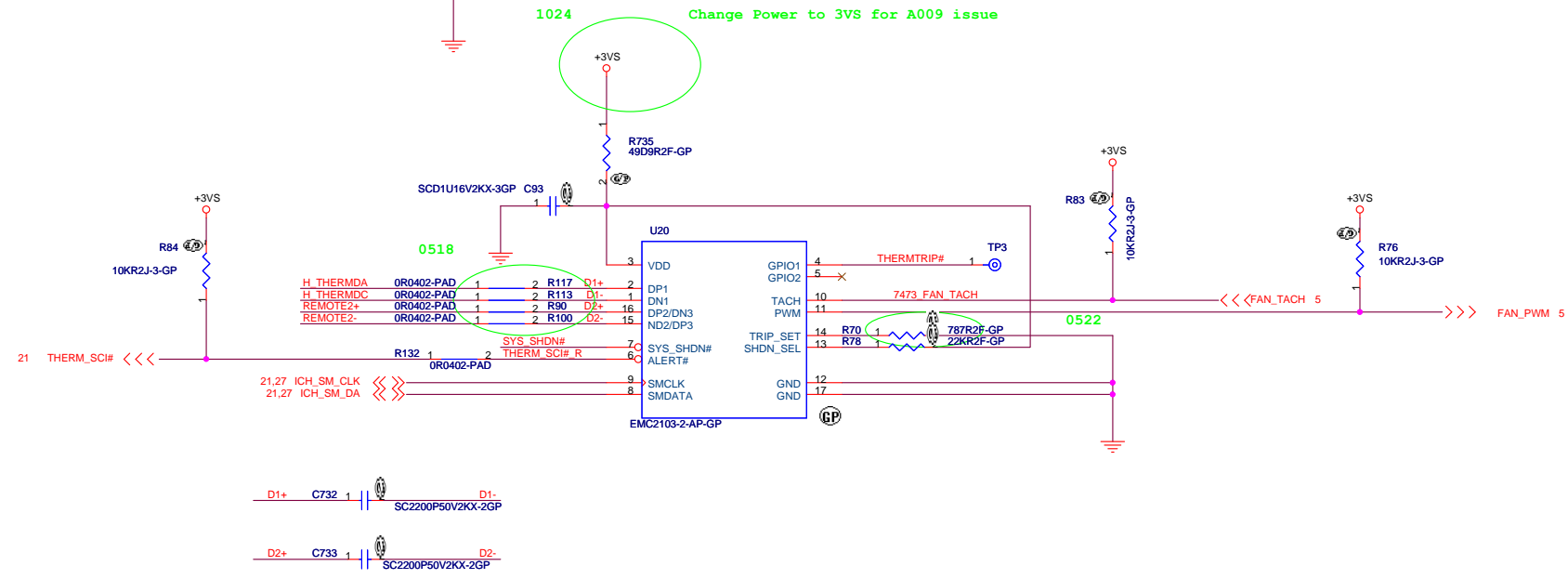
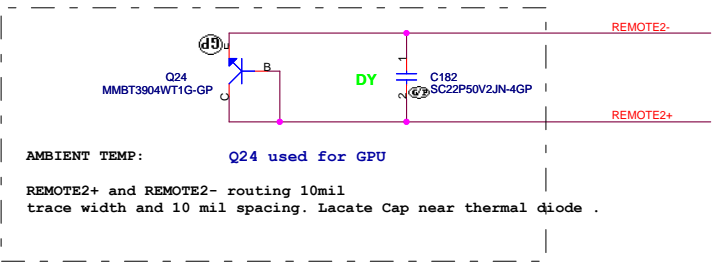
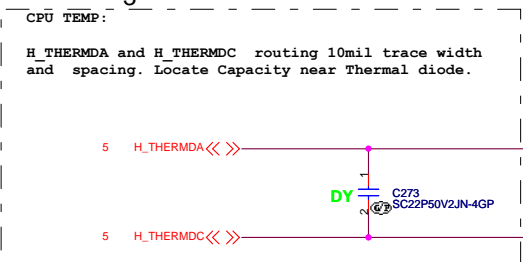
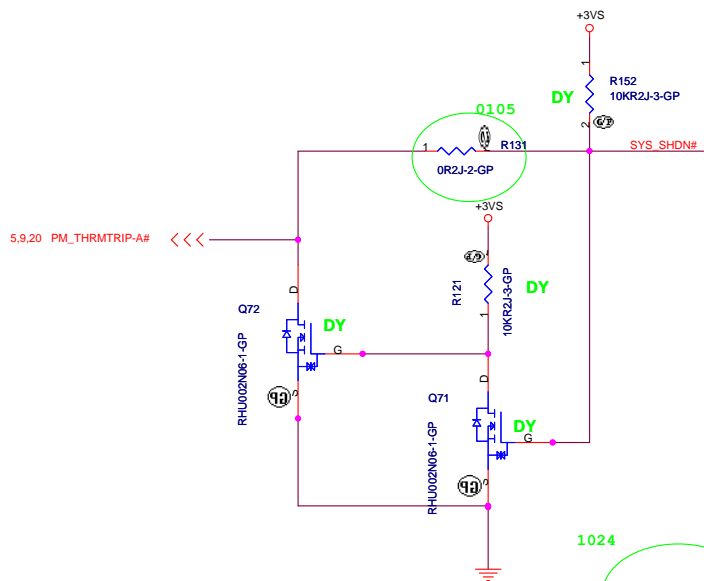
0102

SYSTEM CAPACITY BOARD.



BOM1

緯創資通 Wistron Corporation 21F, 88, Sec 1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
Camera/W-COM	
Size A3	Document Number
KARIA	
Date: Friday, May 02, 2008	Rev SC
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BOM1

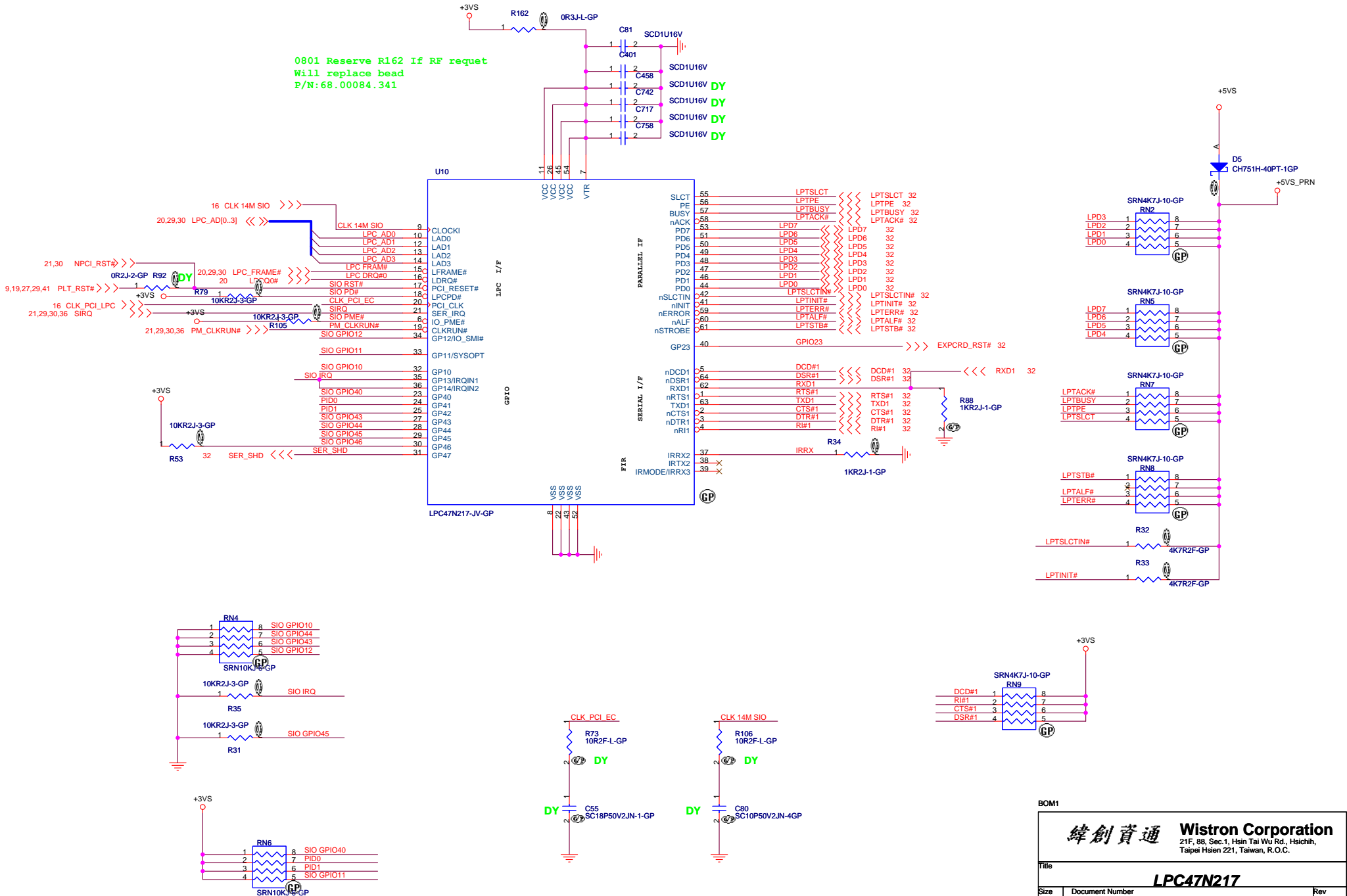
緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin, Taipei Hsin 221, Taiwan, R.O.C.

Title: **SMSC2103 Thermal Sensor**

Size A3	Document Number	Rev SC
KARIA		

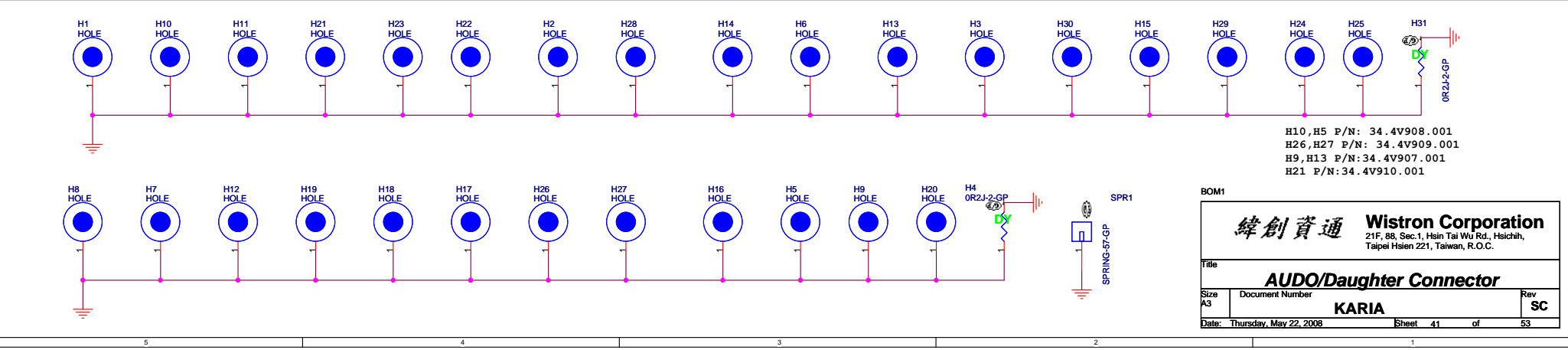
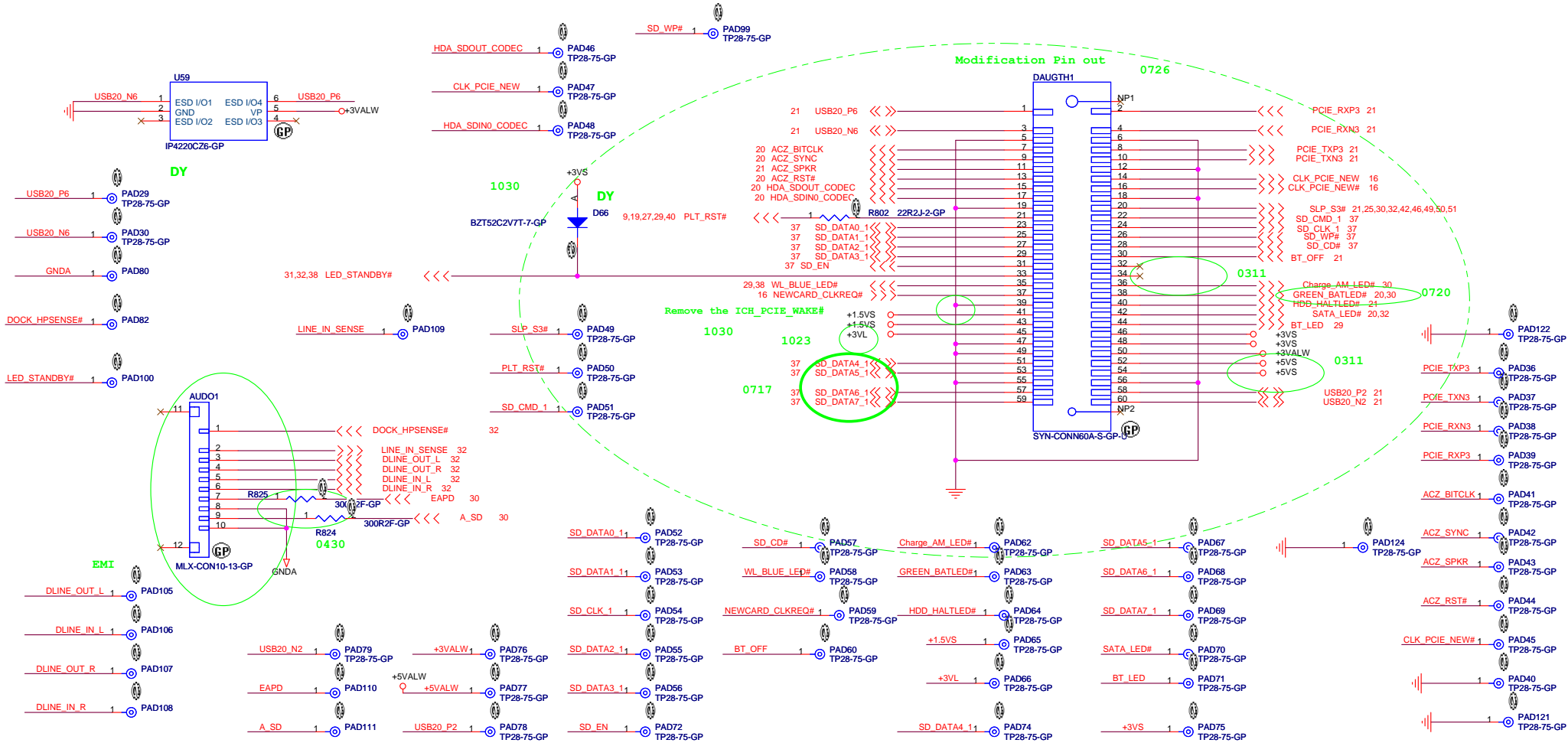
Date: Thursday, May 22, 2008 Sheet 39 of 53

0801 Reserve R162 If RF request
 Will replace bead
 P/N:68.00084.341



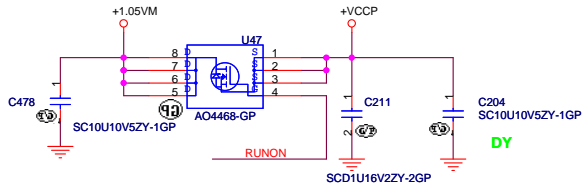
BOM1

Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title LPC47N217	
Size A3	Document Number KARIA
Date: Friday, May 02, 2008	Sheet 40 of 53
Rev PV	

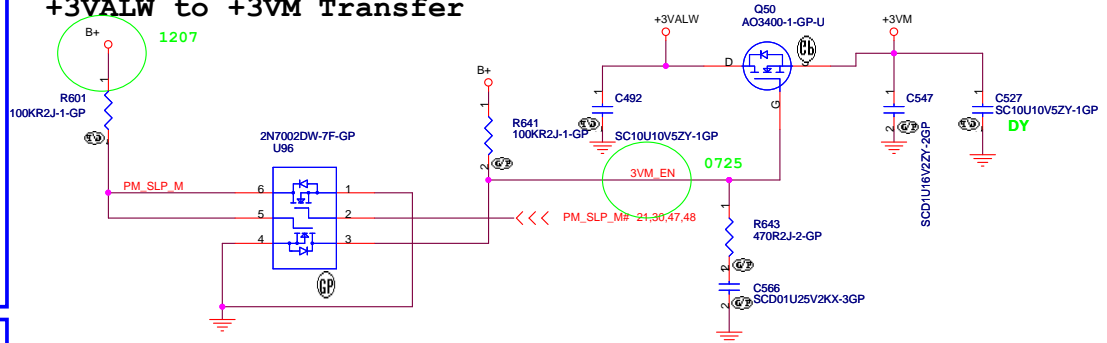


Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title AUDO/Daughter Connector	
Size A3	Document Number KARIA
Date: Thursday, May 22, 2008	Sheet 41 of 53
Rev SC	

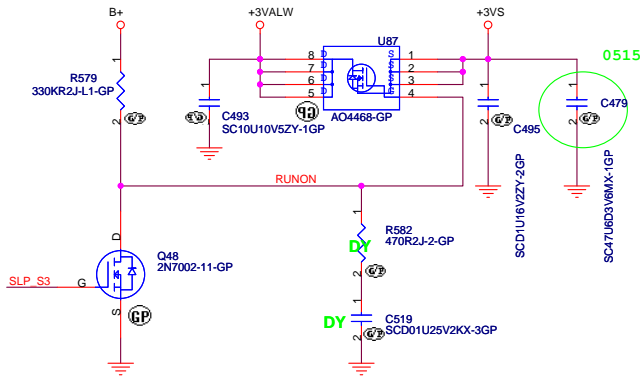
+1.05VM to +VCCP Transfer



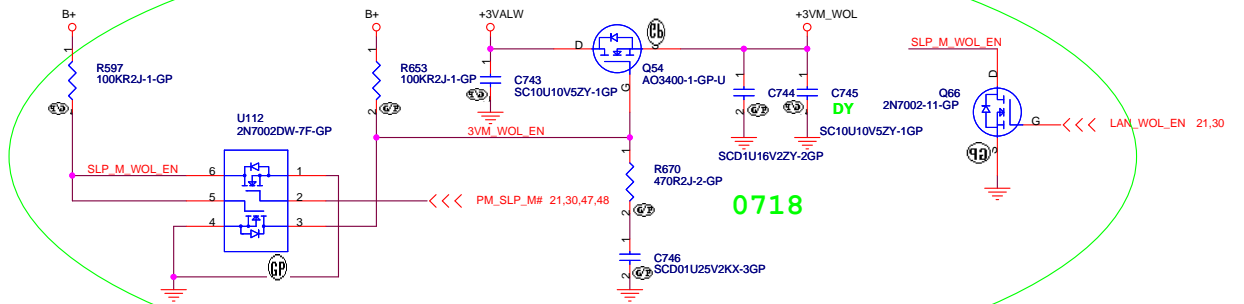
+3VALW to +3VM Transfer



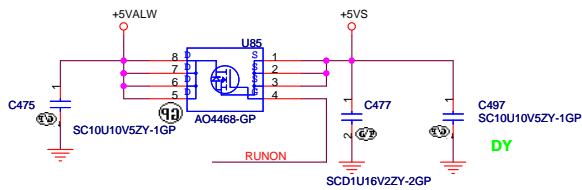
+3VALW to +3VS Transfer



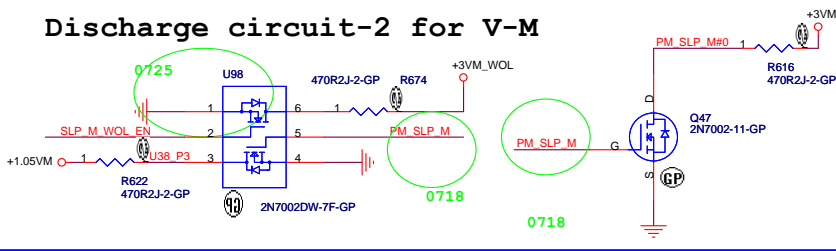
+3VALW to +3VM_WOL



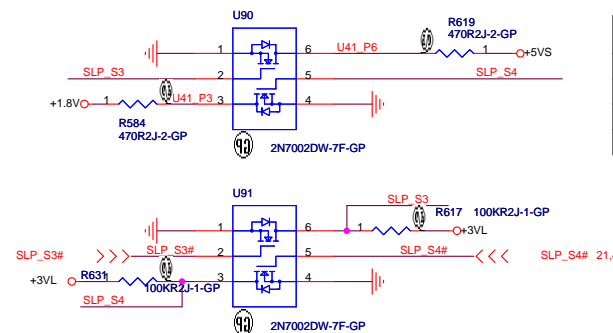
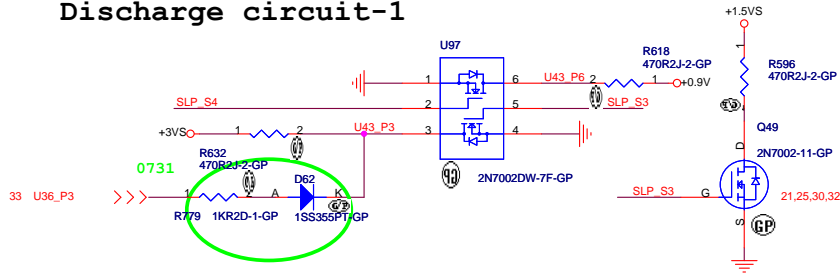
+5VALW to +5VS Transfer



Discharge circuit-2 for V-M



Discharge circuit-1

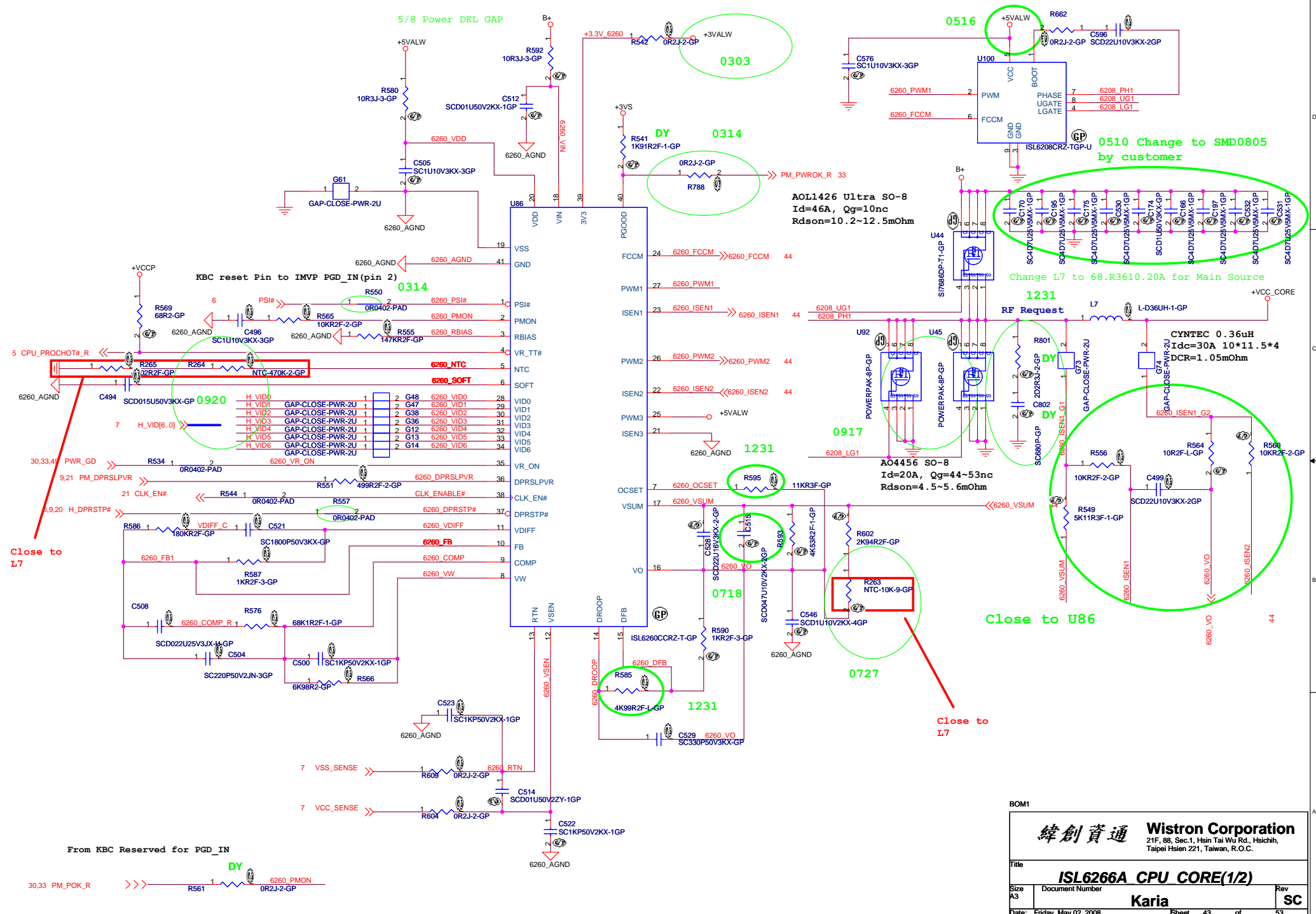


PM_SLP_M#	LAN_WOL_EN	+3VM_WOL	+3VM	SYSTEM STATE
0	0	0V	0V	Moff / No WOL
0	1	3.3V	0V	Legacy WOL/ Moiff
1	0	3.3V	3.3V	M1
1	1	3.3V	3.3V	M1

BOM1

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		DC/DC Circuit	
Size	Document Number	Rev	
A3		SC	
Date:	Thursday, May 15, 2008	Sheet	42 of 53



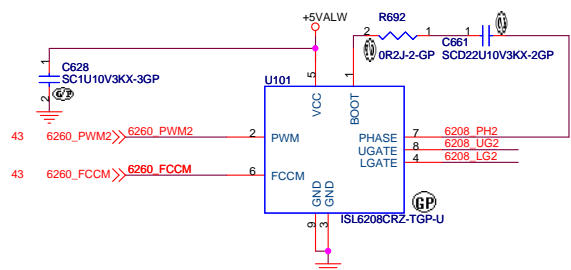
BOM1

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **ISL6266A CPU CORE(1/2)**

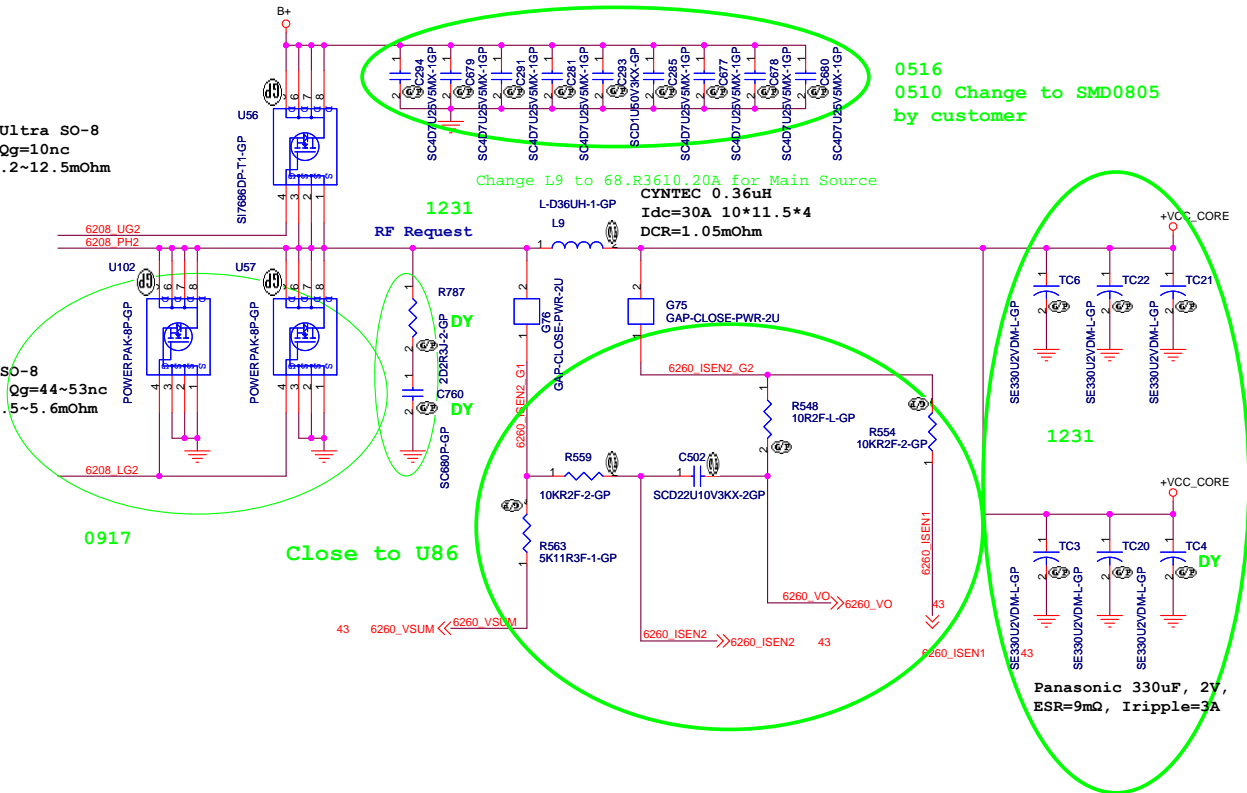
Size A3 Document Number **Karia** Rev **SC**

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AOL1426 Ultra SO-8
 Id=46A, Qg=10nc
 Rdson=10.2~12.5mOhm

AO4456 SO-8
 Id=20A, Qg=44~53nc
 Rdson=4.5~5.6mOhm



5/8 Power DEL GAP

0516
 0510 Change to SMD0805
 by customer

Change L9 to 68.R3610.20A for Main Source

CYNTEC 0.36uH
 Idc=30A 10*11.5*4
 DCR=1.05mOhm

1231
 RF Request

0917

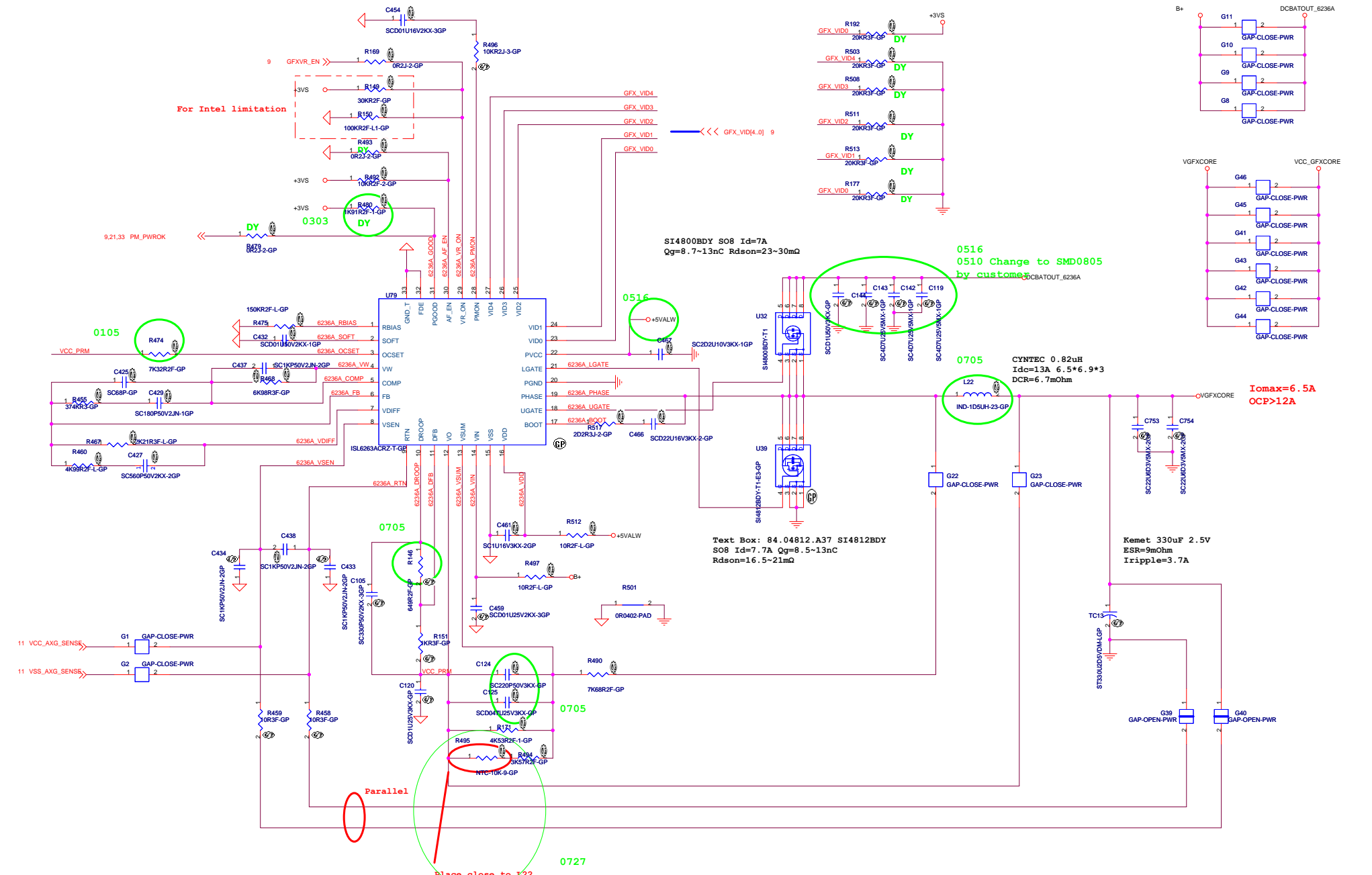
Close to U86

1231

Panasonic 330uF, 2V,
 ESR=9mQ, Iripple=3A

BOM1

緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
ISL6266A CPU CORE(2/2)			
Title	Document Number	Rev	SC
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SI4800BDY SO8 Id=7A
Qg=8.7-13nC Rds(on)=23-30mΩ

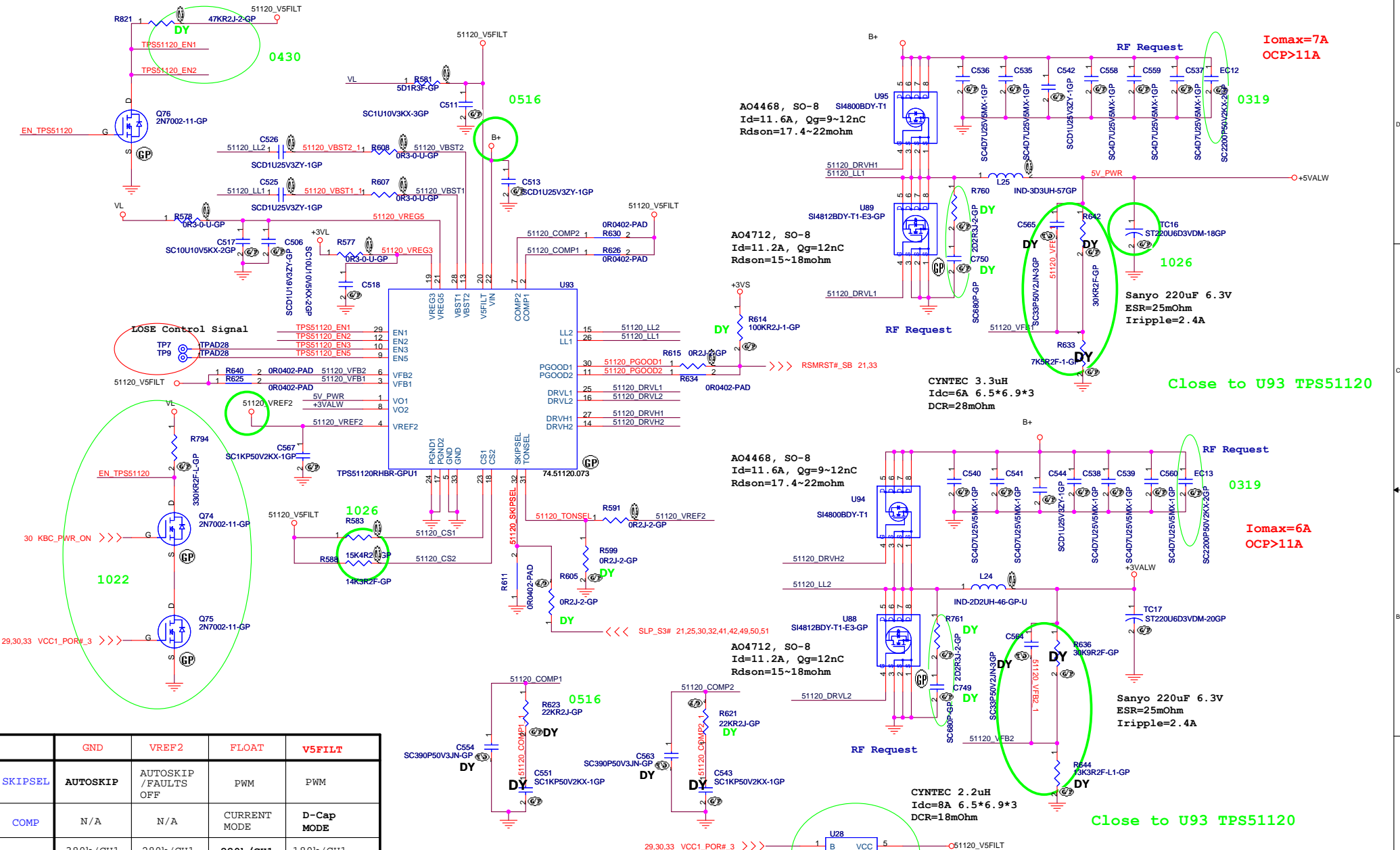
Text Box: 84.04812.A37 SI4812BDY
SO8 Id=7.7A Qg=8.5-13nC
Rds(on)=16.5-21mΩ

CYNTEC 0.82uH
Idc=13A 6.5*6.9*3
DCR=6.7mOhm

Kemet 330uF 2.5V
ESR=9mOhm
Iripple=3.7A

I_{omax}=6.5A
OCP>12A

BOM1		緯創資通 Wistron Corporation 217, 88, Sec. 1, Hsin Tai Wu Rd., Hsinchu, Taipei Hsien 221, Taiwan, R.O.C.	
File: ISL6263A GFX CORE			
Size	Document Number	Karia	Rev
C			SC
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For TPS51120,
Vout=5V

- If you use a 6.8uH inductor, the minimum ESR is 70m ohm.
- If you use a 4.7uH inductor, the minimum ESR is 48m ohm.
- If you use a 3.3uH inductor, the minimum ESR is 34m ohm.

Vout=3.3V

- If you use a 4.7uH inductor, the minimum ESR is 51m ohm.
- If you use a 3.3uH inductor, the minimum ESR is 36m ohm.
- If you use a 2.5uH inductor, the minimum ESR is 27m ohm.

File		TPA51120 +5VALW +3VALW	
Size	A3	Document Number	Karia
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Rev SC

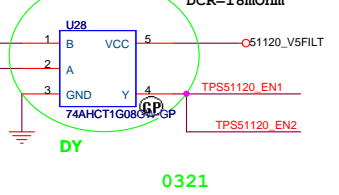
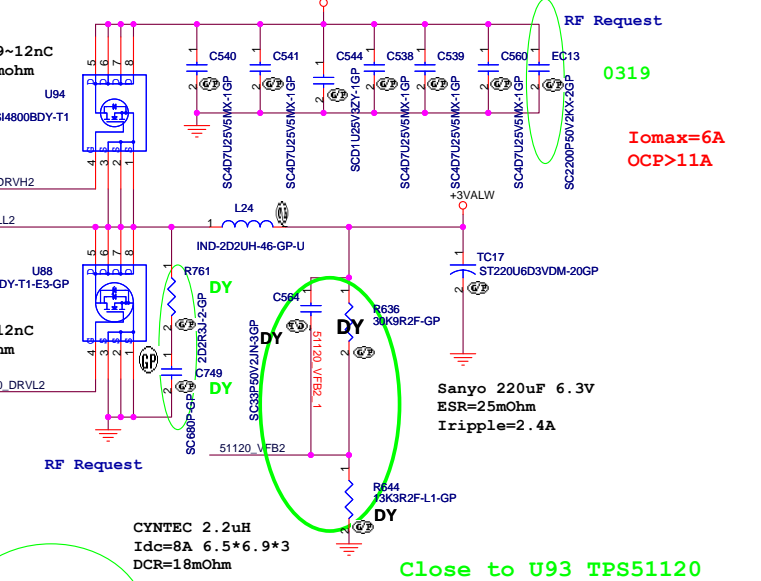
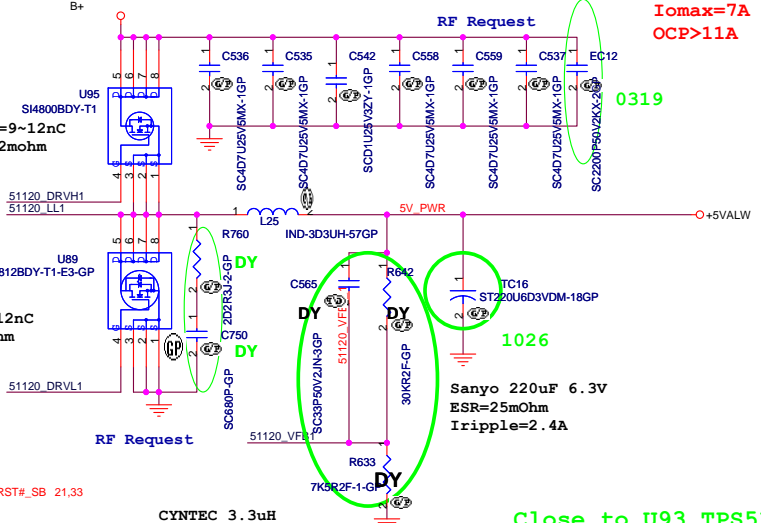
	GND	VREF2	FLOAT	V5FILT
SKIPSEL	AUTOSKIP	AUTOSKIP / FAULTS OFF	PWM	PWM
COMP	N/A	N/A	CURRENT MODE	D-Cap MODE
TONSEL	380k/CH1 580k/CH2	280k/CH1 430k/CH2	220k/CH1 330k/CH2	180k/CH1 280k/CH2
VFB1	Adjustable output (connect to the resistor divider)			5V Fixed Output
VFB2				3.3V Fixed Output
EN1, EN2	Switcher OFF		Switchchr ON	Switcher ON
EN3, EN5	LDO OFF	not use	LDO ON	VREG3 on (EN3 only)

**Iomax=7A
OCP>11A**

Close to U93 TPS51120

**Iomax=6A
OCP>11A**

Close to U93 TPS51120



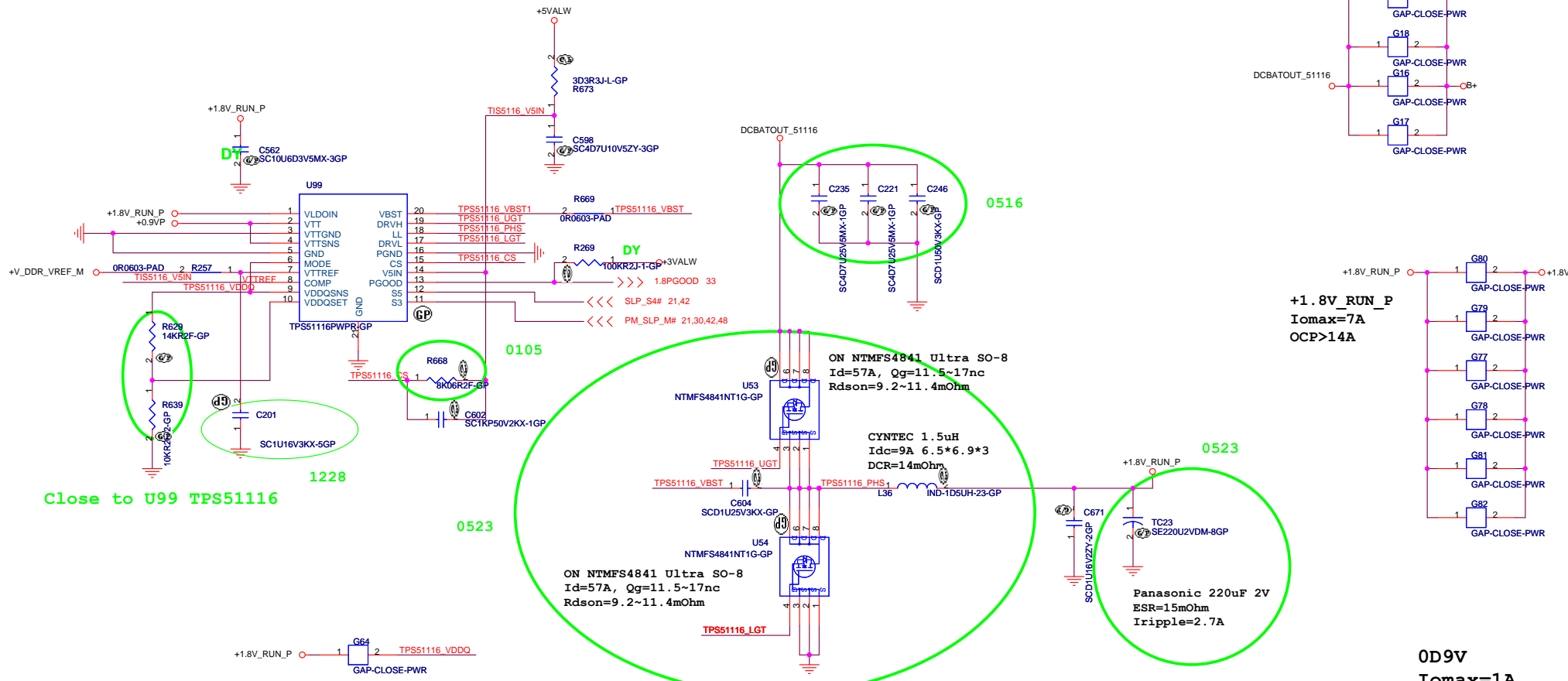
AO4468, SO-8
Id=11.6A, Qg=9~12nC
Rdson=17.4~22mohm

AO4712, SO-8
Id=11.2A, Qg=9~12nC
Rdson=15~18mohm

AO4468, SO-8
Id=11.6A, Qg=9~12nC
Rdson=17.4~22mohm

AO4712, SO-8
Id=11.2A, Qg=12nC
Rdson=15~18mohm

TI TPS51116 for 1D8V and 0D9V



0516

0105

0523

0523

+1.8V_RUN_P
I_{omax}=7A
OCP>14A

0D9V
I_{omax}=1A

State	S3	S5	VDDR	VTTREF	VTT
S0	Hi	Hi	On	On	On
S3	Lo	Hi	On	On	Off (Hi-Z)
S4/S5	Lo	Lo	Off	Off	Off

1228

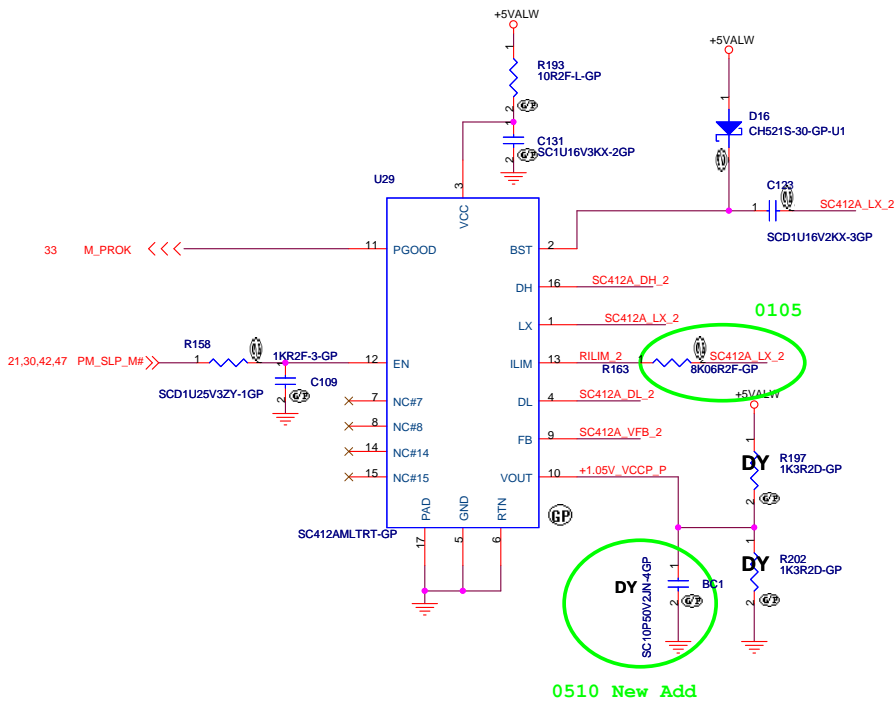
BOM1

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **TPS51116 1D8V/0D9V**

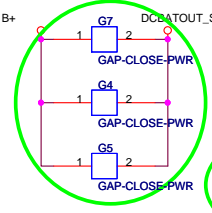
Size A3 Document Number **Karia** Rev **SC**

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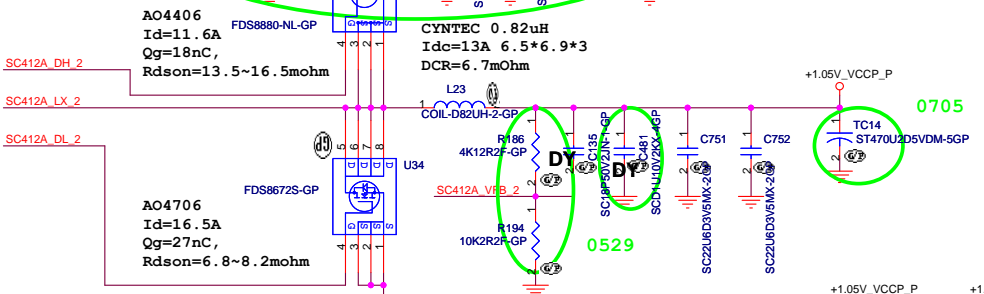


0510 New Add

0105

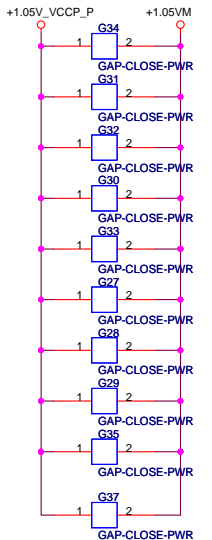


0510



Close to U29 SC412A

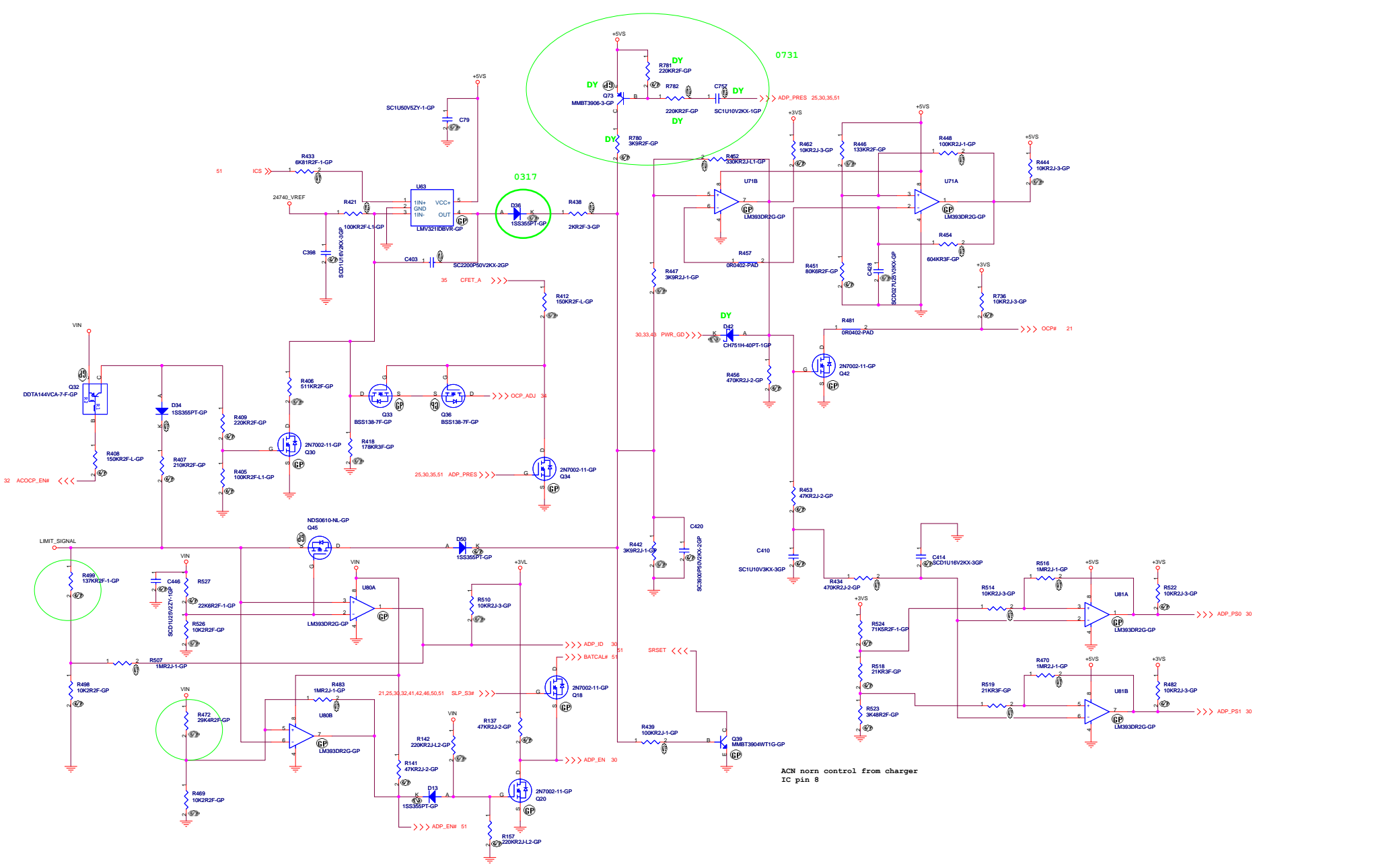
NEC 470uF 2.5V
ESR=9mOhm
Tripple=3.7A



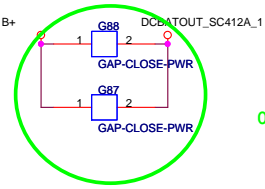
0705

BOM1

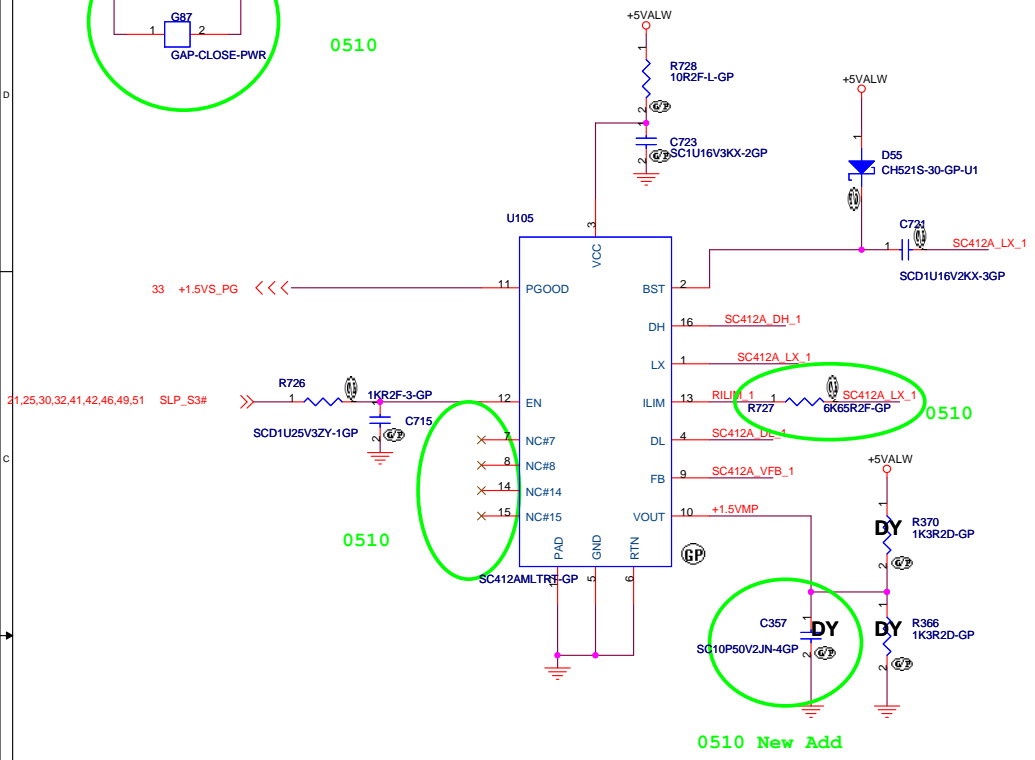
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
SC412A +1.05VM		
Size A3	Document Number	Rev SC
Karia		
Date: Friday, May 02, 2008	Sheet 48 of	53



BOM1		緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Ta Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
File		ADP OCP	
Size	Document Number	Rev	SC
A2	KARIA		
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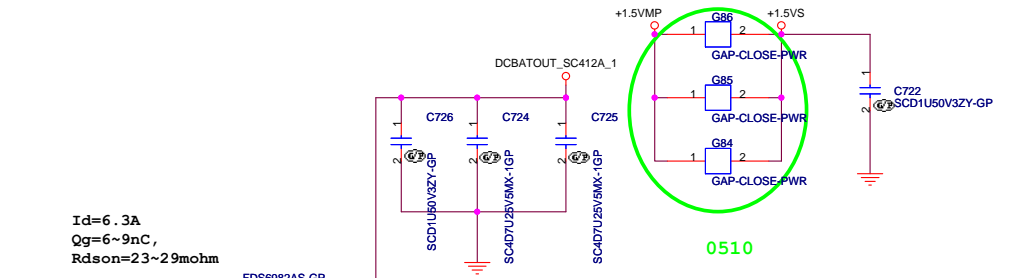


0510



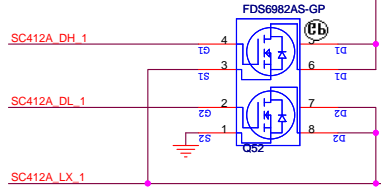
0510

0510 New Add



0510

$I_d = 6.3A$
 $Q_g = 6 \sim 9nC$
 $R_{dson} = 23 \sim 29m\Omega$

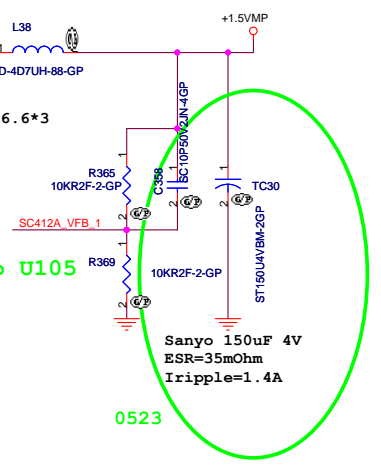


$I_d = 8.6A$
 $Q_g = 12 \sim 16nC$
 $R_{dson} = 13 \sim 16.5m\Omega$

CYNTEC 4.7uH
 $I_{dc} = 5.5A$ $7.3 * 6.6 * 3$
 $DCR = 37m\Omega$

1D5V_S0
 $I_{omax} = 3A$
 $OCP > 6A$

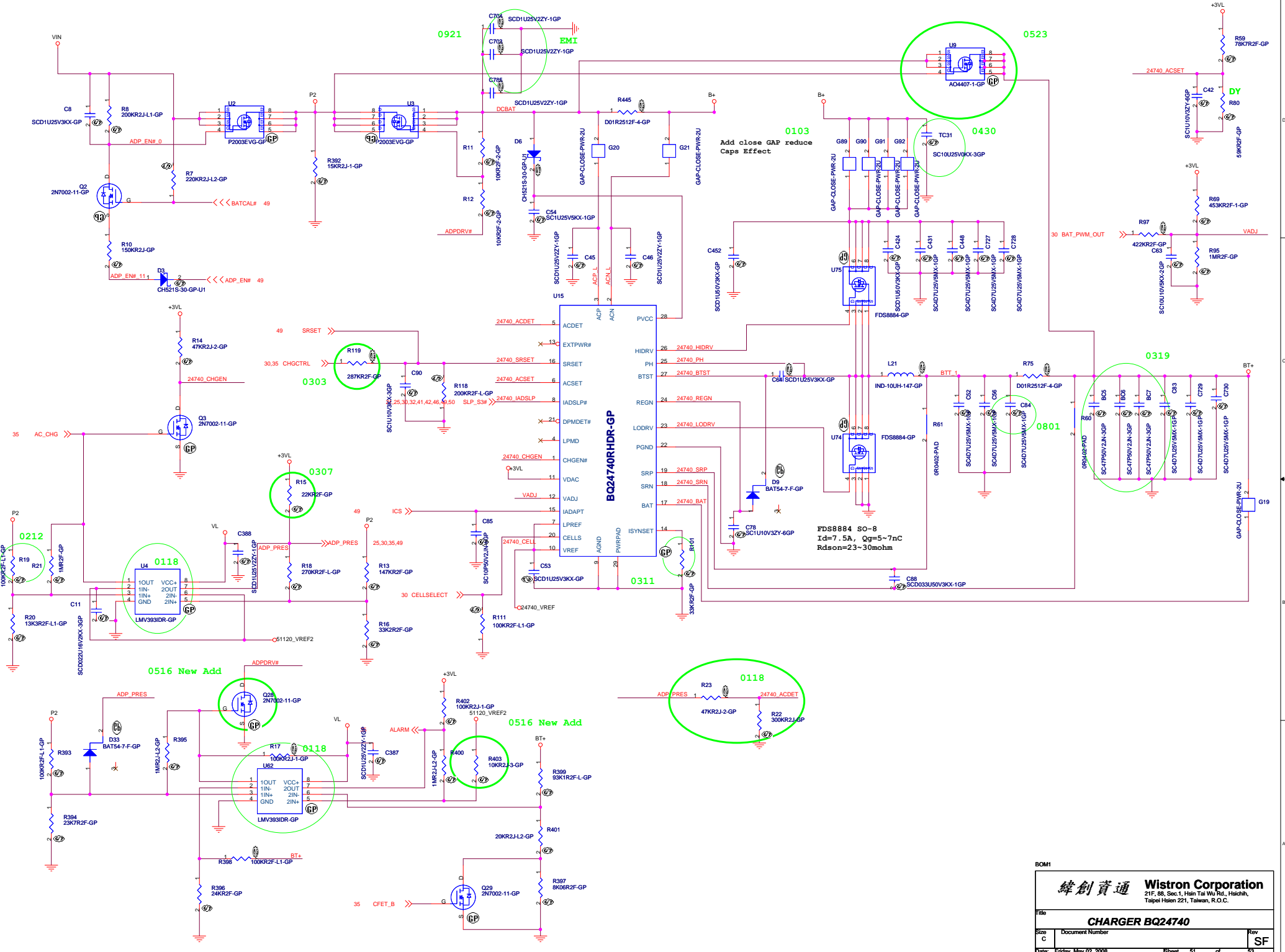
R365, R369 C358 close to U105

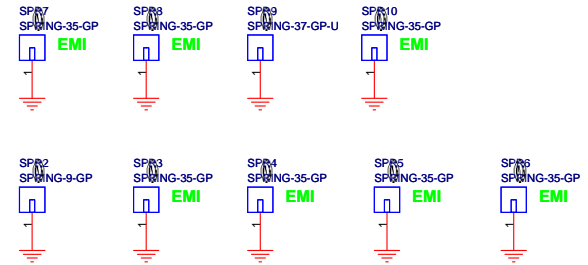
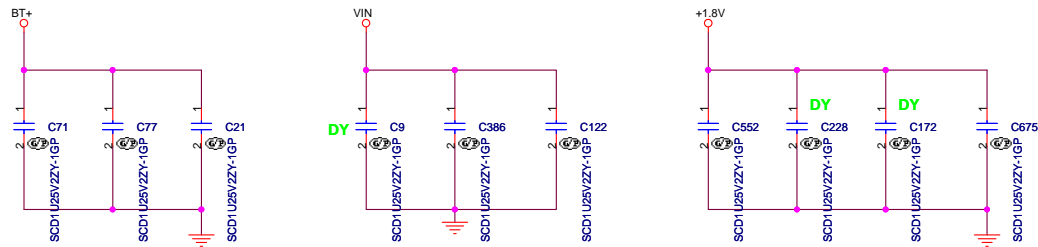
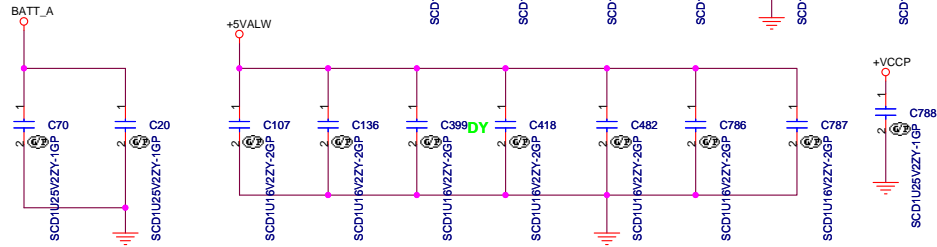
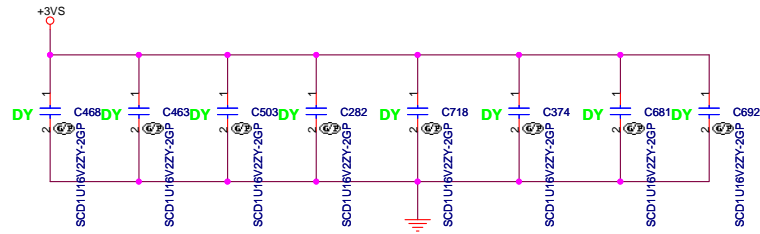
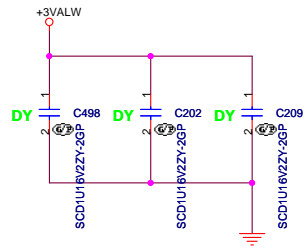
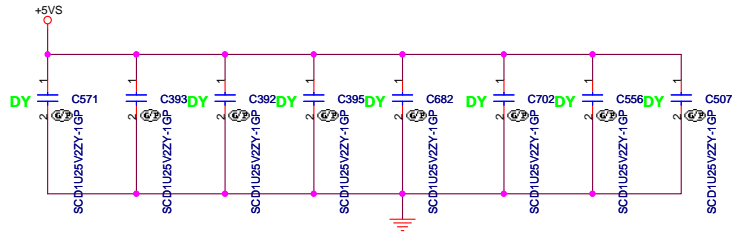
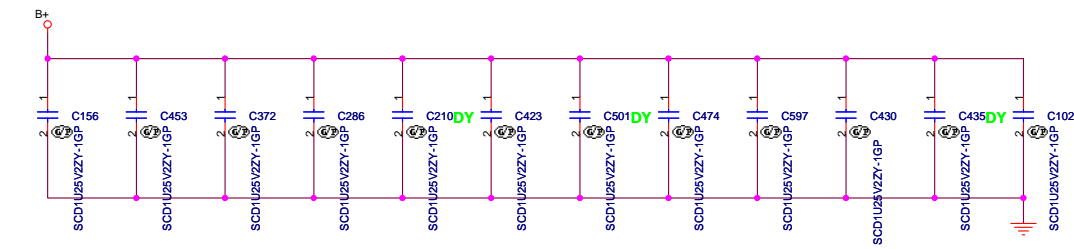


0523

Sanyo 150uF 4V
 $ESR = 35m\Omega$
 $Tripple = 1.4A$

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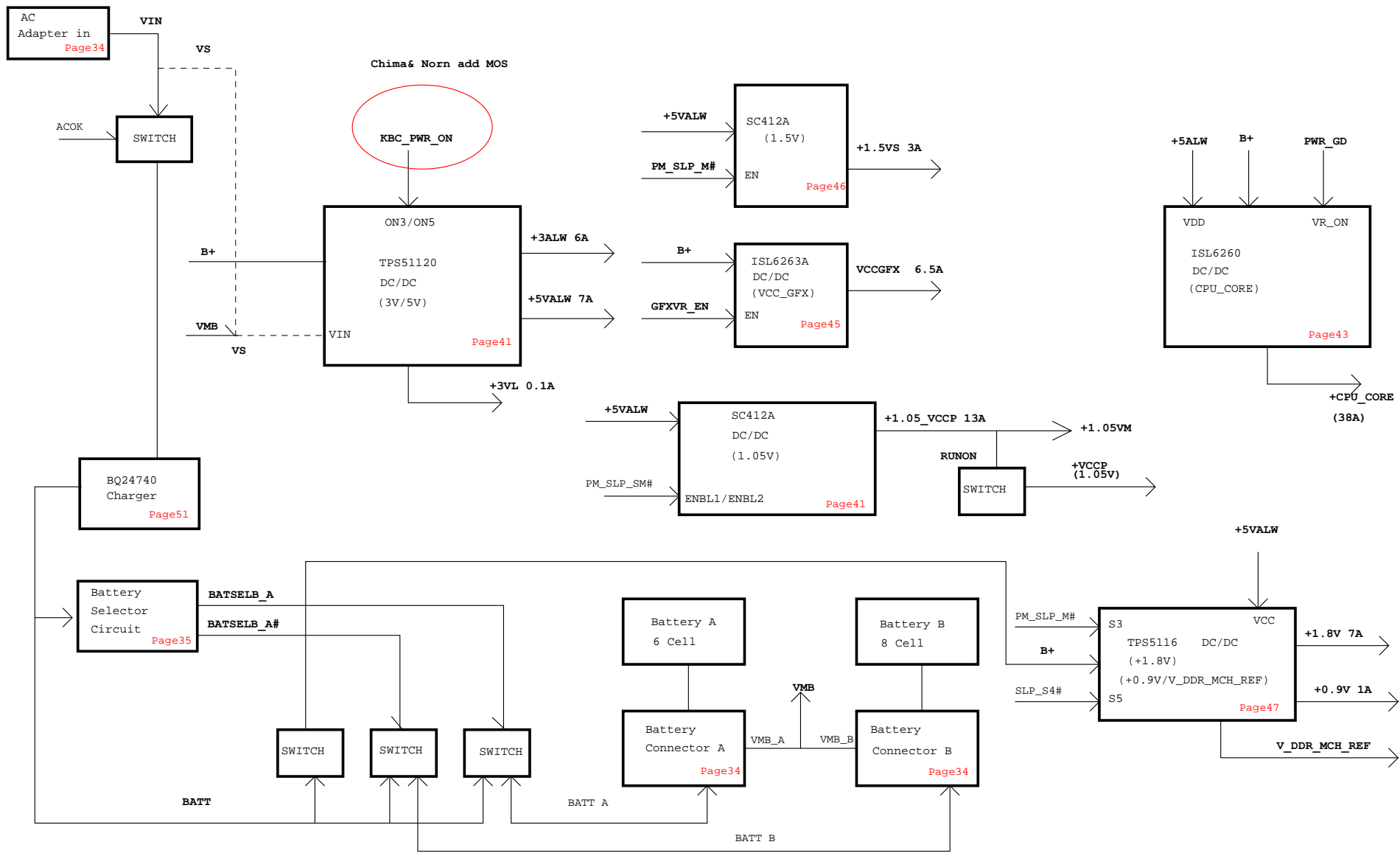




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